

Single Chip Power Solution for Battery Powered Systems

Check for Samples: [TPS65070-Q1](#), [TPS65072-Q1](#), [TPS65073-Q1](#), [TPS650732-Q1](#)

FEATURES

- Qualified for Automotive Applications
- Charger/Power Path Management:
 - 2A Output Current on the Power Path
 - Linear Charger; 1.5A Maximum Charge Current
 - 100mA/500mA/ 800mA/1300mA Current Limit From USB Input
 - Thermal Regulation, Safety Timers
 - Temperature Sense Input
- 3 Step-Down Converters:
 - 2.35MHz Fixed Frequency Operation
 - Up to 1.5A of Output Current
 - Adjustable or Fixed Output Voltage
 - V_{IN} Range From 2.8V to 6.3V
 - Power Save Mode at Light Load Current
 - Output Voltage Accuracy in PWM Mode $\pm 1.5\%$
 - Typical 19 μ A Quiescent Current per Converter
 - 100% Duty Cycle for Lowest Dropout
- LDOs:
 - Fixed Output Voltage
 - Dynamic Voltage Scaling on LDO2
 - 20 μ A Quiescent Current
 - 200mA Maximum Output Current
 - V_{IN} Range From 1.8V to 6.3V
- wLED Boost Converter:
 - Internal Dimming Using I²C
 - Up to 2 × 10 LEDs
 - Up to 25mA per String With Internal Current Sink
- I²C Interface

- 10 Bit A/D Converter
- Touch Screen Interface
- Undervoltage Lockout and Battery Fault Comparator

APPLICATIONS

- Portable Navigation Systems
- Low-Power DSP Supply

DESCRIPTION

The TPS6507x are single chip Power Management ICs for portable applications consisting of a battery charger with power path management for a single Li-Ion or Li-Polymer cell. The charger can either be supplied by a USB port on pin *USB* or by a dc voltage from a wall adapter connected to pin *AC*. Three highly efficient 2.25MHz step-down converters are targeted at providing the core voltage, memory and I/O voltage in a processor based system. The step-down converters enter a low power mode at light load for maximum efficiency across the widest possible range of load currents. For low noise applications the devices can be forced into fixed frequency PWM using the I²C interface. The step-down converters allow the use of small inductors and capacitors to achieve a small solution size. The TPS6507x also integrate two general purpose LDOs for an output current of 200mA. These LDOs can be used to power an SD-card interface and an *always-on* rail, but can be used for other purposes as well. Each LDO operates with an input voltage range between 1.8V and 6.3V allowing them to be supplied from one of the step-down converters or directly from the main battery. An inductive boost converter with two programmable current sinks power two strings of white LEDs.

The TPS6507x come in a 48-pin leadless package (6mm × 6mm QFN) with a 0.4mm pitch.



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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ORDERING INFORMATION

| T _A | OUTPUT VOLTAGE AT DCDC3 | OUTPUT VOLTAGE AT DCDC1/DCDC2 | OUTPUT VOLTAGE AT LDO1/LDO2 | OUTPUT CURRENT AT DCDC1/DCDC2/DCDC3 | PACKAGE | | PART NUMBER ⁽¹⁾ | TOP-SIDE MARKING |
|----------------|-------------------------|-------------------------------|-----------------------------|--|-------------|--------------|----------------------------|------------------|
| | | | | | | | | |
| -40°C to 105°C | 1.0V / 1.2V (OMAP-L1x8) | 3.3V / 1.8V / 3.3V | 1.8V / 1.2V | 0.6A / 1.5A / 1.5A | VQFN-48 RSL | Reel of 2500 | TPS65070TRSLRQ1 | Preview |
| | 1.2V / 1.4V (Atlas IV) | 3.3V / 1.8V / 2.5V | 1.2V / 1.2V | 3 x 600 mA | VQFN-48 RSL | Reel of 2500 | TPS65072TRSLRQ1 | Preview |
| | 1.2V / 1.35V (OMAP35xx) | 1.8V / 1.2V / 1.8V | 1.8V / 1.8V | 0.6A / 0.6A / 1.5A External sequencing | VQFN-48 RSL | Reel of 2500 | TPS65073TRSLRQ1 | Preview |
| | 1.2V / 1.35V (OMAP35xx) | 1.8V / 1.2V / 1.8V | 1.8V / 1.8V | 0.6A / 0.6A / 1.5A Internal sequencing | VQFN-48 RSL | Reel of 2500 | TPS650731TRSLRQ1 | Preview |
| | 1.2V / 1.35V (AM3505) | 1.8V / 1.8V / 3.3V | 1.8V / 1.8V | 0.6A / 0.6A / 1.5A Internal sequencing | VQFN-48 RSL | Reel of 2500 | TPS650732TRSLRQ1 | TPS650732T |

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

| | VALUE / UNIT |
|--|------------------------------|
| Voltage range on all pins except the pins listed below with respect to AGND | -0.3 to 7V |
| Voltage range on pins \overline{INT} , \overline{RESET} , PGOOD, PB_OUT with respect to AGND | -0.3 to V(AVDD6) |
| Voltage range on pins VINDCDC1/2, VINDCDC3, VINLDO respect to AGND | -0.3 to V(SYS) |
| Voltage range on pins AD_IN1, AD_IN2, AD_IN3, AD_IN4 with respect to AGND | -0.3 to 3.3 V |
| Voltage range on pins ISINK1, ISINK2, AC, USB | -0.3 to 20 V |
| Voltage range on pin L4 (output voltage of boost converter), FB_wLED | -0.3 to 40 V |
| Current at SYS, AC, USB, BAT, L3 | 3000 mA |
| Current at all other pins | 1000 mA |
| Continuous total power dissipation | See Dissipation Rating Table |
| Operating free-air temperature, T _A | 40°C to 105°C |
| Maximum junction temperature, T _J | 125°C |
| Storage temperature, T _{st} | -65°C to 150°C |

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATINGS⁽¹⁾

| PACKAGE | R _{θJA} | T _A ≤ 25°C POWER RATING | DERATING FACTOR ABOVE T _A = 25°C | T _A = 70°C POWER RATING | T _A = 85°C POWER RATING | T _A = 105°C POWER RATING |
|---------|------------------|------------------------------------|---|------------------------------------|------------------------------------|-------------------------------------|
| RSL | 37 K/W | 2.6 W | 26 mW/K | 1.48 W | 1.0 W | 520 mW |

(1) The thermal resistance R_{θJ-P} junction to PowerPAD of the RSL package is 1.1 K/W. The value for R_{θJA} was measured on a high K board.

RECOMMENDED OPERATING CONDITIONS

| | | MIN | NOM | MAX | UNIT |
|---------------------------------------|--|------|------|----------------------|------|
| BATTERY CHARGER AND POWER PATH | | | | | |
| V _{IN} | Input voltage for power path manager at pins AC or USB | 4.30 | | 17 | V |
| | Input voltage for power path manager at pins AC or USB, charger and power path active (no overvoltage lockout) | 4.30 | | 5.8 | |
| | Input voltage for power path manager at pins AC or USB in case there is no battery connected at pin BAT | 3.6 | | 17 | |
| I _{IN} | Input current at AC pin | | | 2.5 | A |
| | Input current at USB pin | | | 1.3 | |
| I _{BAT} | Current at BAT pin | | | 2 | A |
| DCDC CONVERTERS AND LDOs | | | | | |
| V _{INDCDC} | Input voltage range for step-down converter DCDC1, DCDC2, DCDC3 | 2.8 | | 6.3 ⁽¹⁾ | V |
| V _{DCDC1} | Output voltage range for VDCDC1 step-down converter | 0.6 | | V _{INDCDC1} | V |
| V _{DCDC2} | Output voltage range for VDCDC2, DCDC3 step-down converter | 0.6 | | V _{INDCDC2} | V |
| V _{INLDOx} | Input voltage range for LDO1 and LDO2 | 1.8 | | 6.3 ⁽¹⁾ | V |
| V _{LDO1} | Output voltage range for LDO1 | 0.9 | | 3.3 | V |
| V _{LDO2} | Output voltage range for LDO2 | 0.8 | | 3.3 | V |
| I _{OUTDCDC1} | Output current at L1 | | 600 | | mA |
| L1 | Inductor at L1 ⁽²⁾ | 1.5 | 2.2 | | μH |
| C _{INDCDC12} | Input Capacitor at VINDCDC1 and VINDCDC2 ⁽²⁾ | 22 | | | μF |
| C _{OUTDCDC1} | Output Capacitor at VDCDC1 ⁽²⁾ | 10 | 22 | | μF |
| I _{OUTDCDC2} | Output current at L2 | | 1500 | | mA |
| L2 | Inductor at L2 ⁽²⁾ | 1.5 | 2.2 | | μH |
| C _{OUTDCDC2} | Output Capacitor at VDCDC2 ⁽²⁾ | 10 | 22 | | μF |
| I _{OUTDCDC3} | Output current at L3 | | 1500 | | mA |
| L3 | Inductor at L3 ⁽²⁾ | 1.5 | 2.2 | | μH |
| C _{INDCDC3} | Input Capacitor at VINDCDC3 ⁽²⁾ | 10 | | | μF |
| C _{OUTDCDC3} | Output Capacitor at VDCDC3 ⁽²⁾ | 10 | 22 | | μF |
| L4 | Inductor at L4 ⁽²⁾ | | 22 | | μH |
| C _{OUTWLED} | Output Capacitor at wLED boost converter | 4.7 | | | μF |
| C _{INLDO1/2} | Input Capacitor at VINLDO1/2 | 2.2 | | | μF |
| C _{OUTLDO1} | Output Capacitor at VLDO1 | 2.2 | | | μF |
| I _{OUTLDO1} | Output Current at VLDO1 | | 100 | | mA |
| C _{OUTLDO2} | Output Capacitor at VLDO2 | 2.2 | | | μF |
| I _{OUTLDO2} | Output Current at VLDO2 | | 100 | | mA |
| C _{AC} | Input Capacitor at AC | 1 | | | μF |
| C _{USB} | Input Capacitor at USB | 1 | | | μF |
| C _{BAT} | Capacitor at BAT pin | 10 | | | μF |
| C _{SYS} | Capacitor at SYS pin | 22 | | 100 ⁽³⁾ | μF |
| C _{BYPASS} | Capacitor at BYPASS pin | 10 | | | μF |
| C _{INT_LDO} | Capacitor at INT_LDO pin | 2.2 | | | μF |
| C _{AVDD6} | Capacitor at AVDD6 pin | 4.7 | | | μF |
| T _A | Operating ambient temperature | -40 | | 105 | °C |
| T _J | Operating junction temperature | -40 | | 125 | °C |

(1) 6.3 V or V_{SYSt} whichever is less

(2) See application section for more details

(3) For proper soft-start

ELECTRICAL CHARACTERISTICS

VSYS = 3.6V, EN_DCDCx = VSYS, L = 2.2μH, C_{OUT} = 10μF, T_A = –40°C to 105°C typical values are at T_A = 25°C (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---|---|--|-----|------------|------------------|------|
| SUPPLY CURRENT | | | | | | |
| V _{INDCDC} | Input voltage range for DCDC converters | | 2.8 | | 6.3 | V |
| I _Q | Operating quiescent current Total current into VSYS, VINDCDCx, VINLDO1/2 | Only DCDC2, DCDC3 and LDO1 enabled, device in ON-mode; DCDC converters in PFM | | 140 | | μA |
| | | Per DC/DC converter, PFM mode | | 19 | 30 | |
| | | Per DC/DC converter, PWM mode | | 2.5 | | |
| | | For LDO1 or LDO2 (either one enabled) | | 20 | 35 | |
| | | For LDO1 and LDO2 (both enabled) | | 34 | | |
| | | For wLED converter | | 1.5 | | mA |
| I _{SD} | Shutdown current | All converters, LDOs, wLED driver and ADC disabled, no input voltage at AC and USB; SYS voltage turned off | | 8 | 12 | μA |
| V _{UVLO} | Undervoltage lockout threshold | Voltage at the output of the power manager detected at pin SYS; falling voltage, voltage defined with <UVLO0>, <UVLO1> DEFAULT: 3.0V | –2% | 2.8 | 2% | V |
| | | | | 3.0 | | |
| | | | | 3.1 | | |
| | Undervoltage lockout hysteresis | Rising voltage defined with <UVLO hysteresis>; DEFAULT: 500mV | | 360 | 450 | mV |
| | Undervoltage lockout deglitch time | Due to internal delay | | 4 | | ms |
| T _{SD} | Thermal shutdown for DCDC converters, wLED driver and LDOs | Increasing junction temperature | | 150 | | °C |
| | Thermal shutdown hysteresis | Decreasing junction temperature | | 20 | | °C |
| EN_DCDC1, EN_DCDC2, EN_DCDC3, DEFDCDC2, DEFDCDC3, SDAT, SCLK, EN_wLED (optional) | | | | | | |
| V _{IH} | High Level Input Voltage, EN_DCDC1, EN_DCDC2, EN_DCDC3, DEFDCDC2, DEFDCDC3, SDAT, SCLK, EN_wLED | | 1.2 | | V _{sys} | V |
| V _{IL} | Low Level Input Voltage, EN_DCDC1, EN_DCDC2, EN_DCDC3, DEFDCDC2, DEFDCDC3, SDAT, SCLK, EN_wLED | | 0 | | 0.4 | V |
| I _{IN} | Input bias current, EN_DCDC1, EN_DCDC2, EN_DCDC3, DEFDCDC2, DEFDCDC3, SDAT, SCLK | | | 0.01 | 1.0 | μA |

DCDC1 CONVERTER

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------|---|--|-------|--------------|------|------------------|
| $V_{VINDCDC1}$ | Input voltage range | Connected to SYS pin | 2.8 | | 6.3 | V |
| I_O | Maximum output | | 600 | | | mA |
| $R_{DS(ON)}$ | High side MOSFET on-resistance | $VINDCDC1 = 2.8\text{ V}$ | | 150 | 300 | m Ω |
| | | $VINDCDC1 = 3.5\text{ V}$ | | 120 | 200 | |
| I_{LH} | High side MOSFET leakage current | $VINDCDC1 = 6.3\text{ V}$ | | | 2 | μA |
| $R_{DS(ON)}$ | Low side MOSFET on-resistance | $VINDCDC1 = 2.8\text{ V}$ | | 200 | 300 | m Ω |
| | | $VINDCDC1 = 3.5\text{ V}$ | | 160 | 180 | |
| I_{LL} | Low side MOSFET leakage current | $V_{DS} = 6.3\text{ V}$ | | | 1 | μA |
| I_{LIMF} | Forward current limit | for TPS65072, TPS65073, TPS650731, TPS650732 | 0.8 | 1.1 | 1.5 | A |
| I_{LIMF} | Forward current limit | for TPS65070 | 1.1 | 1.6 | 2.2 | A |
| f_S | Oscillator frequency | | 1.95 | 2.35 | 2.55 | MHz |
| V_{out} | Fixed output voltage range | Internal resistor divider, I ² C selectable | 0.725 | | 3.3 | V |
| V_{out} | Default output voltage | For TPS65070, TPS65072 | | 3.3 | | V |
| | | For TPS65073, TPS650731, TPS650732 | | 1.8 | | |
| V_{out} | DC output voltage accuracy; PFM mode ⁽¹⁾ | $VINDCDC1 = VDCDC1 + 0.3\text{ V}$ to 6.3 V; $0\text{ mA} \leq I_O \leq 0.6\text{ A}$ | -2% | | 3% | |
| V_{out} | DC output voltage accuracy; PWM mode ⁽¹⁾ | $VINDCDC1 = VDCDC1 + 0.3\text{ V}$ to 6.3 V; $0\text{ mA} \leq I_O \leq 0.6\text{ A}$ | -1.5% | | 1.5% | |
| ΔV_{OUT} | Power save mode ripple voltage ⁽²⁾ | $I_{OUT} = 1\text{ mA}$, PFM mode | | 40 | | mV _{pp} |
| t_{Start} | Start-up time | Time from active EN to Start switching | | 170 | | μs |
| t_{Ramp} | V_{OUT} ramp up time | Time to ramp from 5% to 95% of V_{OUT} | | 250 | | μs |
| | power good threshold | rising voltage | | $V_o - 5\%$ | | |
| | power good threshold | falling voltage | | $V_o - 10\%$ | | |
| R_{DIS} | Internal discharge resistor at L1 | | -35% | 250 | 35% | Ω |

(1) Output voltage specification does not include tolerance of external voltage programming resistors. Output voltage in PFM mode is scaled to +1% of nominal value.

(2) Configuration L= 2.2 μH , $C_{OUT} = 10\text{ }\mu\text{F}$

DCDC2 CONVERTER

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT | |
|----------------|----------------------------------|--|---|------|----------|---------------|---|
| $V_{VINDCDC2}$ | Input voltage range | Connected to SYS pin | 2.8 | | 6.3 | V | |
| I_O | Maximum output current | TPS65072/73/731/732 | | 600 | | mA | |
| | | TPS65070 | $V_{in} > 2.8\text{ V}$ | 1500 | | | |
| $R_{DS(ON)}$ | High side MOSFET on-resistance | $VINDCDC2 = 2.8\text{ V}$ | | 150 | 300 | m Ω | |
| | | $VINDCDC2 = 3.5\text{ V}$ | | 120 | 200 | | |
| I_{LH} | High side MOSFET leakage current | $VINDCDC2 = 6.3\text{ V}$ | | | 2 | μA | |
| $R_{DS(ON)}$ | Low side MOSFET on-resistance | $VINDCDC2 = 2.8\text{ V}$ | | 200 | 300 | m Ω | |
| | | $VINDCDC2 = 3.5\text{ V}$ | | 160 | 180 | | |
| I_{LL} | Low side MOSFET leakage current | $V_{DS} = 6.3\text{ V}$ | | | 1 | μA | |
| I_{LIMF} | Forward current limit | TPS65072/73/731/732 | $2.8\text{ V} < V_{INDCDC2} < 6.3\text{ V}$ | 0.8 | 1.1 | 1.5 | A |
| | | TPS65070 | | 2.1 | 2.4 | 3.5 | |
| f_S | Oscillator frequency | | 1.95 | 2.35 | 2.55 | MHz | |
| V_{out} | Adjustable output voltage range | External resistor divider | 0.6 | | V_{in} | V | |
| V_{ref} | Reference voltage | | | 600 | | mV | |
| V_{out} | Fixed output voltage range | Internal resistor divider, I ² C selectable (Default setting) | 0.725 | | 3.3 | V | |

DCDC2 CONVERTER (continued)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--------------------|---|--|-------|----------------------|------|------------------|
| V _{out} | Default output voltage for TPS65070, TPS650732 | For DEFDCDC2 = LOW | | 1.8 | | V |
| | | For DEFDCDC2 = HIGH | | 3.3 | | |
| | Default output voltage for TPS65072 | For DEFDCDC2 = LOW | | 1.8 | | |
| | | For DEFDCDC2 = HIGH | | 2.5 | | |
| | Default output voltage for TPS65073, TPS650731 | For DEFDCDC2 = LOW | | 1.2 | | |
| | | For DEFDCDC2 = HIGH | | 1.8 | | |
| V _{out} | DC output voltage accuracy; PFM mode ⁽¹⁾ | VINDCDC2 = 2.8 V to 6.3 V; 0 mA ≤ I _O ≤ 1.5 A | -2% | | 3% | |
| | DC output voltage accuracy; PWM mode ⁽¹⁾ | | -1.5% | | 1.5% | |
| | DC output voltage accuracy with resistor divider at DEFDCDC2; PFM | VINDCDC2 = VDCDC2 + 0.3 V (min 2.8 V) to 6.3 V; 0 mA ≤ I _O ≤ 1.5A | -2% | | 3% | |
| | DC output voltage accuracy with resistor divider at DEFDCDC2; PWM | | -1% | | 1% | |
| ΔV _{OUT} | Power save mode ripple voltage | I _{OUT} = 1 mA, PFM mode ⁽²⁾ | | 40 | | mV _{pp} |
| t _{Start} | Start-up time | Time from active EN to Start switching | | 170 | | μs |
| t _{Ramp} | V _{OUT} ramp up time | Time to ramp from 5% to 95% of V _{OUT} | | 250 | | μs |
| | power good threshold | rising voltage | | V _O - 5% | | |
| | power good threshold | falling voltage | | V _O - 10% | | |
| R _{DIS} | Internal discharge resistor at L2 | | -35% | 250 | 35% | Ω |

(1) Output voltage specification does not include tolerance of external voltage programming resistors. Output voltage in PFM mode is scaled to +1% of nominal value.

(2) Configuration L = 2.2 μH, C_{OUT} = 10 μF

DCDC3 CONVERTER

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT | |
|-----------------------|---|--|--|------|-----------------|------|---|
| V _{VINDCDC3} | Input voltage range | Connected to SYS pin | 2.8 | | 6.3 | V | |
| I _O | Maximum output current | Vin > 2.8 V | TPS65072 | 600 | | mA | |
| | | | TPS65070, TPS65073, TPS650731, TPS650732 | 1500 | | | |
| R _{DS(ON)} | High side MOSFET on-resistance | VINDCDC3 = 2.8 V | | 150 | 300 | mΩ | |
| | | VINDCDC3 = 3.5 V | | 120 | 200 | | |
| I _{LH} | High side MOSFET leakage current | VINDCDC3 = 6.3 V | | | 2 | μA | |
| R _{DS(ON)} | Low side MOSFET on-resistance | VINDCDC3 = 2.8 V | | 200 | 300 | mΩ | |
| | | VINDCDC3 = 3.5 V | | 160 | 180 | | |
| I _{LL} | Low side MOSFET leakage current | V _{DS} = 6.3 V | | | 1 | μA | |
| I _{LIMF} | Forward current limit | 2.8 V < V _{INDCDC3} < 6.3 V | TPS65072 | 0.8 | 1.1 | 1.5 | A |
| | | | TPS65070/73/731/732 | 2.1 | 2.4 | 3.5 | |
| f _S | Oscillator frequency | | 1.95 | 2.35 | 2.55 | MHz | |
| V _{out} | Adjustable output voltage range | External resistor divider | 0.6 | | V _{in} | V | |
| V _{ref} | Reference voltage | | | 600 | | mV | |
| V _{out} | Fixed output voltage range | Internal resistor divider, I ² C selectable (Default setting) | 0.725 | | 3.3 | V | |
| V _{out} | Default output voltage for TPS65070 | For DEFDCDC3 = LOW | | 1.0 | | V | |
| | | For DEFDCDC3 = HIGH | | 1.2 | | | |
| | Default output voltage for TPS65072 | For DEFDCDC3 = LOW | | 1.2 | | | |
| | | For DEFDCDC3 = HIGH | | 1.4 | | | |
| | Default output voltage for TPS65073, TPS650731, TPS650732 | For DEFDCDC3 = LOW | | 1.2 | | | |
| | | For DEFDCDC3 = HIGH | | 1.35 | | | |
| V _{out} | DC output voltage accuracy; PFM mode ⁽¹⁾ | VINDCDC3 = 2.8 V to 6.3 V; 0 mA ≤ I _O ≤ 1.5 A | -2% | | 3% | | |
| | DC output voltage accuracy; PWM mode ⁽¹⁾ | | -1.5% | | 1.5% | | |

(1) Output voltage specification does not include tolerance of external voltage programming resistors. Output voltage in PFM mode is scaled to +1% of nominal value.

DCDC3 CONVERTER (continued)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--------------------|---|--|------|----------------------|-----|------------------|
| V _{out} | DC output voltage accuracy with resistor divider at DEFDCDC3; PFM | V _{INDCDC3} = V _{DCDC3} + 0.3 V (min 2.8 V) to 6.3 V; 0 mA ≤ I _O ≤ 1.5A | -2% | | 3% | |
| V _{out} | DC output voltage accuracy with resistor divider at DEFDCDC3; PWM | | -1% | | 1% | |
| ΔV _{OUT} | Power save mode ripple voltage | I _{OUT} = 1 mA, PFM mode ⁽²⁾ | | 40 | | mV _{pp} |
| t _{Start} | Start-up time | Time from active EN to Start switching | | 170 | | μs |
| t _{Ramp} | V _{OUT} ramp up time | Time to ramp from 5% to 95% of V _{OUT} | | 250 | | μs |
| | power good threshold | rising voltage | | V _O - 5% | | |
| | power good threshold | falling voltage | | V _O - 10% | | |
| R _{DIS} | Internal discharge resistor at L3 | | -35% | 250 | 35% | Ω |

(2) Configuration L= 2.2 μH, C_{OUT} = 10 μF

VLDO1 and VLDO2 LOW DROPOUT REGULATORS

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|-------------|---|--|-------|-----|--------------------|---------------|
| V_{INLDO} | Input voltage range for LDO1, LDO2 | | 1.8 | | 6.3 ⁽¹⁾ | V |
| V_{LDO1} | LDO1 output voltage range | | 1.0 | | 3.3 | V |
| V_{LDO2} | LDO2 output voltage range | Voltage options available see register description | 0.725 | | 3.3 | V |
| I_O | Output current for LDO1 | | | | 200 | mA |
| V_{LDO1} | LDO1 default output voltage | For TPS65072 | | 1.2 | | V |
| | | For TPS65070, TPS65073, TPS650731, TPS650732 | | 1.8 | | |
| V_{LDO2} | LDO2 default output voltage | For TPS65070 | | 1.2 | | V |
| | | For TPS65072 | | 1.2 | | |
| | | For TPS65073, TPS650731, TPS650732 | | 1.8 | | |
| I_O | Output current for LDO2 | | | | 200 | mA |
| I_{SC} | LDO1 short circuit current limit | $V_{LDO1} = GND$ | | | 400 | mA |
| I_{SC} | LDO2 short circuit current limit | $V_{LDO2} = GND$ | | | 400 | mA |
| | Minimum voltage drop at LDO1 | $I_O = 100\text{ mA}$, $V_{INLDO} = 3.3\text{ V}$ | | | 150 | mV |
| | Minimum voltage drop at LDO2 | $I_O = 100\text{ mA}$, $V_{INLDO} = 3.3\text{ V}$ | | | 150 | mV |
| | Output voltage accuracy for LDO1, LDO2 | $I_{LDO1} = 100\text{ mA}$; $I_{LDO2} = 100\text{ mA}$; $V_{in} \geq V_{out} + 200\text{ mV}$ | -1% | | 1.5% | |
| | Line regulation for LDO1, LDO2 | $V_{INLDO1,2} = V_{LDO1,2} + 0.5\text{ V}$ (min. 2.8 V) to 6.5 V, $I_{LDO1} = 100\text{ mA}$; $I_{LDO2} = 100\text{ mA}$ | -1% | | 1% | |
| | Load regulation for LDO1, LDO2 | $I_O = 1\text{ mA}$ to 200 mA | -1% | | 1% | |
| | Load regulation for LDO1, LDO2 | $I_O < 1\text{ mA}$; $V_O < 1\text{ V}$ | -2.5% | | 2.5% | |
| R_{DIS} | Internal discharge resistor at VLDO1, VLDO2 | | | 400 | | Ω |
| t_{Ramp} | V_{OUT} ramp up time | Time to ramp from 5% to 95% of V_{OUT} | | 250 | | μs |

(1) 6.3 V or VSYS whichever is less

wLED BOOST CONVERTER

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--|--|--|------|-------|-----|------|
| V _{L4} | voltage at L4 pin | | 2.8 | | 39 | V |
| V _{sink1,2} | Input voltage at ISINK1, ISINK2 pins | | | | 16 | V |
| V _{OUT} | Internal overvoltage protection | | 35 | 37 | 39 | V |
| | Maximum boost factor (V _{out} /V _{in}) | I _{sink1} = I _{sink2} = 20 mA, V _{in} = 2.8 V | 9 | 10 | | |
| T _{min_off} | Minimum off pulse width | | | 70 | | ns |
| R _{DS(ON)} | N-channel MOSFET on-resistance | V _{L4} = 3.6 V | | 0.6 | | Ω |
| | N-channel MOSFET current limit | | 0.8 | 1.6 | 2.0 | A |
| I _{LN_NFET} | N-channel leakage current | V _{DS} = 25 V, T _A = 25°C | | | 1 | μA |
| | Switching frequency | | | 1.125 | | MHz |
| V _{sink1} , V _{sink2} | Minimum voltage drop at Isink pin to GND for proper regulation | | | 400 | | mV |
| V _{ISET} | ISET pin voltage | | | 1.24 | | V |
| K _{ISET} | Current multiple I _{out} /I _{set} | I _{set} current = 15 μA | | 1000 | | |
| | | I _{set} current = 25 μA | | 1000 | | |
| I _{sink1} , I _{sink2} | Minimum current into ISINK1, ISINK2 pins | For proper dimming (string can be disabled also) | | | 4 | mA |
| | Maximum current into ISINK1, ISINK2 pins | V _{in} = 3.3 V | | 25 | | mA |
| | DC current set accuracy | I _{sinkx} = 5 mA to 25 mA; no PWM dimming | | | ±5% | |
| | Current difference between Isink1 and Isink2 | R _{set1} = 50k; I _{sink1} = 25 mA, V _{in} = 3.6 V; no PWM dimming | | | ±5% | |
| | Current difference between Isink1 and Isink2 | R _{set2} = 250k; I _{sink1} = 5 mA, V _{in} = 3.6 V; no PWM dimming | | | ±5% | |
| f _{PWM} | PWM dimming frequency | PWM dimming Bit = 00 | -15% | 100 | 15% | Hz |
| | | PWM dimming Bit = 01 (default) | -15% | 200 | 15% | |
| | | PWM dimming Bit = 10 | -15% | 500 | 15% | |
| | | PWM dimming Bit = 11 | -15% | 1000 | 15% | |
| | Rise / fall time of PWM signal | For all PWM frequencies | | 2 | | μs |
| | Dimming PWM DAC resolution | | | 1% | | |

Reset, PB_IN, PB_OUT, PGood, Power_on, INT, EN_EXTLDO, EN_wLED

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|----------------------|---|---|------|--|-----------------|------|
| | Reset delay time and PGOOD delay time | Input voltage at threshold pin rising; time defined with <PGOOD DELAY0>, <PGOOD DELAY1> | -15% | 20 100 ⁽¹⁾ 200 400 | 15% | ms |
| | PB-IN debounce time | | -15% | 50 | 15% | ms |
| | PB_IN "Reset-detect- time" | Internal timer | -15% | 15 | 15% | s |
| | PGOOD low time when PB_IN = Low for >15s | | -15% | 0.5 | 15% | ms |
| V _{IH} | High level input voltage on pin POWER_ON | | 1.2 | | V _{IN} | V |
| V _{IH} | High level input voltage on pin PB_IN | | 1.8 | | AVDD6 | V |
| V _{IL} | Low Level Input Voltage, PB_IN, Power_on | | 0 | | 0.4 | V |
| | Internal pull-up resistor from PB_IN to AVDD6 | | | 50 | | kΩ |
| | Output current at AVDD6 | | | | 1 | mA |
| I _{IN} | Input bias current at Power_on | | | 0.01 | 1.0 | μA |
| V _{OL} | Reset, PB_OUT, PGood, INT output low voltage, EN_EXTLDO | I _{OL} = 1 mA, V _{threshold} < 1 V | | | 0.3 | V |
| VOH | EN_EXTLDO HIGH level output voltage | I _{OH} = 0.1 mA; optional push pull output | | | VSYS | V |
| I _{OL} | Reset, PB_OUT, PGood, INT sink current | | | 1 | | mA |
| | Reset, PB_OUT, PGood, INT output leakage current | Reset, PB_OUT, PGood, INT open drain output in high impedance state | | | 0.25 | μA |
| V _{th} | Threshold voltage at THRESHOLD pin | Input voltage falling | -4% | 1 | 4% | V |
| V _{th_hyst} | Hysteresis on THRESHOLD pin | Input voltage rising | | 7 | | mV |
| I _{in} | Input bias current at EN_wLED, THRESHOLD | | | | 1 | μA |

(1) Default Reset delay time is set to 100 ms typical

ADC CONVERTER

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|-----------------|--|--|-----|-------|------|------|
| V _{IN} | Input voltage range at AD_IN1 to AD_IN4 pin (channel 0 to channel 3) | For full scale measurement | 0 | | 2.25 | V |
| | Input voltage range internal channel 6 to channel 9 | For full scale measurement | 0 | | 6 | |
| | Input voltage range on channel4 (TS pin) and channel5 (ISET pin) | Unipolar measurement of charge current at pin ISET (voltage at ISET) | 0 | | 2.25 | |
| I _{in} | AD_IN1 to AD_IN4 input current | | | 0.1 | 4 | μA |
| C _{in} | Input capacitance at AD_IN1 to AD_IN4 | | | 15 | | pF |
| | ADC resolution | | | 10 | | Bits |
| | Differential linearity error | | | ±1 | | LSB |
| | Offset error | | | 1 | 5 | LSB |
| | Gain error | | | ±8 | | LSB |
| | Sampling time | | | 220 | | μs |
| | Conversion time | | | 19 | | μs |
| | Wait time after enable | Time needed to stabilize the internal voltages | 1.5 | | | ms |
| | Quiescent current, ADC enabled by I ² C | includes current needed for I2C block | | 500 | | μA |
| | Quiescent current, conversion ongoing | | | | 1 | mA |
| | Reference voltage output on pin BYPASS | | -1% | 2.260 | 1% | V |
| | Output current on reference output pin BYPASS | | | | 0.1 | mA |

TOUCH SCREEN INTERFACE

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---|--|--|------|------|------|------|
| V _{TSREF} | Voltage at internal voltage regulator for TSC | | | 2.30 | | V |
| TOUCHSCREEN PANEL SPECIFICATIONS | | | | | | |
| | Plate resistance X | Specified by design | 200 | 400 | 1200 | Ω |
| | Plate resistance Y | Specified by design | 200 | 400 | 1200 | Ω |
| | Resistance between plates contact | | 180 | 400 | 1000 | Ω |
| | Resistance between plates pressure | | 180 | 400 | 1000 | Ω |
| | Settling time | Position measurement; 400 Ω, 100 pF | | 5.5 | | μs |
| | Capacitance between plates | | | 2 | 10 | nF |
| | Total capacitance at pins TSX1,TSX2,TSY1,TSY2 to GND | | | | 100 | pF |
| | internal TSC reference resistance | | 20.9 | 22 | 23.1 | kΩ |
| SWITCH MATRIX SPECIFICATIONS | | | | | | |
| | Tgate resistance | Specified by design | 111 | 160 | 230 | Ω |
| | PMOS resistance | Specified by design | | | 20 | Ω |
| | NMOS resistance | Specified by design | | | 20 | Ω |
| | Quiescent supply current | in TSC standby mode with TSC_M[2..0] = 101 | | 10 | | μA |

POWER PATH

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--------------------------|--|--|------|-----|-----|------|
| QUIESCENT CURRENT | | | | | | |
| I _{QSP1} | Quiescent current, AC or USB mode | Current into AC or USB, AC or USB selected, no load at SYS | | | 20 | μA |
| INPUT SUPPLY | | | | | | |
| V _{BATMIN} | Minimum battery voltage for BAT SWITCH operation | No input power, BAT_SWITCH on | 2.75 | | | V |
| V _{IN(DT)} | Input voltage detection threshold | AC detected when V(AC)-V(BAT) > V _{IN(DT)} ; USB detected when V(USB)-V(BAT) > V _{IN(DT)} | 150 | | | mV |
| V _{IN(NDT)} | Input Voltage removal threshold | AC not detected when V(AC)-V(BAT) < V _{IN(NDT)} ; USB not detected when V(USB)-V(BAT) < V _{IN(NDT)} | | | 75 | mV |
| I _{DISCH} | Internal discharge current at AC and USB input | Activated based on settings in CHGCONFIG3 Bit 0 and Bit 7 | | 95 | | μA |

POWER PATH (continued)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--|---|--|------|--------------------------------|------|----------|
| $T_{DGL(DT)}$ | Power detected deglitch | AC or USB voltage increasing | | 22.5 | | ms |
| $V_{IN(OVP)}$ | Input over voltage detection threshold | | 5.8 | 6 | 6.3 | V |
| POWER PATH TIMING | | | | | | |
| $T_{SW(ACBAT)}$ | Switching from AC to BAT | No USB, AC power removed | | | 200 | μ s |
| $S_{W(USBAT)}$ | T Switching from USB to BAT | No AC, USB power removed | | | 200 | μ s |
| $T_{SW(PSEL)}$ | Switching from USB to AC | I2C | | | 150 | μ s |
| $T_{SW(ACUSB)}$ | Switching from AC/ USB, USB / AC | AC power removed or USB power removed | | | 200 | μ s |
| T_{SYSOK} | SYS power up delay | Measured from power applied to start of power-up sequence | | 11 | | ms |
| POWER PATH INTEGRATED MOSFETS CHARACTERISTICS | | | | | | |
| | AC Input switch dropout voltage | ($I_{LIMIT_{AC}}$ set = 2.5 A $I(SYS) = 1$ A) | | 150 | | mV |
| | USB input switch dropout voltage | $I_{LIMIT_{USB}} = 1300$ mA $I(SYS) = 500$ mA $I_{LIMIT_{USB}} = 1300$ mA $I(SYS) = 800$ mA | | 100 160 | | mV |
| | Battery switch dropout voltage | $V(BAT) = 3.0$ V, $I(BAT) = 1$ A | | 85 | 100 | mV |
| Input Current Limit | | | | | | |
| I_{USB100} | Input current limit; USB pin | USB input current [0,0] | 90 | | 100 | mA |
| I_{USB500} | Input current limit; USB pin | USB input current [0,1] (default) | 450 | | 500 | mA |
| I_{USB800} | Input current limit; USB pin | USB input current [1,0] | 700 | | 800 | mA |
| $I_{USB1300}$ | Input current limit; USB pin | USB input current [1,1] | 1000 | | 1300 | mA |
| I_{AC100} | Input current limit; AC pin | AC input current [0,0] | 90 | | 100 | mA |
| I_{AC500} | Input current limit; AC pin | AC input current [0,1] | 450 | | 500 | mA |
| I_{A1300} | Input current limit; AC pin | AC input current [1,0] | 1000 | | 1300 | mA |
| I_{AC2500} | Input current limit; AC pin | AC input current [1,1] (default) | 2000 | | 2500 | mA |
| POWER PATH SUPPLEMENT DETECTION PROTECTION AND RECOVERY FUNCTIONS | | | | | | |
| V_{BSUP1} | Enter battery supplement mode | AC input current set to 10: 1.3A | | $V_{OUT} \leq V_{BAT} - 45$ mV | | |
| V_{BSUP2} | Exit battery supplement mode | | | $V_{OUT} \geq V_{BAT} - 35$ mV | | |
| $V_{SYS(SC1)}$ | Sys short-circuit detection threshold, power-on | All power path switches set to OFF if $V_{SYS} < V_{SYS(SC1)}$ | 1.4 | 1.8 | 2.0 | V |
| | Short circuit detection threshold hysteresis | | | 50 | | mV |
| $R_{FLT(AC)}$ | Sys Short circuit recovery pull-up resistors | Internal resistor connected from AC to SYS; Specified by design | | 500 | | Ω |
| $R_{FLT(USB)}$ | Sys Short circuit recovery pull-up resistors | Internal resistor connected from USB to SYS; Specified by design | | 500 | | Ω |
| $V_{SYS(SC2)}$ | Output short-circuit detection threshold, supplement mode $V_{BAT} - V_{SYS} > V_{O(SC2)}$ indicates short-circuit | | 200 | 250 | 300 | mV |
| $t_{DGL(SC2)}$ | Deglitch time, supplement mode short circuit | | | 120 | | μ s |
| $t_{REC(SC2)}$ | Recovery time, supplement mode short circuit | | | 60 | | ms |
| $V_{BAT(SC)}$ | BAT pin short-circuit detection threshold | | 1.4 | 1.8 | 2.0 | V |
| $I_{BAT(SC)}$ | Source current for BAT pin short-circuit detection | | 4 | 7.5 | 11 | mA |
| DPPM LOOP⁽¹⁾ | | | | | | |
| V_{DPM} | Threshold at which DPPM loop is enabled. This is the approximate voltage at SYS pin, when the USB or AC switch reaches current limit and the charging current is reduced; Selectable by I2C | Set with Bits <PowerPath DPPM threshold1>; <PowerPath DPPM threshold0> | | 3.5 3.75 4.25 4.50 | | V |

(1) If the DPPM threshold is lower than the battery voltage, supplement mode will be engaged first and the SYS voltage will chatter around the battery voltage; during that condition no DPPM mode is available.

BATTERY CHARGER (1)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---------------------------------|---|--|---------------------------|------------------------------------|---------------------------|------|
| CHARGER SECTION | | | | | | |
| | Battery discharge current | | | | 2 | A |
| V _{O(BATREG)} | Battery charger voltage | Depending on setting in CHGCONFIG2 And internal EEPROM Default = 4.20V | -1% | 4.10 | 1% | V |
| | | | -1% | 4.15 | 1% | |
| | | | -1% | 4.20 | 1% | |
| | | | -1% | 4.25 | 1% | |
| V _{LOWV} | Pre-charge to fast-charge transition threshold | default = 2.9 V set with Bit <Precharge Voltage> | | 2.9 2.5 | | V |
| t _{DGL1(LOWV)} | Deglintch time on pre-charge to fast-charge transition | | | 25 | | ms |
| t _{DGL2(LOWV)} | Deglintch time on fast-charge to pre-charge transition | | | 25 | | ms |
| I _{CHG} | Battery fast charge current range | V _{BAT(REG)} > V _{BAT} > V _{LOWV} , V _{IN} = V _{AC} OR V _{USB} = 5 V | 100 | | 1500 | mA |
| I _{CHG} | Battery fast charge current | V _{BAT} > V _{LOWV} , V _{IN} = 5 V, I _{IN-MAX} > I _{CHG} , no load on SYS pin, thermal loop not active, DPPM loop not active | | K _{SET} /R _{SET} | | A |
| K _{SET} | Fast charge current factor | for a charge current of 1500 mA | 840 | 900 | 1000 | AΩ |
| K _{SET} | Fast charge current factor | for a charge current of 100 mA | 930 | 1100 | 1200 | AΩ |
| I _{PRECHG} | Pre-charge current | | 0.08x I _{CHG} | 0.1x I _{CHG} | 0.12x I _{CHG} | A |
| I _{TERM} | Charge current value for termination detection threshold (internally set) | | 0.08x I _{CHG} | 0.1x I _{CHG} | 0.13x I _{CHG} | A |
| t _{DGL(TERM)} | Deglintch time, termination detected | | | 25 | | ms |
| V _{RCH} | Recharge detection threshold | Voltage below nominal charger voltage | 150 | 100 | 65 | mV |
| t _{DGL(RCH)} | Deglintch time, recharge threshold detected | | | 125 | | ms |
| t _{DGL(NO-IN)} | Delay time, input power loss to charger turn-off | V _{BAT} = 3.6V. Time measured from VIN: 5V → 3.3V 1μs fall-time | | 20 | | ms |
| I _{BAT(DET)} | Sink current for battery detection | | 3 | | 10 | mA |
| t _{DET} | Battery detection timer | | | 250 | | ms |
| T _{CHG} | Charge safety timer | Safety timer range, thermal and DPM not active selectable by I2C with Bits <ChargeSafetyTimerValue1> <ChargeSafetyTimerValue0> | -15% | 4 5 6 8 | 15% | h |
| T _{PRECHG} | Precharge timer | Pre charge timer range, thermal and DPM/DPPM loops not active scalable with <Precharge Time> | 25 50 | 30 60 | 35 70 | min |
| T _{PCHGADD} | Pre-charge safety timer "add-on" time range | Maximum value for pre-charge safety timer, thermal, DPM or DPPM loops always active | 0 | | 2xT _{CHG} | h |
| BATTERY-PACK NTC MONITOR | | | | | | |
| R _{T1} | Pull-up resistor from thermistor to Internal LDO . I2C selectable | 10 k curve 2 NTC | -2% | 7.35 | 2% | kΩ |
| | | 100 k curve 1 NTC | -2% | 62.5 | 2% | kΩ |
| V _{HOT} | High temperature trip point (set to 45°C) | Battery charging | | 860 | | mV |
| V _{HYS(HOT)} | Hysteresis on high trip point (set to 3°C) | Battery charging | | 50 | | mV |
| V _{COLD} | Low temperature trip point (set to 0°C) | Battery charging | | 1660 | | mV |
| V _{HYS(COLD)} | Hysteresis on low trip point (set to 3°C) | Battery charging | | 50 | | mV |
| V _{noNTC} | No NTC detected | NTC error | | 2000 | | mV |
| T _{H_{RMDLY}} | Deglintch time for thermistor detection after thermistor power on | | 3 | | | ms |
| t _{DGL(TS)} | Deglintch time, pack temperature fault detection | Battery charging | | 50 | | ms |

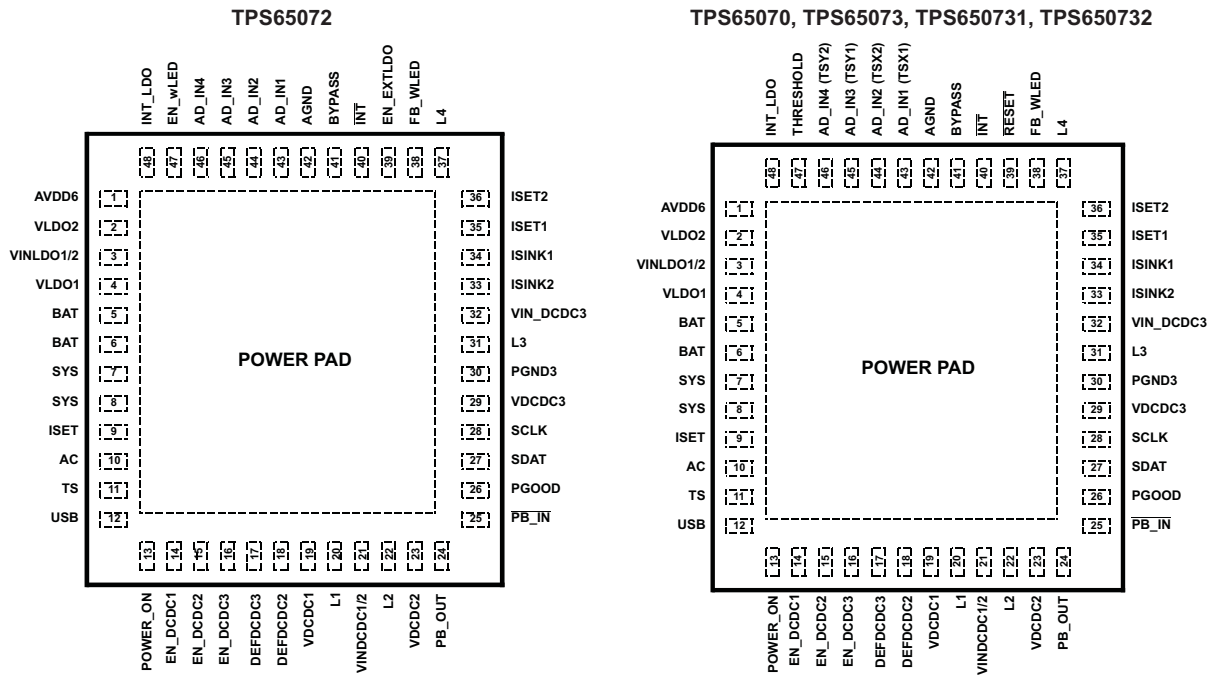
(1) The Battery Charger is DISABLED by default

BATTERY CHARGER (1) (continued)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---------------------------|-------------------------------------|---|-----|-----|-----|------|
| THERMAL REGULATION | | | | | | |
| T _{J(REG)} | Temperature regulation limit | If temperature is exceeded, charge current is reduced | 115 | 125 | 135 | °C |
| T _{J(OFF)} | Charger thermal shutdown | | | 155 | | °C |
| T _{J(OFF-HYS)} | Charger thermal shutdown hysteresis | | | 20 | | °C |

DEVICE INFORMATION

PIN ASSIGNMENT (TOP VIEW)



PIN FUNCTIONS

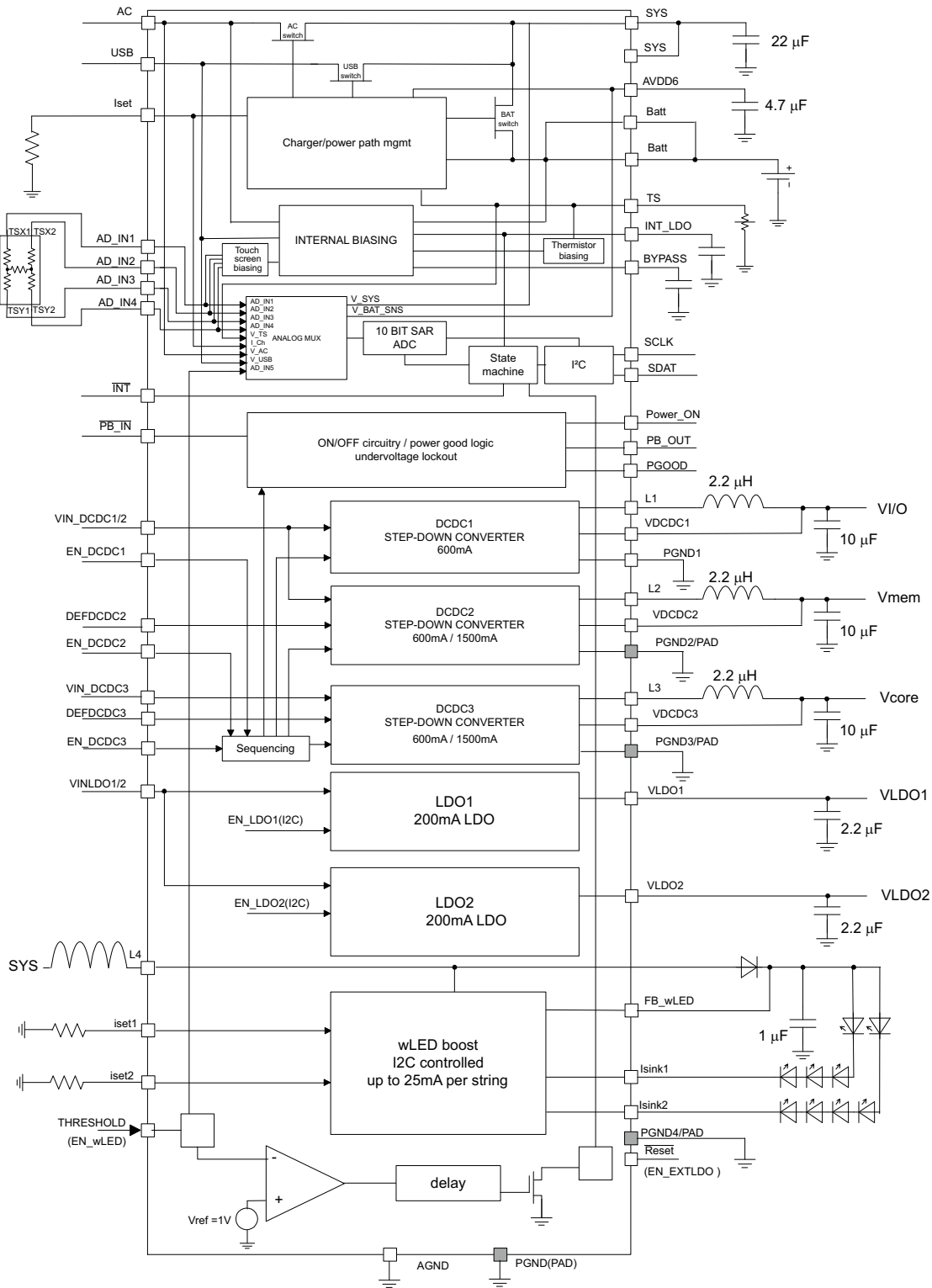
| PIN | | I/O | DESCRIPTION |
|-----------------------|------|-----|--|
| NAME | NO. | | |
| CHARGER BLOCK: | | | |
| AC | 10 | I | Input power for power path manager, connect to external DC supply. Connect external 1µF (minimum) to GND |
| USB | 12 | I | Input power for power path manager, connect to external voltage from a USB port. Connect external 1µF (minimum) to GND. Default input current limit is 500 mA max |
| BAT | 5,6 | O | Charger power stage output, connect to battery. Place a ceramic capacitor of 10µF from these pins to GND |
| AVDD6 | 1 | O | Internal "always-on"-voltage. Connect a 4.7µF cap from AVDD6 to GND |
| SYS | 7, 8 | O | System voltage; output of the power path manager. All voltage regulators are typically powered from this output. |
| TS | 11 | I | Temperature sense input. Connect to NTC thermistor to sense battery pack temperature. TPS6507x can be internally programmed to operate with a 10k curve 2 or 100k curve 1 thermistor. To linearize the thermistor response, use a 75k (for the 10k NTC) or a 360k (for the 100k NTC) in parallel with the thermistor. Default setting is 10k NTC |
| ISET | 9 | I | Connect a resistor from ISET to GND to set the charge current. |
| SCLK | 28 | I | Clock input for the I2C interface. |
| SDAT | 27 | I/O | Data line for the I2C interface. |
| AD_IN1 (TSX1) | 43 | I | Analog input1 for A/D converter TPS65070, TPS65073, TPS650731, TPS650732 only: Input 1 to the x-plate for the touch screen. |

PIN FUNCTIONS (continued)

| PIN | | I/O | DESCRIPTION |
|----------------------------|-----|-----|--|
| NAME | NO. | | |
| AD_IN2 (TSX2) | 44 | I | Analog input2 for A/D converter TPS65070, TPS65073, TPS650731, TPS650732 only: Input 2 to the x-plate for the touch screen |
| AD_IN3 (TSY1) | 45 | I | Analog input3 for A/D converter TPS65070, TPS65073, TPS650731, TPS650732 only: Input 1 to the y-plate for the touch screen |
| AD_IN4 (TSY2) | 46 | I | Analog input4 for A/D converter TPS65070, TPS65073, TPS650731, TPS650732 only: Input 2 to the y-plate for the touch screen |
| BYPASS | 41 | O | Connect a 10 μ F bypass cap from this pin to GND. This pin can optionally be used as a reference output (2.26 V). The maximum load on this pin is 0.1mA. |
| INT_LDO | 48 | O | Connect a 2.2 μ F bypass cap from this pin to GND. The pin is connected to an internal LDO providing the power for the touch screen controller (TSREF). |
| $\overline{\text{INT}}$ | 40 | O | Open drain interrupt output. An interrupt can be generated upon: <ul style="list-style-type: none"> • A touch of the touch screen • Voltage applied or removed at pins AC or USB • PB_IN actively pulled low (optionally actively pulled high) The output is actively pulled low if the interrupt is active. The output goes high after the Bit causing the interrupt in register INT has been read. The interrupt sources can be masked in register INT, so no interrupt is generated and pin $\overline{\text{INT}}$ is pulled high with its external pull-up resistor. |
| CONVERTERS: | | | |
| VINDCDC1/2 | 21 | I | Input voltage for DCDC1 and DCDC2 step-down converter. This pin must be connected to the SYS pin. |
| VDCDC1 | 19 | I | Feedback voltage sense input. For the fixed voltage option, this pin must directly be connected to Vout1, for the adjustable version, this pin is connected to an external resistor divider. |
| L1 | 20 | O | Switch Pin for DCDC1. Connect to Inductor |
| EN_DCDC1 | 14 | I | Enable Input for DCDC1, active high |
| VDCDC2 | 23 | I | Feedback voltage sense input, connect directly to Vout2 |
| DEFDCDC2 | 18 | I | Select Pin of DCDC2 output voltage. |
| L2 | 22 | O | Switch Pin of DCDC2. Connect to Inductor. |
| EN_DCDC2 | 15 | I | Enable Input for DCDC2, active high |
| VINDCDC3 | 32 | I | Input voltage for DCDC3 step-down converter. This pin must be connected to the SYS pin. |
| VDCDC3 | 29 | I | Feedback voltage sense input, connect directly to Vout3 |
| DEFDCDC3 | 17 | I | Select Pin of DCDC3 output voltage. |
| L3 | 31 | O | Switch Pin of DCDC3. Connect to Inductor. |
| EN_DCDC3 | 16 | I | Enable Input for DCDC3, active high |
| PGND3 | 30 | | Power GND for DCDC3. Connect to PGND (PowerPAD) |
| AGND | 42 | | Analog GND, connect to PGND (PowerPAD) |
| VINLDO1/2 | 3 | I | Input voltage for LDO1 and LDO2 |
| VLDO1 | 4 | O | Output voltage of LDO1 |
| VLDO2 | 2 | O | Output voltage of LDO2 |
| L4 | 37 | I | Switch Pin of the white LED (wLED) boost converter. Connect to Inductor and rectifier diode. |
| FB_wLED | 38 | I | Feedback input for the boost converter's output voltage. |
| Iset1 (AD_IN6) | 35 | I | Connect a resistor from this pin to GND to set the full scale current for Isink1 and Isink2 with Bit Current Level in register WLED_CTRL0 set to 1. Analog input6 for the A/D converter. |
| Iset2 (AD_IN7) | 36 | I | Connect a resistor from this pin to GND to set the full scale current for Isink1 and Isink2 with Bit Current Level in register WLED_CTRL0 set to 0. Analog input7 for the A/D converter. |
| Isink1 | 34 | I | Input to the current sink 1. Connect the cathode of the LEDs to this pin. |
| Isink2 | 33 | I | Input to the current sink 2. Connect the cathode of the LEDs to this pin. |
| $\overline{\text{PB_IN}}$ | 25 | I | Enable input for TPS6507x. When pulled LOW, the DCDC converters and LDOs start with the sequencing as programmed internally. Internal 50k Ω pull-up resistor to AVDD6 |

PIN FUNCTIONS (continued)

| PIN | | I/O | DESCRIPTION |
|---------------------------|-----|-----|---|
| NAME | NO. | | |
| POWER_ON | 13 | I | Power_ON input for the internal state machine. After $\overline{\text{PB_IN}}$ was pulled LOW to turn on the TPS6507x, the POWER_ON pin needs to be pulled HIGH by the application processor to keep the system in ON-state when $\overline{\text{PB_IN}}$ is released HIGH. If POWER_ON is released LOW, the DCDC converters and LDOs will turn off when $\overline{\text{PB_IN}}$ is HIGH. |
| PB_OUT | 24 | O | Open drain output. This pin is driven by the status of the /PB_IN input (after debounce). PB_OUT=LOW if PB_IN=LOW |
| PGOOD | 26 | O | Open drain power good output. The delay time equals the setting for $\overline{\text{Reset}}$. The pin will go low depending on the setting in register PGOODMASK. Optionally it is also driven LOW for 0.5ms when PB_IN is pulled LOW for >15s. |
| THRESHOLD | 47 | I | TPS65070, TPS65073, TPS650731, TPS650732: Input for the reset comparator. $\overline{\text{RESET}}$ will be LOW if this voltage drops below 1V. |
| $\overline{\text{RESET}}$ | 39 | O | Open drain active low reset output, reset delay time. The status depends on the voltage applied at THRESHOLD. |
| PowerPAD™ | | | Power ground connection for the PMU. Connect to GND |

Functional Block Diagram


PARAMETER MEASUREMENT INFORMATION

The data sheet graphs were taken on the evaluation module (EVM). Please refer to the EVM user's guide ([SLVU291](#)) for the setup information.

TYPICAL CHARACTERISTICS

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| Efficiency DCDC2 vs Load current / PFM mode up to 1.5A | $V_O = 2.5V$; $V_I = 3.0V, 3.6V, 4.2V, 5V$ | 4 |
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| Efficiency DCDC3 vs Load current / PFM mode up to 1.5A | $V_O = 1.2V$; $V_I = 3.0V, 3.6V, 4.2V, 5V$ | 8 |
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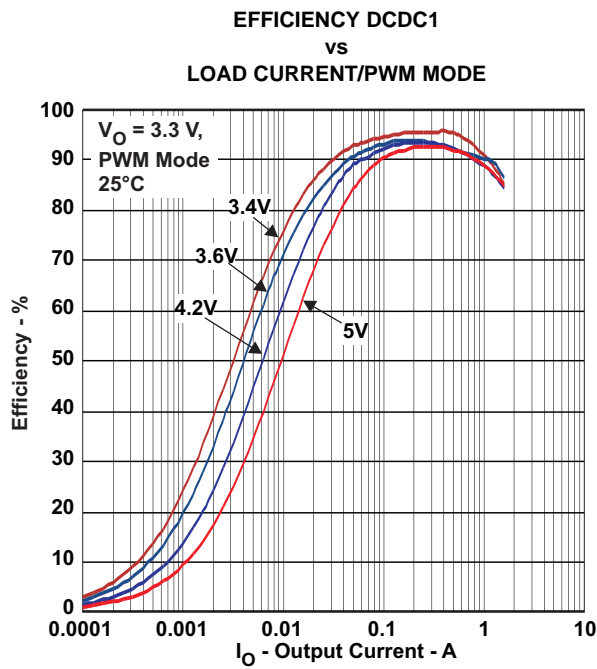


Figure 1.

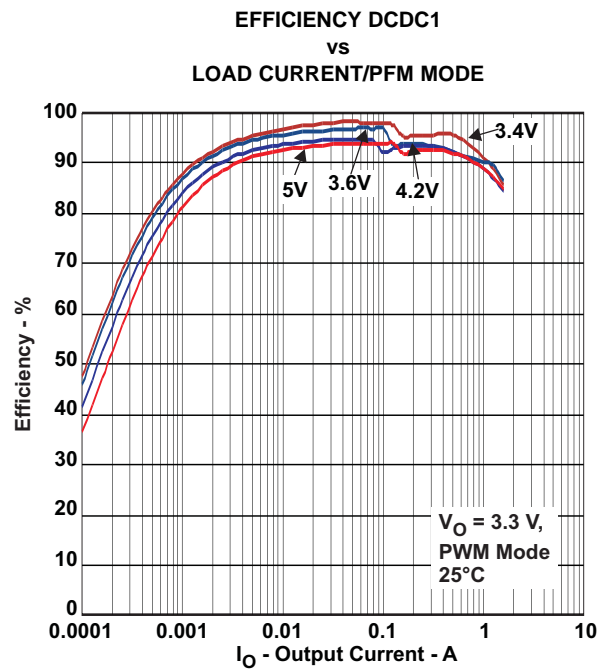


Figure 2.

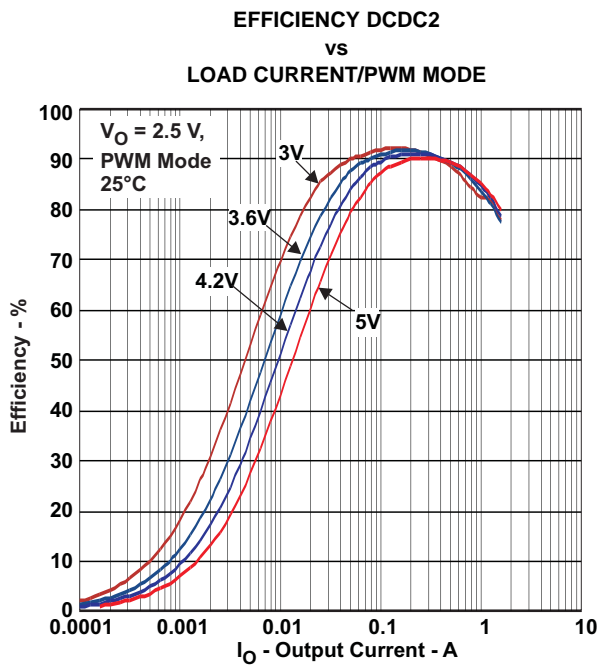


Figure 3.

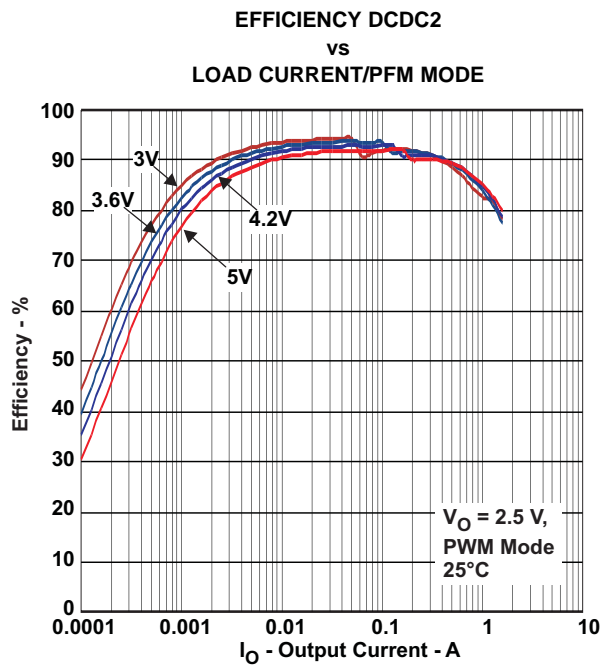


Figure 4.

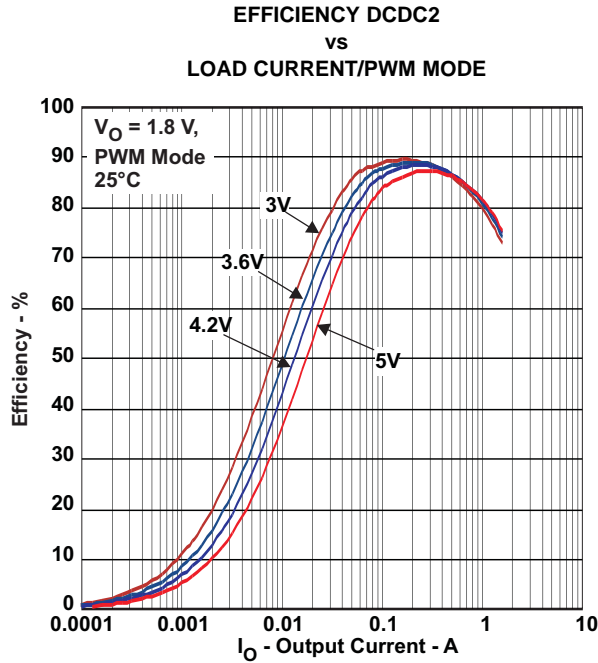


Figure 5.

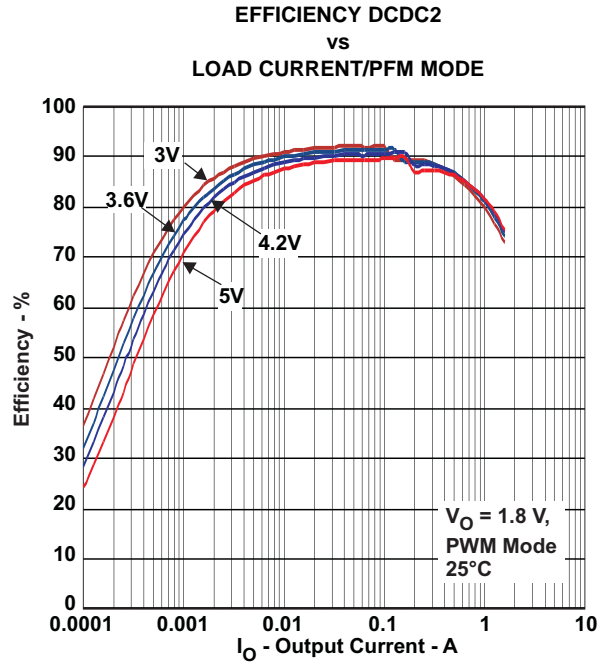


Figure 6.

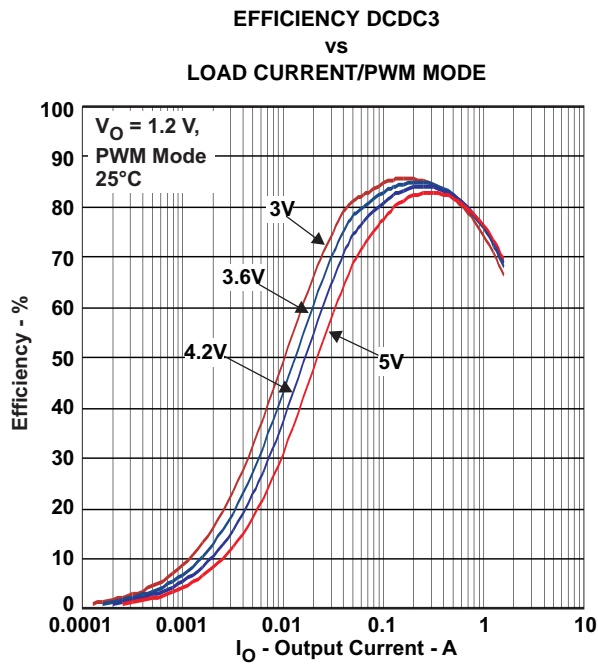


Figure 7.

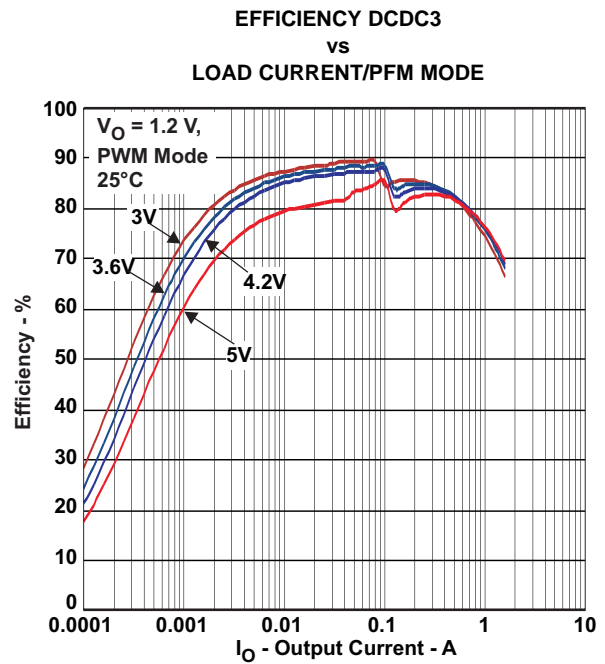


Figure 8.

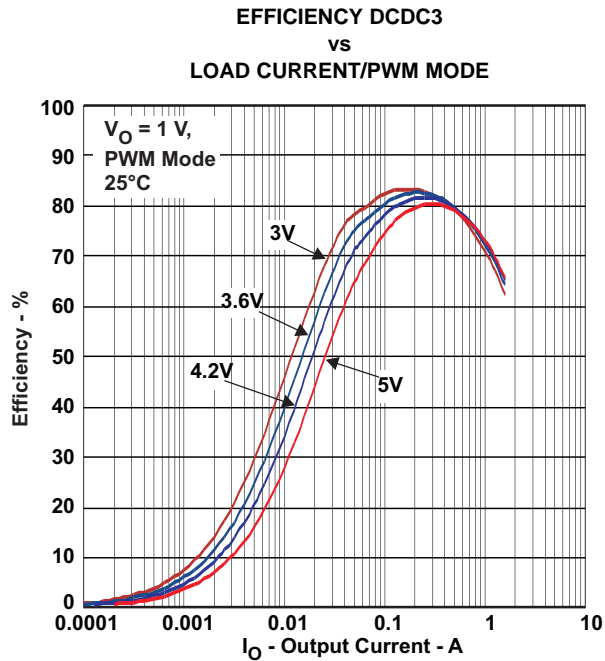


Figure 9.

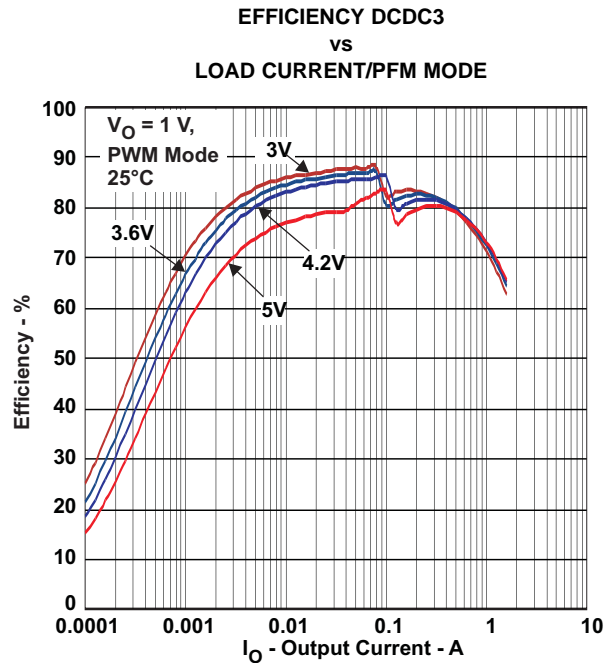


Figure 10.

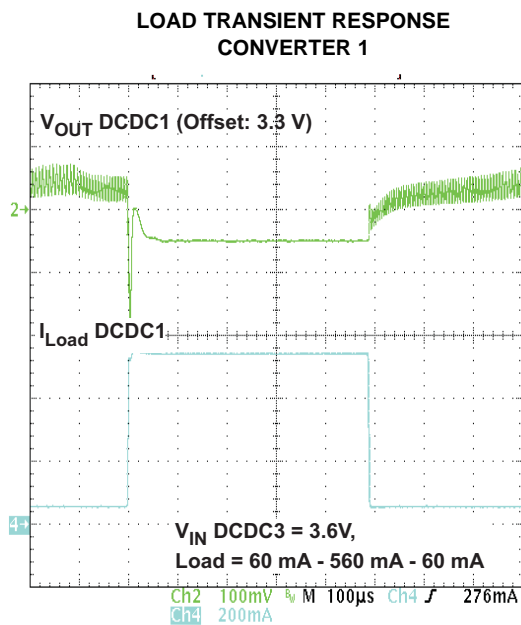


Figure 11.

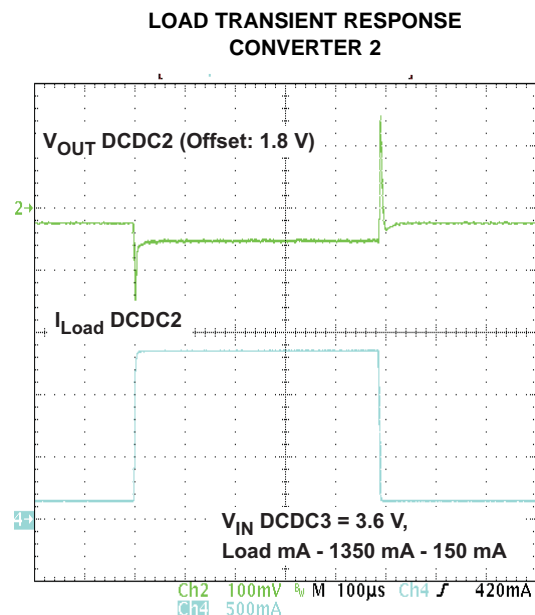


Figure 12.

LOAD TRANSIENT RESPONSE
CONVERTER 3

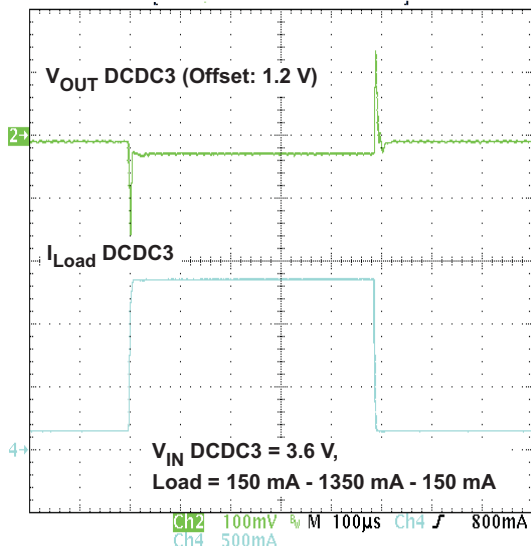


Figure 13.

LINE TRANSIENT RESPONSE
CONVERTER 1

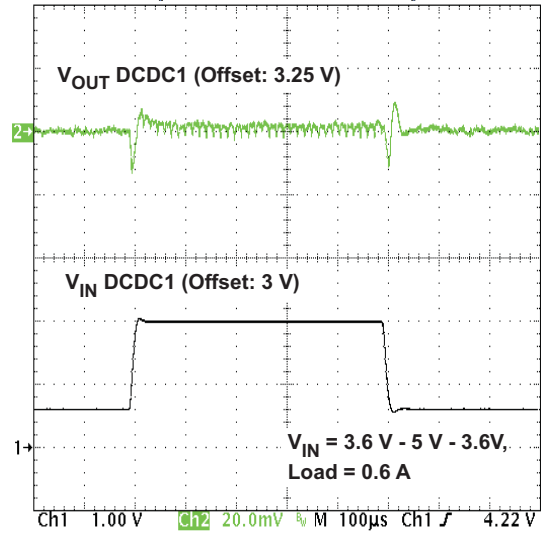


Figure 14.

LINE TRANSIENT RESPONSE
CONVERTER 2

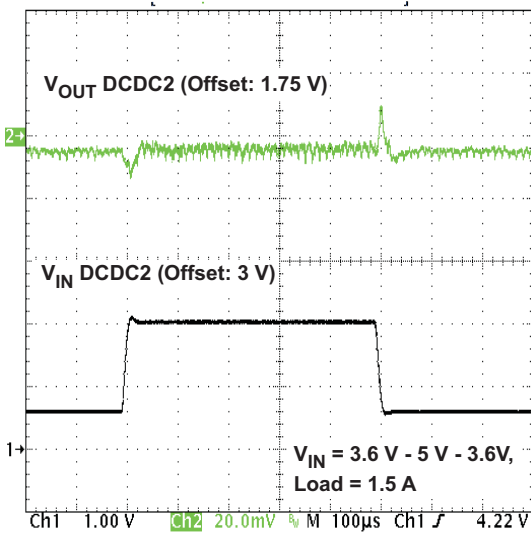


Figure 15.

LINE TRANSIENT RESPONSE
CONVERTER 3

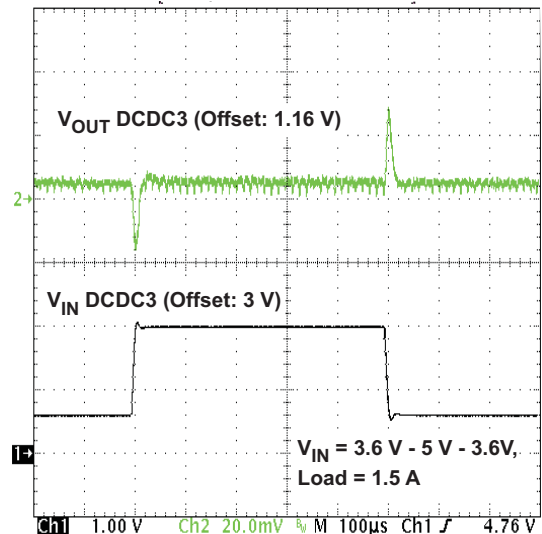


Figure 16.

OUTPUT VOLTAGE RIPPLE AND INDUCTOR CURRENT
CONVERTER 2 – PWM MODE

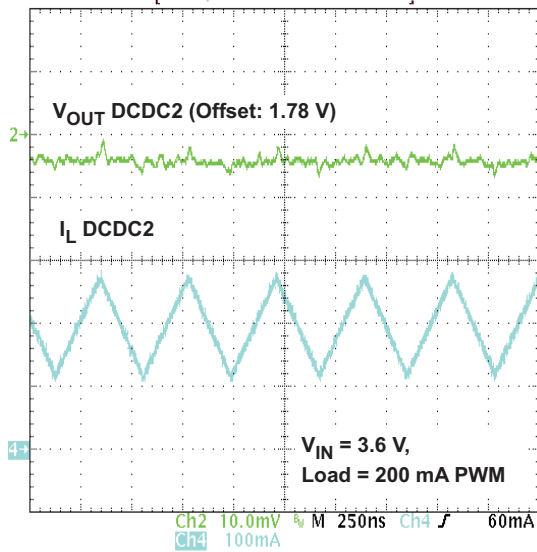


Figure 17.

OUTPUT VOLTAGE RIPPLE AND INDUCTOR CURRENT
CONVERTER 2 – PFM MODE

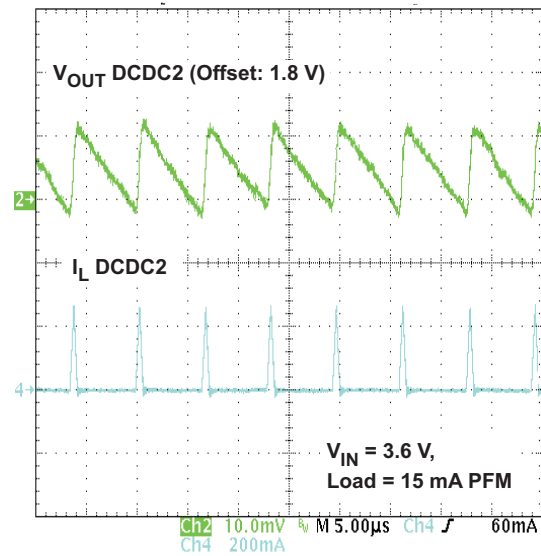


Figure 18.

STARTUP DCDC1, DCDC2, AND DCDC3,
LDO1, LDO2

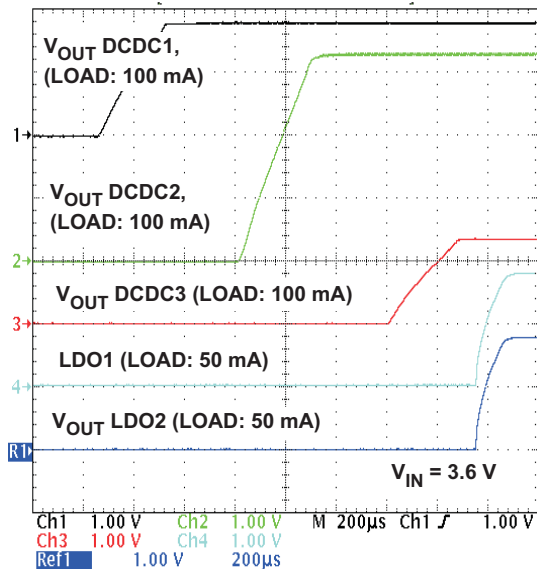


Figure 19.

LOAD TRANSIENT RESPONSE LDO1

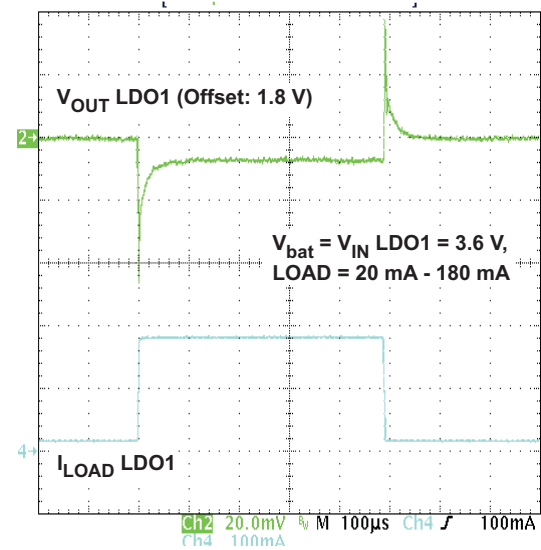


Figure 20.

LINE TRANSIENT RESPONSE LDO1

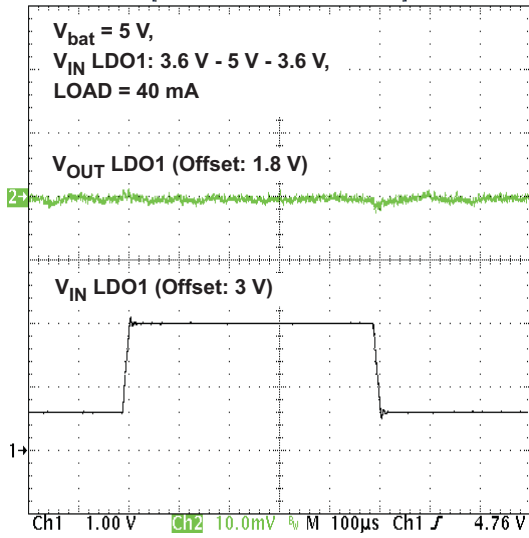


Figure 21.

K_{SET}
vs
R_{ISET}

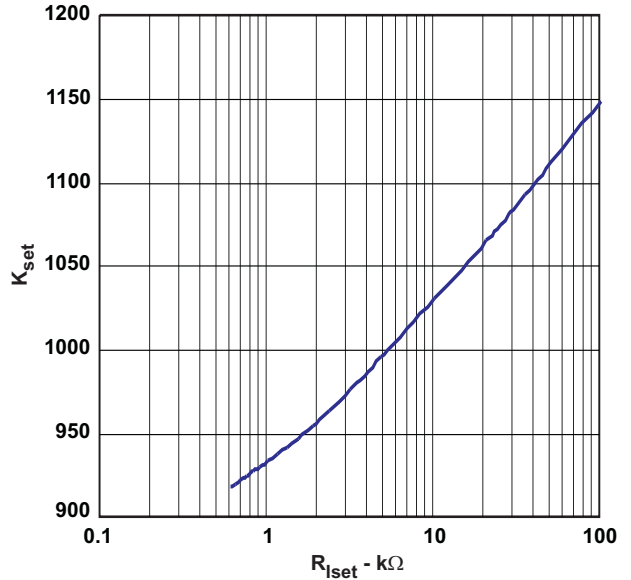


Figure 22.

wLED EFFICIENCY
vs
Duty Cycle

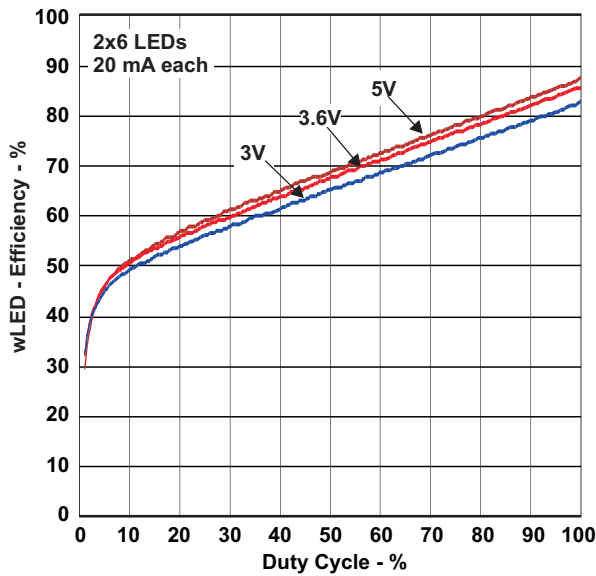


Figure 23.

wLED EFFICIENCY
vs
V_{IN}

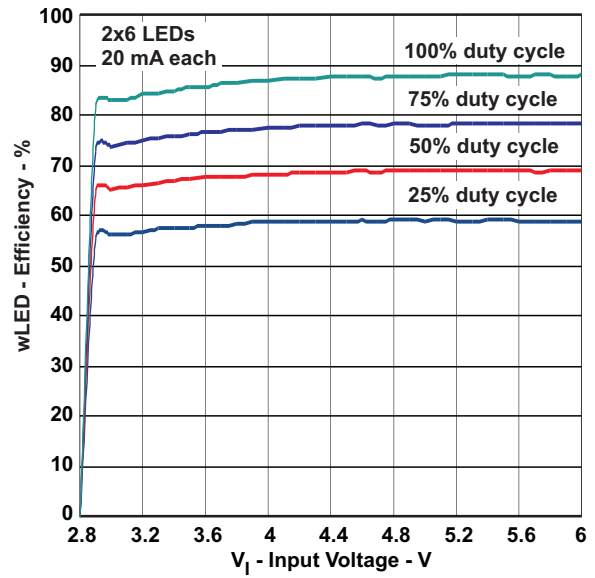


Figure 24.

DETAILED DESCRIPTION

BATTERY CHARGER AND POWER PATH

The integrate a Li-ion linear charger and system power path management targeted at space-limited portable applications. The power the system while simultaneously and independently charging the battery. This feature reduces the number of charge and discharge cycles on the battery, allows for proper charge termination and enables the system to run with a defective or absent battery pack. It also allows instant system turn-on even with a totally discharged battery. The input power source for charging the battery and running the system can be an AC adapter or a USB port. The power-path management feature automatically reduces the charging current if the system load increases. The power-path architecture also permits the battery to supplement the system current requirements when the adapter cannot deliver the peak system currents.

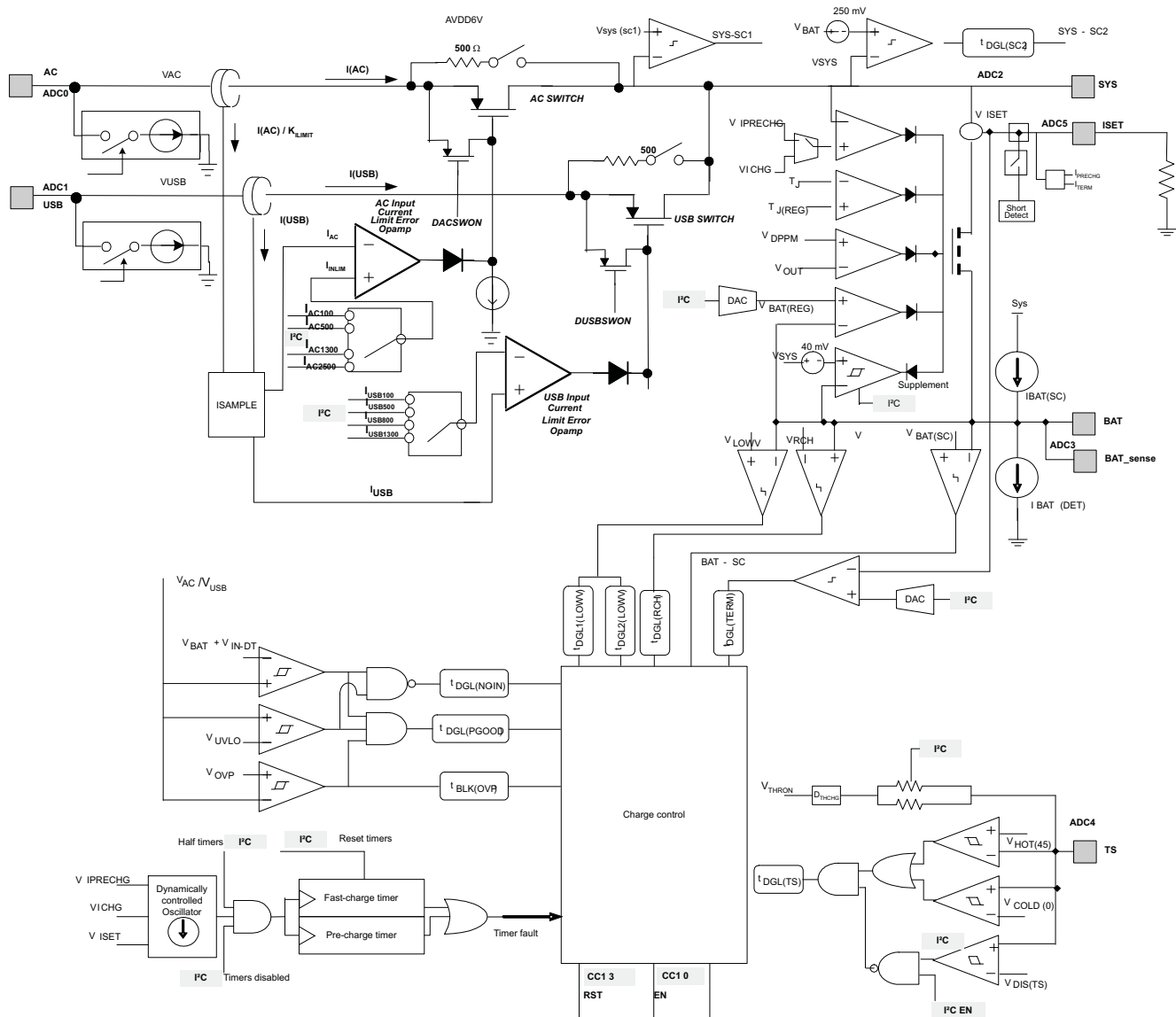


Figure 25. Charger Block Diagram

POWER DOWN

The charger remains in a power down mode when the input voltage at the AC or USB pin is below the under-voltage lockout threshold V_{UVLO} . During the power down mode the host commands at the control pins are not interpreted.

POWER-ON RESET

The charger resets when the input voltage at the AC or USB pin enters the valid range between V_{UVLO} and V_{OVLO} . All internal timers and other circuit blocks are reset. The device then waits for a time period $T_{DGL(PGOOD)}$, after which CHARGER ACTIVE Bit indicates the input power status, and the Iset pin is interpreted.

POWER-PATH MANAGEMENT

There are two inputs to the power path called AC and USB. Both inputs support the same voltage rating but are typically set to a different current limit with AC being at the higher limit and USB at the lower. If voltage is applied at both inputs and both are enabled in register PPATH1 (default setting), AC will be preferred over USB. In this case, the device is only powered from AC and there is no current from USB. If voltage at AC is removed, the USB input will become and is powered from USB. The current at the input pin AC or USB of the power path manager is shared between charging the battery and powering the system load on the SYS pin. Priority is given to the system load. The input current is monitored continuously. If the sum of the charging and system load currents exceeds the preset maximum input current (programmed internally by I2C), the charging current is reduced automatically. See the electrical characteristics or the register description for the default current limit on AC and USB for the different family members.

Figure 26 illustrates what happens in an example case where the battery fast-charge current is set to 500mA, the input current limit is set at 900mA and the system load varies from 0 to 750mA.

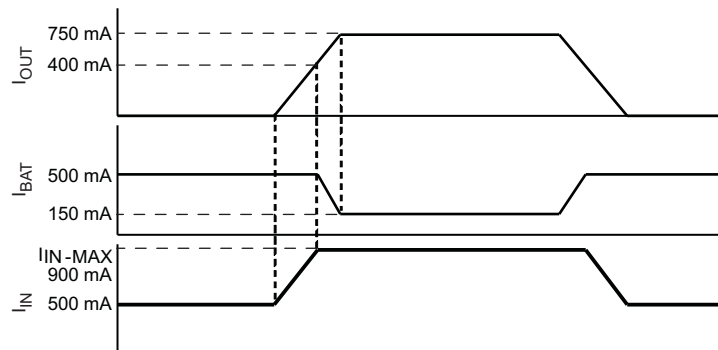


Figure 26. Power Path Functionality

SYS Output

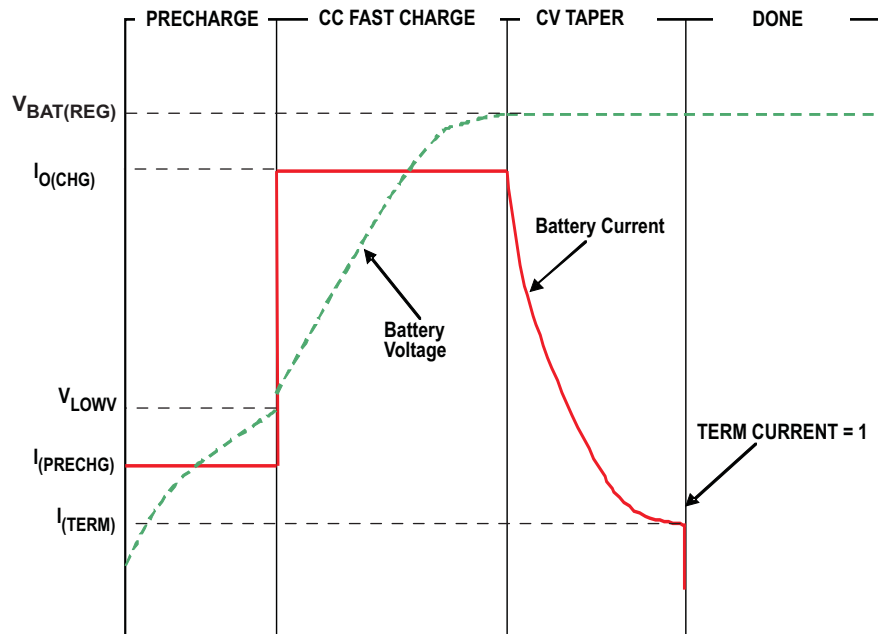
The SYS pin is the output of the power path. When is turned off and there is no voltage at AC or USB, the SYS output is disconnected internally from the battery. When is turned on by pulling $PB_IN = LOW$, the voltage at SYS will ramp with a soft-start. During soft start, the voltage at SYS is ramped with a 30mA current source until the voltage reached 1.8V. During the soft start, the SYS pin must not be loaded by an external load.

BATTERY CHARGING

When Bit CHARGER ENABLE in register CHGCONFIG1 is set to 1, battery charging can begin. First, the device checks for a short-circuit on the BAT pin: $I_{BAT(SC)}$ is turned on till the voltage on the BAT pin rises above $V_{BAT(SC)}$. If conditions are safe, it proceeds to charge the battery.

The battery is charged in three phases: conditioning pre-charge, constant current fast charge (current regulation) and a constant voltage tapering-off (voltage regulation). In all charge phases, an internal control loop monitors the IC junction temperature and reduces the charge current if the internal temperature threshold is exceeded.

Figure 27 shows what happens in each of the three phases:


Figure 27. Battery Charge

In the pre-charge phase, the battery is charged at a current of I_{PRECHG} . The battery voltage starts rising. Once the battery voltage crosses the V_{LOWV} threshold, the battery is charged at a current of I_{CHG} . The battery voltage continues to rise. When the battery voltage reaches $V_{BAT(REG)}$, the battery is held at a constant value of $V_{BAT(REG)}$. The battery current now decreases as the battery approaches full charge. When the battery current reaches I_{TERM} , the TERM CURRENT flag in register CHGCONFIG0 indicates charging done by going high.

Note that termination detection is disabled whenever the charge rate is reduced from the set point because of the actions of the thermal loop, the DPM loop or the V_{IN-LOW} loop.

The value of the fast-charge current is set by the resistor connected from the ISET pin to GND, and is given by the equation

$$I_{CHG} = K_{ISET} / R_{ISET} \quad (1)$$

$$R_{ISET} = K_{ISET} / I_{CHG} \quad (2)$$

Note that if I_{CHG} is programmed as greater than the input current limit, the battery will not charge at the rate of I_{CHG} , but at the slower rate of I_{IN-MAX} (minus the load current on the OUT pin, if any). In this case, the charger timers will be slowed down by 2x whenever the thermal loop or DPPM is active.

I-PRECHARGE:

The value for the pre-charge current is fixed to a factor of 0.1 of the fast charge current (full scale current) programmed by the external resistor R_{set}

I_TERM:

The value for the termination current threshold can be set in register CHGCONFIG3 using Bits TERMINATION CURRENT FACTOR 0 and TERMINATION CURRENT FACTOR 1. The termination current is pre-set to a factor of 0.1 of the fast charge current programmed by the external resistor R_{set} .

Battery Detection and Recharge:

Whenever the battery voltage falls below V_{RCH} ($V_{set}-100mV$), a check is performed to see whether the battery has been removed: current $I_{BAT(DET)}$ is pulled from the battery for a duration t_{DET} . If the voltage on the BAT pin remains above V_{LOWV} , it indicates that the battery is still connected. If the charger is enabled by Bit CHARGER ENABLE in register CHGCONFIG1 set to 1, the charger is turned on again to top up the battery.

If the BAT pin voltage falls below V_{LOWV} in the battery detection test, it indicates that the battery has been removed. The device then checks for battery insertion: it turns on FET Q2 and sources I_{PRECHG} out of the BAT pin for duration t_{DET} . If the voltage does not rise above V_{RCH} , it indicates that a battery has been inserted, and a new charge cycle can begin. If, however, the voltage does rise above V_{RCH} , it is possible that a fully charged battery has been inserted. To check for this, $I_{BAT(DET)}$ is pulled from the battery for t_{DET} : if the voltage falls below V_{LOWV} , a battery is not present. The device keeps looking for the presence of a battery.

Charge Termination On/Off:

Charge termination can be disabled by setting the Bit CHARGE TERMINATION ON/OFF in register CHGCONFIG1 to logic high. When termination is disabled, the device goes through the pre-charge, fast-charge and CV phases, then remains in the CV phase – the charger behaves like an LDO with an output voltage equal to $V_{BAT(REG)}$, able to source current up to I_{CHG} or I_{IN-MAX} , whichever is lesser. Battery detection is not performed.

Timers:

The charger in has internal safety timers for the pre-charge and fast-charge phases to prevent potential damage to either the battery or the system. The default values for the timers can be changed in registers CHGCONFIG1 and CHGCONFIG3. The timers can be disabled by clearing Bit SAFETY TIMERS ENABLE in register CHGCONFIG1. (Note that the timers are disabled when termination is disabled: Bit CHARGE TERMINATION ON/OFF in register CHGCONFIG1 =1).

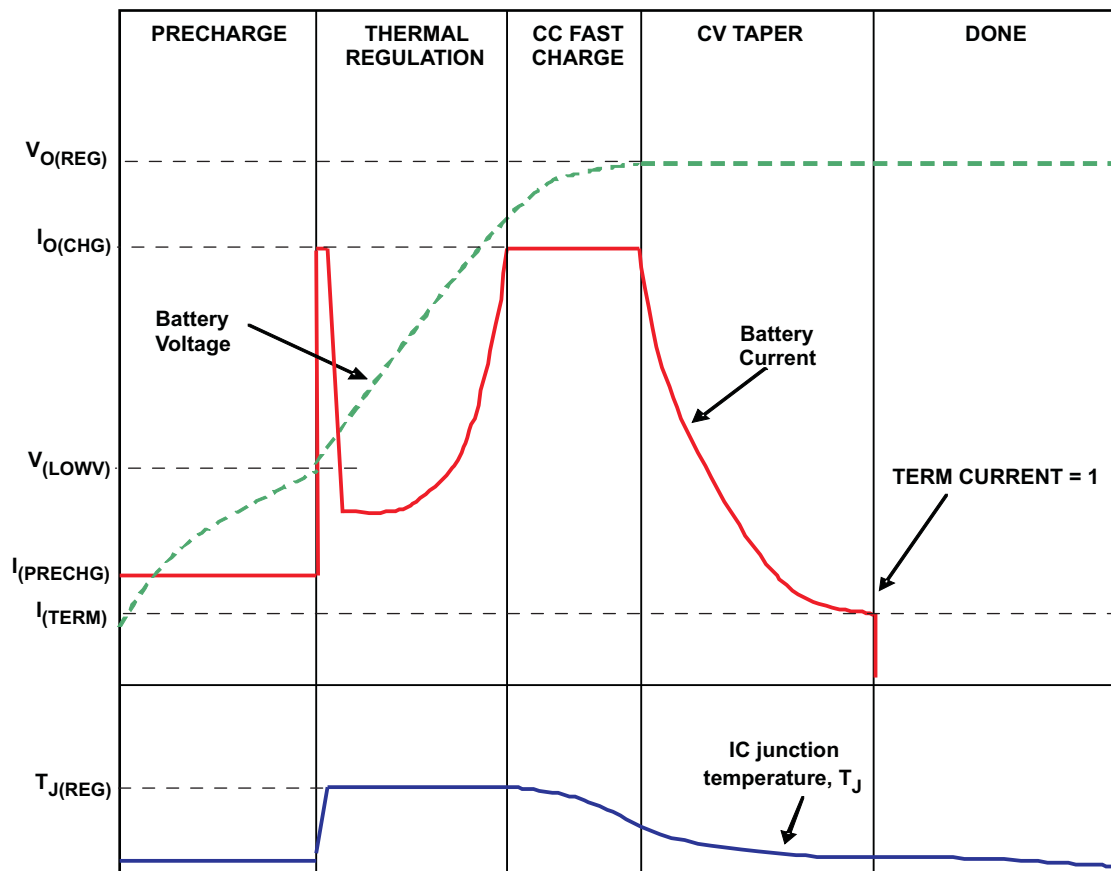
Dynamic Timer Function:

The following events can reduce the charging current and increase the timer durations in the fast charge phase:

1. The system load current increases, and the DPPM loop reduces the available charging current
2. The input current is reduced because the input voltage has fallen to V_{IN-LOW}
3. The device has entered thermal regulation because the IC junction temperature has exceeded $T_{J(REG)}$

In each of these events, the internal timers are slowed down proportionately to the reduction in charging current. Note also that whenever any of these events occurs, termination detection is disabled.

A modified charge cycle with the thermal loop active is shown in [Figure 28](#).


Figure 28. Thermal Loop
Timer Fault:

The following events generate a fault status:

1. If the battery voltage does not exceed V_{LOWV} in time t_{PRECHG} during pre-charging
2. If the battery current does not reach I_{TERM} in time t_{MAXCH} in fast charge (measured from beginning of fast charge).

The fault status is indicated by Bits CHG TIMEOUT or PRECHG TIMEOUT in register CHGCONFIG0 set to 1.

BATTERY PACK TEMPERATURE MONITORING

The device has a TS pin that connects to the NTC resistor in the battery pack. During charging, if the resistance of the NTC indicates that the battery is operating outside the limits of safe operation, charging is turned off. All timers maintain their values. When the battery pack temperature returns to a safe value, charging is resumed, and the timers are also turned back on.

Battery pack temperature sensing is disabled when termination is disabled and the voltage on the TS pin is higher than $V_{DIS(TS)}$ (caused by absence of pack and thus absence of NTC).

The default for the NTC is defined in register CHGCONFIG1 with Bit SENSOR TYPE as a 10k curve 2 NTC. The sensor can be changed to a 100k curve 1 NTC by setting the Bit to 0.

There needs to be a resistor in parallel to the NTC for linearization of the temperature curve. The value for the resistor is given in the table below:

| | |
|--------------|---------------------------------------|
| Sensor type | resistor value in parallel to the NTC |
| 10K curve 2 | 75k |
| 100k curve 1 | 360k |

BATTERY CHARGER STATE DIAGRAM

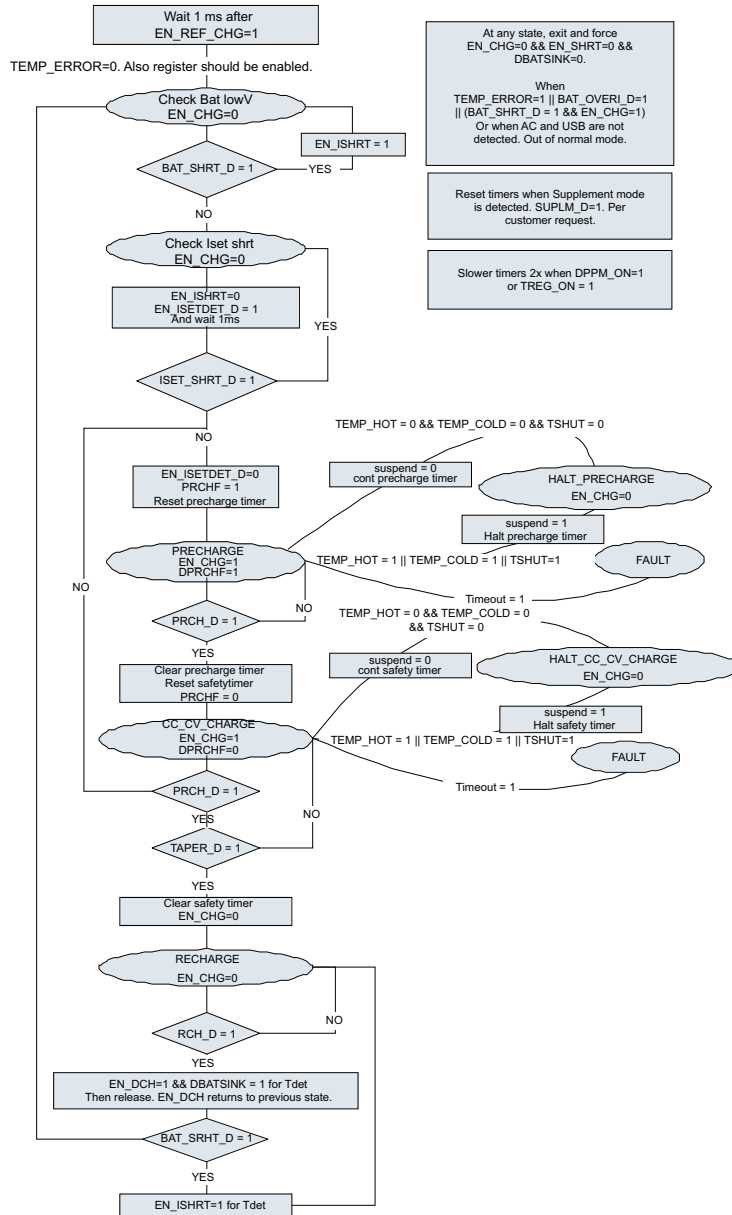


Figure 29. Charger State Machine

DCDC CONVERTERS AND LDOs

OPERATION

The step down converters operate with typically 2.25MHz fixed frequency pulse width modulation (PWM) at moderate to heavy load currents. At light load currents the converter automatically enters Power Save Mode and operates in Pulse Frequency Modulation (PFM) .

During PWM operation the converter use a unique fast response voltage mode controller scheme with input

voltage feed-forward to achieve good line and load regulation allowing the use of small ceramic input and output capacitors. At the beginning of each clock cycle initiated by the clock signal, the High Side MOSFET switch is turned on. The current flows now from the input capacitor via the High Side MOSFET switch through the inductor to the output capacitor and load. During this phase, the current ramps up until the PWM comparator trips and the control logic will turn off the switch. The current limit comparator will also turn off the switch in case the current limit of the High Side MOSFET switch is exceeded. After a dead time preventing shoot through current, the Low Side MOSFET rectifier is turned on and the inductor current will ramp down. The current flows now from the inductor to the output capacitor and to the load. It returns back to the inductor through the Low Side MOSFET rectifier.

The next cycle will be initiated by the clock signal again turning off the Low Side MOSFET rectifier and turning on the High Side MOSFET switch.

The DC-DC converters operate synchronized to each other, with converter 1 as the master. A phase shift of 180° between converter 1 and converter 2 decreases the input RMS current. Therefore smaller input capacitors can be used. Converter 3 operates in phase with converter 1.

DCDC1 Converter

The output voltage for converter 1 is set to a fixed voltage internally in register DEFDCDC1. The voltage can be changed using the I2C interface. The default settings are given in [Table 1](#).

Optionally the voltage can be set by an external resistor divider if configured in register DEFDCDC1.

DCDC2 Converter

The VDCDC2 pin must be directly connected to the DCDC2 converter's output voltage. The DCDC2 converter's output voltage can be selected via the DEFDCDC2 pin or optionally by changing the values in registers DEFDCDC2_LOW and DEFDCDC2_HIGH. If pin DEFDCDC2 is pulled to GND, register DEFDCDC2_LOW defines the output voltage. If the pin DEFDCDC2 is driven HIGH, register DEFDCDC2_HIGH defines the output voltage. Therefore, the voltage can either be changed between two values by toggling pin DEFDCDC2 or by changing the register values. Default voltages for DCDC1, DCDC2 and DCDC3 are:

Table 1. Default Voltages

| | DCDC1 | DCDC2 | | DCDC3 | |
|--|-------|--------------|---------------|--------------|---------------|
| | | DEFDCDC2=LOW | DEFDCDC2=HIGH | DEFDCDC3=LOW | DEFDCDC3=HIGH |
| | | | | | |

DCDC3 Converter

The VDCDC3 pin must be directly connected to the DCDC3 converter's output voltage. The DCDC3 converter's output voltage can be selected via the DEFDCDC3 pin or optionally by changing the values in registers DEFDCDC3_LOW and DEFDCDC3_HIGH. If pin DEFDCDC3 is pulled to GND, register DEFDCDC3_LOW defines the output voltage. If the pin DEFDCDC3 is driven HIGH, register DEFDCDC3_HIGH defines the output voltage. Therefore, the voltage can either be changed between two values by toggling pin DEFDCDC3 or by changing the register values.

LDO2 can optionally be forced to follow the voltage defined for DCDC3 by setting Bit LDO2 TRACKING in register DEF LDO2.

POWER SAVE MODE

The Power Save Mode is enabled by default. If the load current decreases, the converter will enter Power Save Mode operation automatically. During Power Save Mode the converter skips switching and operates with reduced frequency in PFM mode and with a minimum quiescent current to maintain high efficiency. The converter will position the output voltage typically +1% above the nominal output voltage. This voltage positioning feature minimizes voltage drops caused by a sudden load step.

The transition from PWM Mode to PFM Mode occurs once the inductor current in the Low Side MOSFET switch becomes 0.

During the Power Save Mode the output voltage is monitored with a PFM comparator. As the output voltage falls below the PFM comparator threshold of $V_{OUTnominal} + 1\%$, the device starts a PFM pulse. For this the High Side MOSFET switch will turn on and the inductor current ramps up. Then it will be turned off and the Low Side MOSFET switch will be turned on until the inductor current becomes 0.

The converter effectively delivers a current to the output capacitor and the load. If the load is below the delivered current the output voltage will rise. If the output voltage is equal or higher than the PFM comparator threshold, the device stops switching and enters a sleep mode with typical $15\mu A$ current consumption.

In case the output voltage is still below the PFM comparator threshold, further PFM current pulses will be generated until the PFM comparator threshold is reached. The converter starts switching again once the output voltage drops below the PFM comparator threshold.

With a single threshold comparator, the output voltage ripple during PFM Mode operation can be kept very small. The ripple voltage depends on the PFM comparator delay, the size of the output capacitor and the inductor value. Increasing output capacitor values and/or inductor values will minimize the output ripple.

The PFM Mode is left and PWM Mode entered in case the output current can not longer be supported in PFM Mode or if the output voltage falls below a second threshold, called PFM comparator low threshold. This PFM comparator low threshold is set to -1% below nominal V_{out} , and enables a fast transition from Power Save Mode to PWM Mode during a load step. In Power Save Mode the quiescent current is reduced typically to $15\mu A$.

The Power Save Mode can be disabled through the I2C interface for each of the step-down converters independent from each other. If Power Save Mode is disabled, the converter will then operate in fixed PWM mode.

Dynamic Voltage Positioning

This feature reduces the voltage under/overshoots at load steps from light to heavy load and vice versa. It is active in Power Save Mode. It provides more headroom for both the voltage drop at a load step, and the voltage increase at a load throw-off. This improves load transient behavior. At light loads, in which the converter operates in PFM Mode, the output voltage is regulated typically 1% higher than the nominal value. In case of a load transient from light load to heavy load, the output voltage drops until it reaches the PFM comparator low threshold set to -1% below the nominal value and enters PWM mode. During a load throw off from heavy load to light load, the voltage overshoot is also minimized due to active regulation turning on the Low Side MOSFET switch.

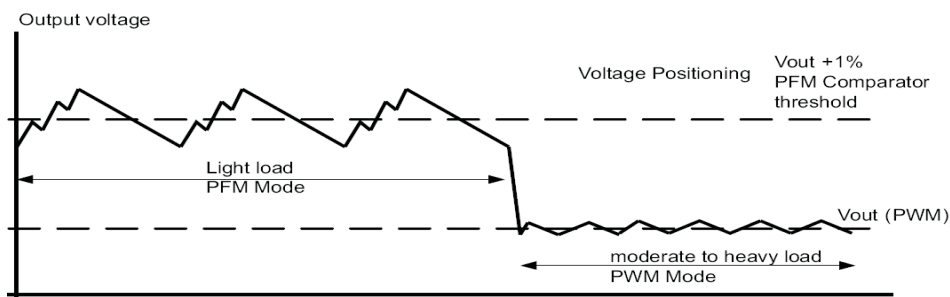


Figure 30. Power Save Mode

100% Duty Cycle Low Dropout Operation

The device starts to enter 100% duty cycle Mode once the input voltage comes close the nominal output voltage. In order to maintain the output voltage, the High Side MOSFET switch is turned on 100% for one or more cycles.

With further decreasing V_{IN} the High Side MOSFET switch is turned on completely. In this case the converter offers a low input-to-output voltage difference. This is particularly useful in battery-powered applications to achieve longest operation time by taking full advantage of the whole battery voltage range.

The minimum input voltage to maintain regulation depends on the load current and output voltage, and can be calculated as:

$$V_{in_{min}} = V_{out_{max}} + I_{out_{max}} \times (R_{DSon_{max}} + R_L) \quad (3) \quad (3)$$

With:

$I_{out_{max}}$ = maximum output current plus inductor ripple current
 $R_{DSon_{max}}$ = maximum P-channel switch R_{DSon} .
 R_L = DC resistance of the inductor
 $V_{out_{max}}$ = nominal output voltage plus maximum output voltage tolerance

Under-Voltage Lockout

The under voltage lockout circuit prevents the device from malfunctioning at low input voltages and from excessive discharge of the battery and disables the DCDC converters and LDOs. The under-voltage lockout threshold is configurable in the range of typically 2.8V to 3.25V with falling voltage at the SYS pin. The default undervoltage lockout voltage as well as the hysteresis are defined in register CON_CTRL2. The default undervoltage lockout voltage is 3.0V with 500mV hysteresis.

SHORT-CIRCUIT PROTECTION

The High Side and Low Side MOSFET switches are short-circuit protected with maximum output current = ILIMF. Once the High Side MOSFET switch reaches its current limit, it is turned off and the Low Side MOSFET switch is turned. The High Side MOSFET switch can only turn on again, once the current in the Low Side MOSFET switch decreases below its current limit.

Soft Start

The 3 step-down converters in have an internal soft start circuit that controls the ramp up of the output voltage. The output voltage ramps up from 5% to 95% of its nominal value within typ. 250 μ s. This limits the inrush current in the converter during start up and prevents possible input voltage drops when a battery or high impedance power source is used. The Soft start circuit is enabled after the start up time t_{start} has expired.

During soft start, the output voltage ramp up is controlled as shown in [Figure 31](#).

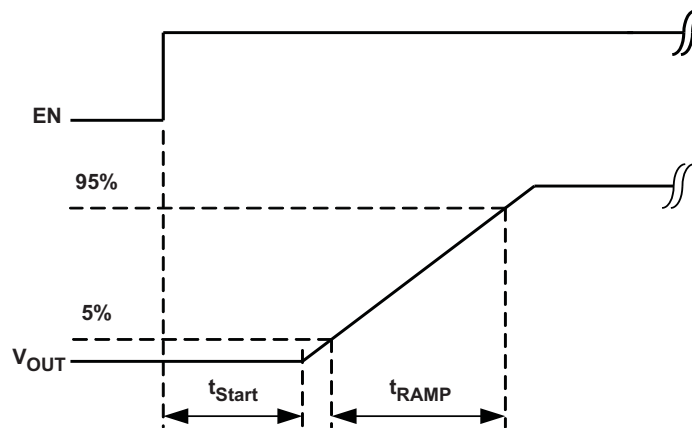


Figure 31. Soft Start

ENABLE

To start up each converter independently, the device has a separate enable pin for each of the DCDC converters. In order to enable any converter with its enable pins, the devices need to be in ON-state by pulling $PB_IN=LOW$ or $POWER_ON=HIGH$. The sequencing option programmed needs to be $DCDC_SQ[2..0] = 101$.

If EN_DCDC1 , EN_DCDC2 , EN_DCDC3 are set to high, the corresponding converter starts up with soft start as previously described.

Pulling the enable pin low forces the device into shutdown, with a shutdown quiescent current as defined in the electrical characteristics. In this mode, the high side and low side MOSFETs are turned-off, and the entire internal control circuitry is switched-off. If disabled, the outputs of the DCDC converters are pulled low by internal 250 Ω resistors, actively discharging the output capacitor. For proper operation the enable pins must be terminated and must not be left floating.

Optionally, there is internal sequencing for the DCDC converters and both LDOs available. Bits DCDC_SQ[0..2] in register CON_CTRL1 define the start-up and shut-down sequence for the DCDC converters. Depending on the sequencing option, the signal at EN_DCDC1, EN_DCDC2 and EN_DCDC3 are ignored. For automatic internal sequencing, the enable signals which are not used should be connected to GND.

LDO1 and LDO2 will start up automatically as defined in register LDO_CTRL1. See details about the sequencing options in the register description for CON_CTRL1 and LDO_CTRL1.

RESET

The contain circuitry that can generate a reset pulse for a processor with a certain delay time. The input voltage at a comparator is sensed at an input called THRESHOLD. When the voltage exceeds the threshold, the output goes high with the delay time defined in register PGOOD. The reset circuitry is not active in OFF-state. The pull-up resistor for this open drain output must not be connected directly to the battery as this may cause a leakage path when the power path (SYS voltage) is turned off. The reset delay time equals the setting for the PGOOD signal.

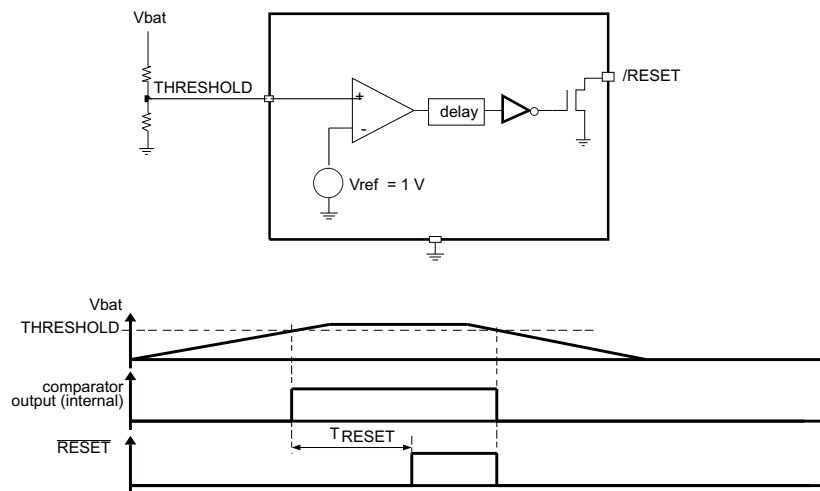


Figure 32. Reset Timing

PGOOD (reset signal for applications processor)

This open drain output generates a power-good signal depending on the status of the power good Bits for the DCDC converters and the LDOs. Register PGOODMASK defines which of the power good Bits of the converters and LDOs are used to drive the external PGOOD signal low when the voltage is below the target value. If e.g., Bit MASK DCDC2 is set to 1, the PGOOD pin will be driven low as long as the output of DCDC2 is below the target voltage. If the output voltage of DCDC2 rises to its nominal value, the PGOOD pin will be released after the delay time defined. See the default settings in the register description.

PB_IN (Push-button IN)

This pin is the ON/OFF button for the PMU to leave OFF-state and enter ON-state by pulling this pin to GND. Entering ON-state will first ramp the output voltage of the power path (SYS), load the default register settings and start up the DCDC converters and LDOs with the sequencing defined. In ON-state, the I2C interface is active and the wLED converter can be enabled. The system turns on if PB_IN is pulled LOW for >50ms (debounce time) AND the output voltage of the power path manager is above the undervoltage lockout voltage ($AVDD6 > 3V$). This is for $V_{bat} > 3V$ OR $V_{AC} > 3V$ OR $V_{USB} > 3V$. The default voltage for the undervoltage lockout voltage can be changed with Bits <UVLO1>, <UVLO0> in register CON_CTRL2. The value will be valid until the device was turned off completely by entering Off state. The system turns off if PB_IN is released OR the system voltage falls below the undervoltage lockout voltage of 3V. This is the case when either the battery voltage drops below 3.0V or the input voltage at the pins AC or USB is below 3V. In order to keep the enabled after PB_IN is released HIGH, there is an input pin called POWER_ON which needs to be pulled HIGH before the PB_IN button is released. POWER_ON=HIGH will typically be asserted by the application processor to keep the PMU in ON-state after the power button at PB_IN is released.

In addition to this, there is a 15s timer which will drive PGOOD=LOW for 0.5ms when 15s are expired. The 15s timer is enabled again when PB_IN is released HIGH. If PB_IN is pulled LOW for 30s continuously, PGOOD will be driven LOW only once after the first 15s. When PGOOD is driven LOW due to PB_IN=low for 15s, all registers in are set to their default value. See [Figure 33](#).

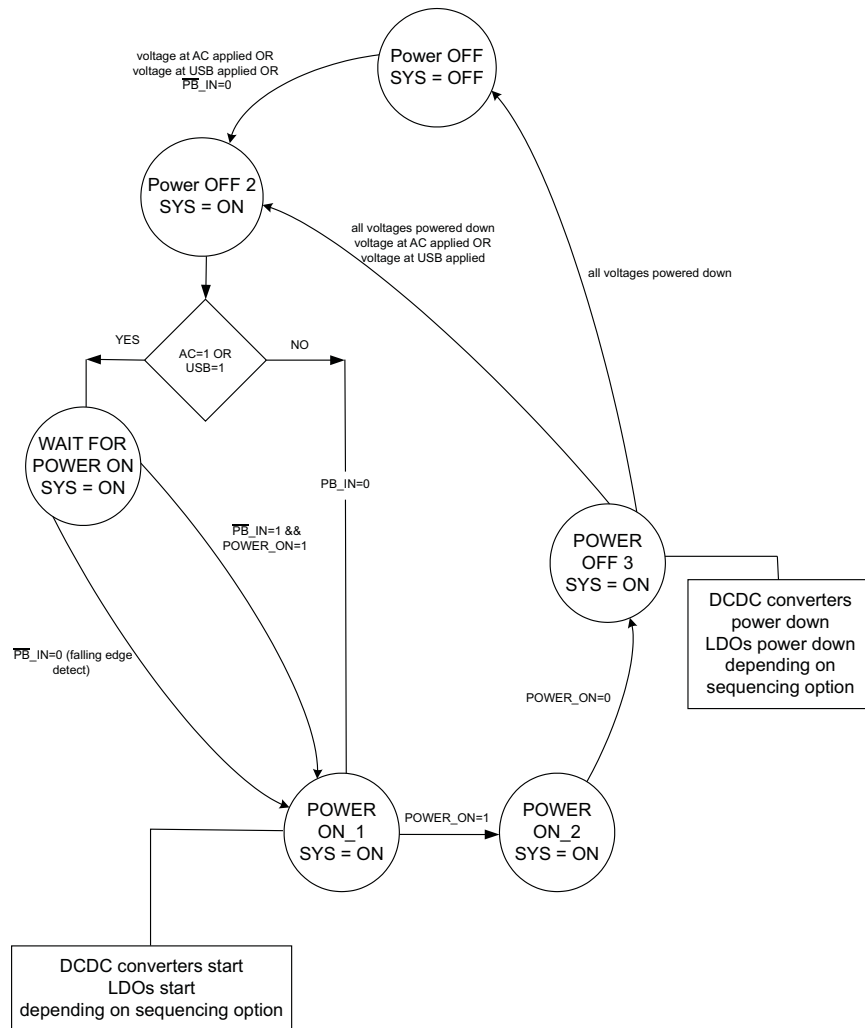


Figure 33. State Machine

PB_OUT

This pin is a status output. PB_OUT is used as the wake-up interrupt to an application processor based on the status of PB_IN. If PB_IN=LOW, PB_OUT = LOW (after 50ms debounce). If PB_IN=HIGH, PB_OUT= high impedance (HIGH).

The pull-up resistor for this open drain output must not be connected directly to the battery as this may cause a leakage path when the power path (SYS) is turned off.

POWER_ON

This pin is an input to the PMU which needs to be pulled HIGH for the PMU to stay in POWER ON_2-state once PB_IN is released. Once this pin is pulled LOW while PB_IN=LOW, the PMU is shutting down without delay, turning off the DCDC converters and the LDOs. If POWER_ON is pulled HIGH while there is power at USB or AC, the will enter POWER ON_2-state and start the DCDC converters and LDOs according to the sequence programmed. See [Figure 33](#).

SHORT-CIRCUIT PROTECTION

All outputs are short circuit protected with a maximum output current as defined in the electrical specifications.

THERMAL SHUTDOWN

As soon as the junction temperature, T_j , exceeds typically 150°C for the DCDC converters or LDOs, the device goes into thermal shutdown. In this mode, the high side MOSFETs are turned-off. The device continues its operation when the junction temperature falls below the thermal shutdown hysteresis again. A thermal shutdown for one of the DCDC converters or LDOs will disable all step-down converters simultaneously.

Low Dropout Voltage Regulators

The low dropout voltage regulators are designed to operate well with low value ceramic input and output capacitors. They operate with input voltages down to 1.8V. The LDOs offer a maximum dropout voltage of 200mV at rated output current. Each LDO supports a current limit feature. LDO2 is enabled internally using Bit ENABLE_LDO2 in register CON_CTRL1. The output voltage for LDO2 is defined by the settings in register DEFLDO2. LDO2 can also be configured in such a way that it follows the output voltage of converter DCDC3 by setting Bit LDO2 TRACKING = 1 in register DEFLDO2.

LDO1 is enabled internally using Bit ENABLE_LDO1 in register CON_CTRL1. The output voltage for LDO1 is defined by the settings in register DEFLDO1. LDO1 can also be enabled automatically depending on the settings in register LDO_CTRL1.

White LED Boost Converter

The converter is in shutdown mode by default and is being turned on by setting the enable Bit with the I2C interface or for TPS65072 with pin EN_wLED. The enable Bit is located in register WLED_CTRL1 and is called ENABLE_ISINK as it enables the current sink for the white LEDs. Once enabled, an output voltage is automatically generated at FB_wLED, high enough to force the programmed current through the string of white LEDs. Two strings of white LEDs can be powered. The current in each of the two strings is regulated by an internal current sink at pins Isink1 and Isink2. The maximum current through the current sinks is set with two external resistors connected from pins ISET1 and ISET2 to GND. ISET1 sets the maximum current when Bit CURRENT_LEVEL in register WLED_CTRL2 is set to 1. If this Bit is set to 0, which is the default setting, the maximum current is defined by the resistor connected at ISET2. This allows change between two different maximum current settings during operation. The LED current can further be dimmed with an internal PWM signal. The duty cycle for this PWM signal can be changed with the Bits LED DUTY CYCLE 0 to LED DUTY CYCLE 6 in register WLED_CTRL2 in a range from 1% to 100%. In case a dimming ratio higher than 1:100 is needed, the maximum LED current need to be changed to a lower value as defined with Iset2. In order to do this without any flicker, the PWM dimming and the current level is defined in the same register, so both settings can be changed at the same time with a single write access to register WLED_CTRL2. An internal overvoltage protection limits the maximum voltage at FB_wLED to 37V typically. The output voltage at FB_WLED also has a lower limit which is set to 12V. In case less than 4LEDs are used, the output voltage at the boost converter will not drop below 12V but the voltage from ISINK1 and ISINK2 to GND is increased accordingly.

A/D Converter

The 10Bit successive approximation (SAR) A/D converter with an input multiplexer can be used to monitor different voltages in the system. These signals are monitored:

- Battery voltage
- Voltage at AC input
- Voltage at SYS output
- Input voltage of battery charger
- Battery temperature
- Battery charge current (voltage at pin Iset; $I_{charge} = U_{ISET}/R_{set} \times K_{ISET}$)
- External voltage 1 to external voltage 4 (AD_IN1 to AD_IN4); 0V to 2.25V
- Optionally: External voltage 5 to external voltage 7 (AD_IN5 to AD_IN7); 0V to 6.0V
- Internal channel AD_IN14 and AD_IN15 for touch screen measurements

The A/D converter uses an internal 2.26V reference. The reference needs a bypass capacitor for stability which

is connected to pin BYPASS. The pin can be used as a reference output with a maximum output current of 0.1mA. The internal reference voltage is forced to be on when the ADC or the touch screen interface is enabled. The reference voltage can additionally forced to be on using Bit Vref_enable in register ADCONFIG while ADC and touch screen are off to allow external circuits to be supplied with a precise reference voltage while ADC and touch screen are not used.

Touch Screen Interface

The touch screen itself consists of two parallel plates, called the X and Y plates, separated by short distance; contact is initiated by using a stylus or your finger. This action creates a series of resistances noted by RX1, RX2, RY1, RY2, and Rcontact, shown in Figure 35. The points shown in the diagram as TSX1, TSX2, TSY1 and TSY2 are connected to the touch screen interface. The resistances RX1 and RX2 scale linearly with the x-position of the point of contact, where the RY1 and RY2 resistances scale with the y-position. The Rcontact resistance decreases as the pressure applied at the point of contact increases and increases as the pressure decreases. Using these relationships, the touch screen interface can make measurements of either position or pressure.

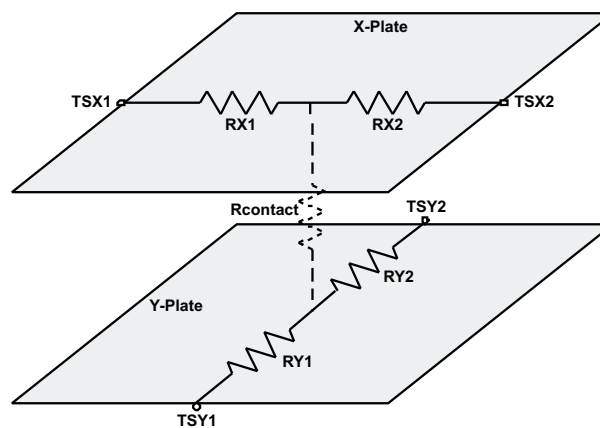


Figure 34. Touch Screen

The touch screen interface consists of a digital state machine, a voltage reference, and an analog switch matrix which is connected to the four wire resistive touch screen inputs (TSX1, TSX2, TSY1, TSY2) and an internal 10-Bit ADC. The state machine controls the sequencing of the switch matrix to cycle through the three types of measurement modes (position, pressure, plate resistance) and the low power standby mode. The separate internal voltage reference (TSREF) is disabled in standby and off modes. The voltage is generated by an internal LDO. Its voltage is bypassed by a capacitor connected to pin INT_LDO. The state of the touch screen is controlled by the TSC_M[2,0] Bits of the TSCMODE register (08h) as shown in Table 2. The touch screen controller uses transfer gates to the internal ADC on input channels AD_IN14 and AD_IN15.

Table 2. TSC Modes

| CONTROL MULTIPLEXER | | | CONNECTIONS | | | | MODE | MEASUREMENT |
|---------------------|--------|--------|------------------|------------------|------------------|------------------|--------------------------------|-----------------------|
| TSC_M2 | TSC_M1 | TSC_M0 | TSX1 | TSX2 | TSY1 | TSY2 | | |
| 0 | 0 | 0 | TSREF PMOS | GND NMOS | ADC_IN3 TGATE | ADC_IN4 TGATE | X-Position | Voltage TSY1 |
| 0 | 0 | 1 | ADC_IN1 TGATE | ADC_IN2 TGATE | TSREF PMOS | GND NMOS | Y-Position | Voltage TSX1 |
| 0 | 1 | 0 | TSREF | TSREF | GND NMOS | GND NMOS | Pressure | Current TSX1 and TSX2 |
| 0 | 1 | 1 | TSREF PMOS | GND NMOS | HiZ | HiZ | Plate X Reading on ADC_IN14 | Current TSX1 |
| 1 | 0 | 0 | HiZ | HiZ | TSREF PMOS | GND NMOS | Plate Y Reading on ADC_IN14 | Current TSY1 |
| 1 | 0 | 1 | TSREF TGATE | TSREF TGATE | GND NMOS | GND NMOS | TSC standby | Voltage TSX1 and TSX2 |

Table 2. TSC Modes (continued)

| CONTROL MULTIPLEXER | | | CONNECTIONS | | | | MODE | MEASUREMENT |
|---------------------|--------|--------|--------------|--------------|--------------|--------------|-------------------------|--|
| TSC_M2 | TSC_M1 | TSC_M0 | TSX1 | TSX2 | TSY1 | TSY2 | | |
| 1 | 1 | 0 | A/D TGATE | A/D TGATE | A/D TGATE | A/D TGATE | A/D | ADC used as stand alone ADC using its analog inputs |
| 1 | 1 | 1 | OPEN | OPEN | OPEN | OPEN | Disabled (no interrupt) | None |

If the Touch screen multiplexer is set to disabled mode [111], touch to the screen will not be detected. Standby mode is entered by setting TSC_M[2:0] to 101. When there is a touch, the controller will detect a change in voltage at the TSX1 point and after a 8ms deglitch the $\overline{\text{INT}}$ pin will be asserted if the interrupt is unmasked in register INT. Once the host detects the interrupt signal, will enable the ADC converter and set the TSC_M<2:0> via the I²C bus to select any of five measurements (position, pressure, plate) as shown in [Table 3](#).

Table 3. TSC Equations

| MEASUREMENT | CHANNEL | EQUATION |
|--------------------|---------|---|
| X Plate resistance | AD_IN14 | $R_x = V_{TSREF} / [(V_{ADC} / 22k) \times 150]$ |
| Y plate resistance | AD_IN14 | $R_y = V_{TSREF} / [(V_{ADC} / 22k) \times 150]$ |
| X position | AD_IN14 | $X_{pos} = R_{x2} / (R_{x1} + R_{x2}) = R_{x2} / R_x$ $R_{x2} = V_{ADC} \times R_x / V_{TSREF}; R_{x1} = R_x - R_{x2}$ $X_{pos} = ADRESULT / 1024$ |
| Y position | AD_IN14 | $Y_{pos} = R_{y2} / (R_{y1} + R_{y2}) = R_{y2} / R_y$ $R_{y2} = V_{ADC} \times R_y / V_{TSREF}; R_{y1} = R_y - R_{y2}$ $Y_{pos} = ADRESULT / 1024$ |
| Pressure | AD_IN14 | $R_c = R - R_{x1} // R_{x2} - R_{y1} // R_{y2}$ $R = V_{TSREF} / [(V_{ADC} / 22k) \times 150]$ $R_{x1} // R_{x2} = R_x \times X_{pos} \times (1 - X_{pos})$ $R_{y1} // R_{y2} = R_y \times Y_{pos} \times (1 - Y_{pos})$ |

Performing Measurements Using the Touch Screen Controller

In order to take measurements with the touch screen controller, the ADC has to be enabled and configured for use with the touch screen controller (TSC) first. In case the TSC is planned to be operated interrupt driven, the TSC needs to be in *TSC standby* mode per default. Only in *TSC standby* mode an interrupt is generated based on a *touch* of the screen. The TSC should therefore be in this mode until a *touch* is detected. Afterwards, the TSC has to be configured for x-position measurement followed by y-position measurement. Now, the TSC can be set to *TSC standby* again to wait for the next *touch* of the screen. For a non-interrupt driven sequence, see TSCMODE. Register Address: 08h (page 50) in the *Registers* section. A typical interrupt driven sequence is given below:

- Set TSCMODE to 101 to set TSC to *TSC standby*, so an interrupt is generated when the screen is touched
- Set Bit AD enable = 1 to provide power to the ADC
- Set input select for the ADC in register ADCONFIG to 1110 (AD_IN14 selected)
- In register INT, set MASK TSC = 1 to unmask the interrupt on a *touch* of the touch screen
- Read Bit TSC INT as it will be set after the TSC has been configured. Reading clears the interrupt.
- After a *touch* was detected, an interrupt is generated by \overline{INT} pin going LOW
- Read Bit TSC INT to clear the interrupt
- Set TSCMODE to 000 to select *x-position measurement*
- Start an ADC conversion by setting CONVERSION START = 1; wait until END OF CONVERSION = 1
- Read register ADRESULT_1 and AD_RESULT_2
- Set TSCMODE to 001 to select *y-position measurement*
- Start an ADC conversion by setting CONVERSION START = 1; wait until END OF CONVERSION = 1
- Read register ADRESULT_1 and AD_RESULT_2
- Set TSCMODE to 101 to set TSC to *TSC standby* again

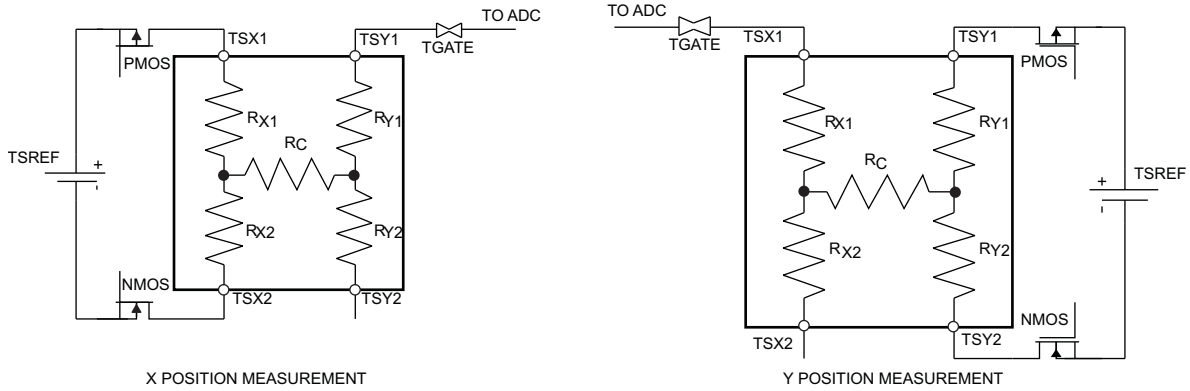


Figure 35. Two Position Measurement

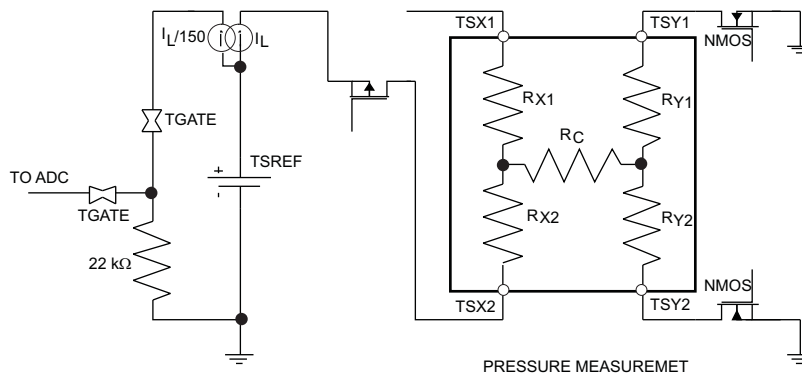


Figure 36. Pressure Measurement

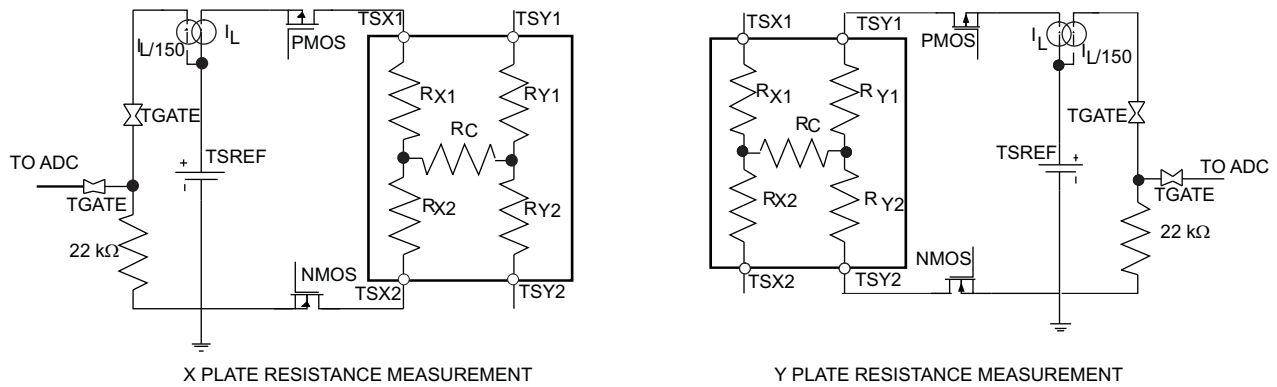


Figure 37. Two Plate Resistance Measurement

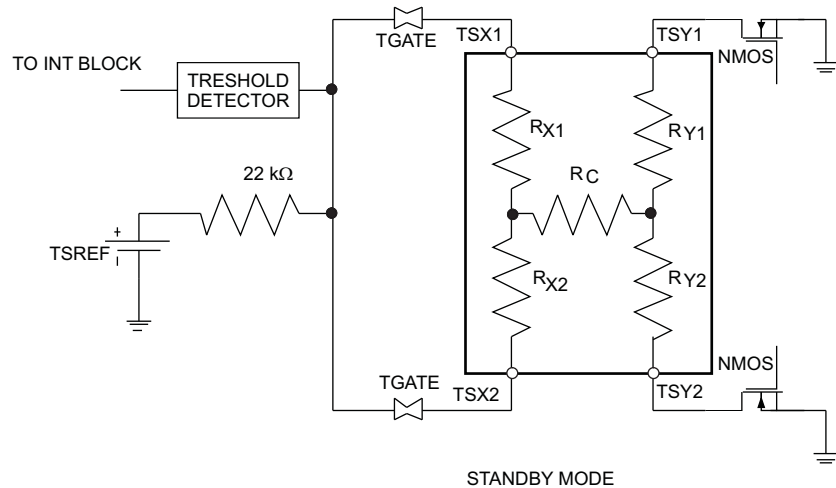


Figure 38. Touch Screen Standby Mode

I2C Interface Specification:

Serial interface

The serial interface is compatible with the standard and fast mode I²C specifications, allowing transfers at up to 400kHz. The interface adds flexibility to the power supply solution, enabling most functions to be programmed to new values depending on the instantaneous application requirements and charger status to be monitored. The has a 7-Bit address: '1001000', other addresses are available upon contact with the factory. Attempting to read data from register addresses not listed in this section will result in 00h being read out. For normal data transfer, SDAT is allowed to change only when SCLK is low. Changes when SCLK is high are reserved for indicating the start and stop conditions. During data transfer, the data line must remain stable whenever the clock line is high. There is one clock pulse per Bit of data. Each data transfer is initiated with a start condition and terminated with a stop condition. When addressed, the device generates an acknowledge Bit after the reception of each byte. The master device (microprocessor) must generate an extra clock pulse that is associated with the acknowledge Bit. The device must pull down the SDAT line during the acknowledge clock pulse so that the SDAT line is a stable low during the high period of the acknowledge clock pulse. The SDAT line is a stable low during the high period of the acknowledge-related clock pulse. Setup and hold times must be taken into account. During read operations, a master must signal the end of data to the slave by not generating an acknowledge Bit on the last byte that was clocked out of the slave. In this case, the slave device must leave the data line high to enable the master to generate the stop condition.

All registers are set to their default value by one of these conditions:

- Voltage is below the UVLO threshold defined with registers <UVLO1>, <UVLO0>
- PB_IN is asserted LOW for >15s (option)

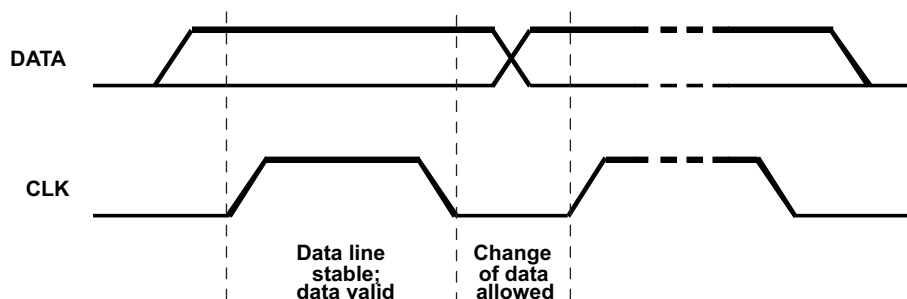


Figure 39. Bit Transfer on the Serial Interface

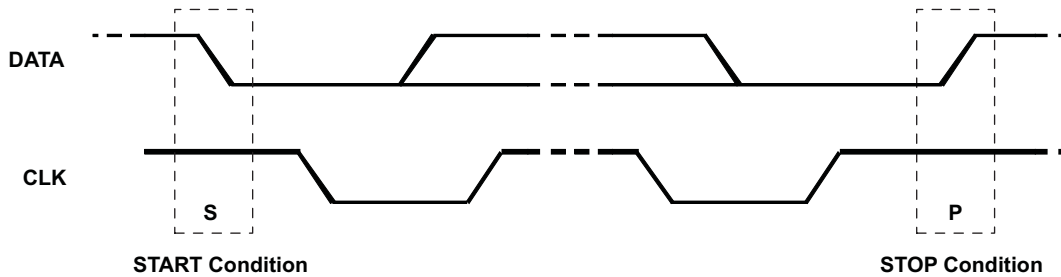
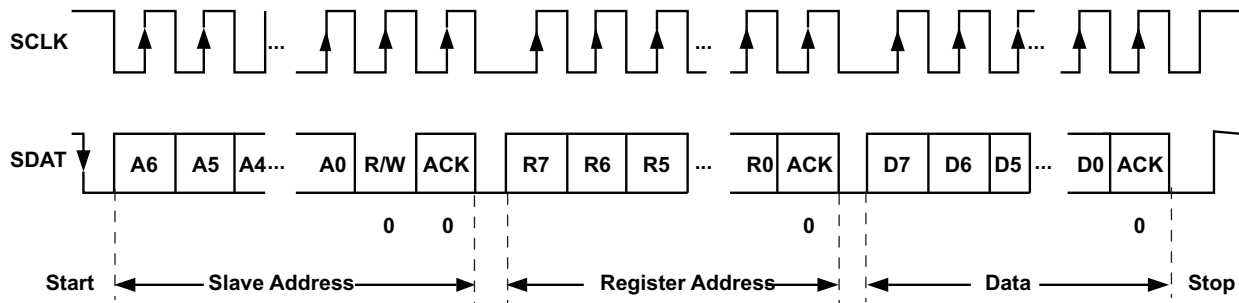
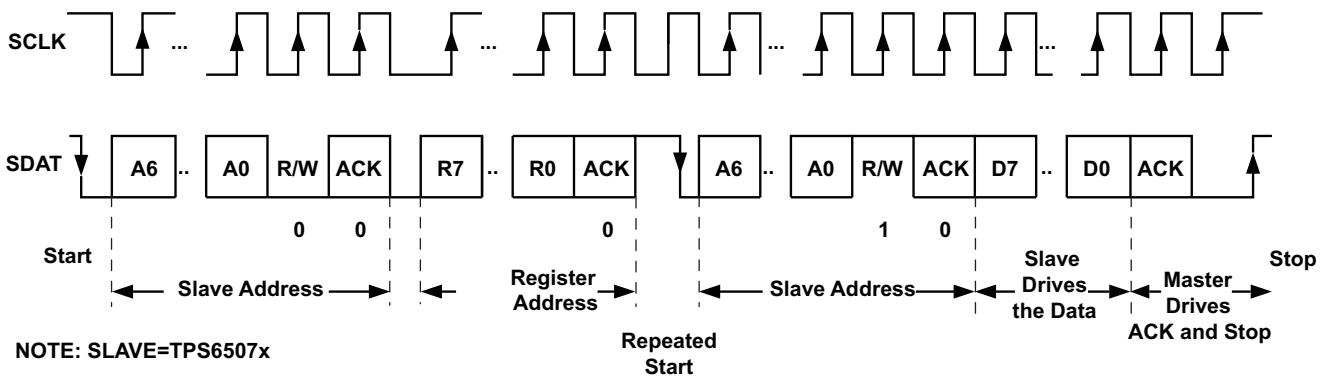


Figure 40. START and STOP Conditions



NOTE: SLAVE=TPS6507x

Figure 41. Serial I/f WRITE to TPS6507x



NOTE: SLAVE=TPS6507x

Figure 42. Serial I/f READ from TPS6507x: Protocol A

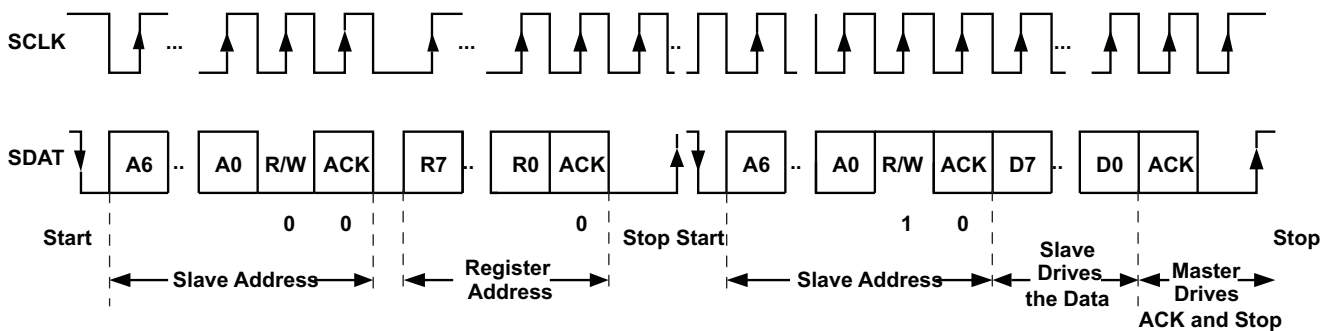
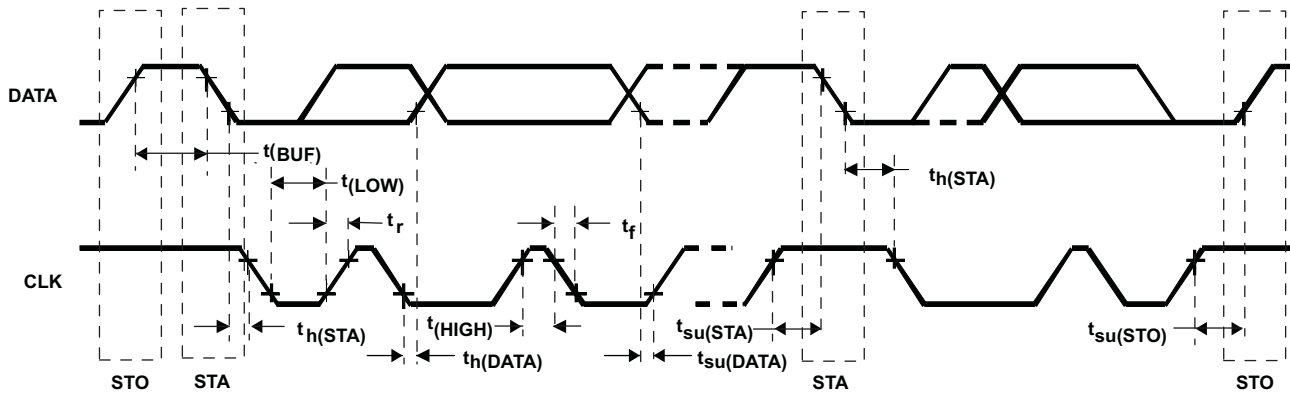


Figure 43. Serial I/f READ from TPS6507x: Protocol B


Figure 44. Serial I/f Timing Diagram

| | | MIN | MAX | UNIT |
|----------------|---|------|-----|------|
| f_{MAX} | Clock frequency | | 400 | kHz |
| $t_{WH(HIGH)}$ | Clock high time | 600 | | ns |
| $t_{WL(LOW)}$ | Clock low time | 1300 | | ns |
| t_R | SDAT and CLK rise time | | 300 | ns |
| t_F | SDAT and CLK fall time | | 300 | ns |
| $t_{h(STA)}$ | Hold time (repeated) START condition (after this period the first clock pulse is generated) | 600 | | ns |
| $t_{h(SDAT)}$ | Setup time for repeated START condition | 600 | | ns |
| $t_{h(SDAT)}$ | Data input hold time | 0 | | ns |
| $t_{su(SDAT)}$ | Data input setup time | 100 | | ns |
| $t_{su(STO)}$ | STOP condition setup time | 600 | | ns |
| $t_{(BUF)}$ | Bus free time | 1300 | | ns |

REGISTERS
PPATH1. Register Address: 01h

| PPATH1 | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
|--------------------------|-----------|----------|--------------------------------------|-------------------------------------|-------------------------------|-------------------------------|--------------------------------|--------------------------------|
| Bit name and function | USB power | AC power | $\overline{\text{USB}}$ power enable | $\overline{\text{AC}}$ power enable | AC input current MSB | AC input current LSB | USB input current MSB | USB input current LSB |
| Default | x | x | 0 | 0 | 1 | 1 | 0 | 1 |
| Set by signal | | | | | | | | |
| Default value loaded by: | | | UVLO | UVLO | Voltage removed at AC OR UVLO | Voltage removed at AC OR UVLO | Voltage removed at USB OR UVLO | Voltage removed at USB OR UVLO |
| Read/write | R | R | R/W | R/W | R/W | R/W | R/W | R/W |

- Bit 7 USB power:
 0 = USB power is not present and/or not in the range valid for charging
 1 = USB source is present and in the range valid for charging. B7 remains active as long as the charge source is present
- Bit 6 AC power:
 0 = wall plug is not present and/or not in the range valid for charging
 1 = wall plug source is present and in the range valid for charging. B6 remains active as long as the charge source is present
- Bit 5 $\overline{\text{USB}}$ POWER ENABLE
 0 = USB power input is enabled
 1 = USB power input is disabled (USB suspend mode)
- Bit 4 $\overline{\text{AC}}$ POWER ENABLE
 0 = AC power input is enabled
 1 = AC power input is disabled
- Bit 3..2 AC INPUT CURRENT
 00 = input current from AC input is 100 mA max
 01 = input current from AC input is 500 mA max
 10 = input current from AC input is 1300 mA max
 11 = input current from AC input is 2500 mA
- Bit 1..0 USB INPUT CURRENT
 00 = input current from USB input is 100 mA max
 01 = input current from USB input is 500 mA max
 10 = input current from USB input is 800 mA max
 11 = input current from USB input is 1300 mA max

Note: safety timers are cleared if the input voltage at both AC and USB are removed.

INT. Register Address: 02h

| INT | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
|--------------------------|-------------|----------|------------|----|-------------------|-------------------|---------------------------------|---------------------------------|
| Bit name and function | MASK AC/USB | MASK TSC | MASK PB_IN | | TSC INT | PB_IN INT | USB or AC input voltage applied | USB or AC input voltage removed |
| Default | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| Set by signal | | | | | Cleared when read | Cleared when read | Cleared when read | Cleared when read |
| Default value loaded by: | UVLO | UVLO | UVLO | | UVLO | UVLO | UVLO | UVLO |
| Read/write | R/W | R/W | R/W | R | R | R | R | R |

Bit 7 MASK AC/USB

0 = no interrupt generated if voltage at AC or USB is applied or removed

1 = the pin INT is actively pulled low if one of the Bits 1 to Bit 0 are 1

Bit 6 MASK TSC

0 = no interrupt generated if the touch screen is detecting a “touch”

1 = the pin INT is actively pulled low if a “touch” on the touch screen is detected

Bit 5 MASK PB_IN

0 = no interrupt generated if the PB_IN is pulled low.

1 = the pin INT is actively pulled low if PB_IN was pulled low.

Bit 3 TSC INT

0 = no “touch” on the touch screen detected

1 = “touch” detected and the Bit has not been read ever since

Bit 2 PB_IN INT

0 = PB_IN not active

1 = PB_IN is actively pulled low (or high optionally) and the Bit has not been read ever since

Bit 1 USB or AC INPUT VOLTAGE APPLIED

0 = no change (voltage still applied or never applied)

1 = voltage at USB or AC has been applied and the Bit has not been read ever since

Bit 0 USB or AC INPUT VOLTAGE REMOVED

0 = no change (voltage still applied or never applied)

1 = the voltage at USB or AC has been removed and the Bit has not been read ever since

CHGCONFIG0. Register Address: 03h

| CHGCONFIG0 | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
|--------------------------|--------------------|-------------|-----------------|--------------|----|-------------|----------------|---------------|
| Bit name and function | Thermal regulation | DPPM active | Thermal Suspend | Term Current | | Chg Timeout | Prechg Timeout | BatTemp error |
| Default | x | x | x | x | 0 | x | x | x |
| Set by signal | | | | | | | | |
| Default value loaded by: | UVLO | UVLO | UVLO | UVLO | | UVLO | UVLO | UVLO |
| Read/write | R | R | R | R | R | R | R | R |

- Bit 7 THERMAL REGULATION:
 0 = charger is in normal operation
 1 = charge current is reduced due to high chip temperature
- Bit 6 DPPM ACTIVE:
 0 = DPPM loop is not active
 1 = DPPM loop is active; charge current is reduced to support the load with the current required
- Bit 5 THERMAL SUSPEND:
 0 = charging is allowed
 1 = charging is momentarily suspended because battery temperature is out of range
- Bit 4 TERM CURRENT:
 0 = charge termination current threshold has not been crossed; charging or no voltage at AC and USB
 1 = charge termination current threshold has been crossed and charging has been stopped. This can be due to a battery reaching full capacity or to a battery removal condition
- Bit 2..Bit1 CHG TIMEOUT, PRECHG TIMEOUT
 0 = charging, timers did not time out
 1 = one of the timers has timed out and charging has been terminated
- Bit 0 BAT TEMP ERROR:
 0 = battery temperature is in the allowed range for charging
 1 = no temperature sensor detected

CHGCONFIG1. Register Address: 04h

| CHGCONFIG1 | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
|--------------------------|----------------------------|----------------------------|---------------------|-------------|---------------|---------------------------|----------------|----------------|
| Bit name and function | Charge safety timer value1 | Charge safety timer value0 | Safety timer enable | SENSOR TYPE | Charger reset | Charge Termination ON/OFF | Suspend Charge | Charger enable |
| Default | 0 | 0 | 1 | 1 | 0 | 0 | 0 | 1 |
| Set by signal | | | | | | | | |
| Default value loaded by: | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO |
| Read/write | R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

Bit 7..6 CHARGE SAFETY TIMER VALUE0/1:

00 = safety timer times out after 4 hours

01 = safety timer times out after 5 hours

10 = safety timer times out after 6 hours

11 = safety timer times out after 8 hours

Bit 5 SAFETY TIMER ENABLE

0 = pre-charge timer, fast charge timer and taper timers are disabled

1 = pre-charge timer, fast charge timer and taper timers are enabled

Bit 4 SENSOR TYPE (NTC for battery temperature measurement)

0 = 100k curve 1 NTC

1 = 10k curve 2 NTC

Bit 3 CHARGER RESET:

0 = inactive

1 = Reset active. This Bit must be set and then reset via the serial interface to restart the charge algorithm

Bit 2 CHARGE TERMINATION ON/OFF:

0 = charge termination enabled, based on timers and termination current

1 = charge termination will not occur and the charger will always be on

Bit 1 SUSPEND CHARGE:

0 = Safety Timer and Pre-Charge timers are not suspended

1 = Safety Timer and Pre-Charge timers are suspended

Bit 0 CHARGER ENABLE

0 = charger is disabled

1 = charger is enabled; toggling the enable Bit will not reset the charger. Use CHARGER RESET Bit to reset charger.

CHGCONFIG2. Register Address: 05h

| CHGCONFIG2 | B7 | B6 | B5 | B4 | B3 | B2 | B1 | BO |
|--------------------------|------------------------|-------------------|---------------------------|---------------------------|----|----|----|----|
| Bit name and function | Dynamic Timer function | Precharge voltage | Charge voltage selection1 | Charge voltage selection0 | | | | |
| Default | 1 | 1 | 1 | 0 | 0 | 0 | 0 | 0 |
| Set by signal | | | | | | | | |
| Default value loaded by: | UVLO | UVLO | UVLO | UVLO | | | | |
| Read/write | R/W | R/W | R/W | R/W | R | R | R | R |

Bit 7 DYNAMIC TIMER FUNCTION

0 = safety timers run with their nominal clock speed

1 = clock speed is divided by 2 if thermal loop or DPPM loop is active

Bit 6 PRECHARGE VOLTAGE

0 = pre-charge to fast charge transition voltage is 2.5V

1 = pre-charge to fast charge transition voltage is 2.9V

Bit 5..4 CHARGE VOLTAGE SELECTION0/1:

00 = 4.10V

01 = 4.15V

10 = 4.20V

11 = 4.25V

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CHGCONFIG3. Register Address: 06h

| CHGCONFIG3 | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
|--------------------------|---------------------|----------------------------|----------------------------|----------------|-----------------------------|-----------------------------|----------------|----------------------|
| Bit name and function | Disable Isink at AC | Power path DPPM threshold1 | Power path DPPM threshold0 | Precharge time | Termination current factor1 | Termination current factor0 | Charger active | Disable Isink at USB |
| Default | 0 | 1 | 1 | 0 | 0 | 1 | x | 0 |
| Set by signal | | | | | | | | |
| Default value loaded by: | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO |
| Read/write | R/W | R/W | R/W | R/W | R/W | R/W | R | R/W |

Bit 7 **DISABLE ISINK AT AC** (disables an internal current sink from pin AC to GND)

0 = 60 μ A current sink enabled when no input voltage at pin AC detected

1 = 60 μ A current sink disabled

Bit 6..5 **POWER PATH DPPM THRESHOLD1/0:**

00 = 3.5 V

01 = 3.75 V

10 = 4.25 V

11 = 4.50 V

Bit 4 **PRECHARGE TIME**

0 = pre-charge time is 30 min

1 = pre-charge time is 60 min

Bit 3..2 **TERMINATION CURRENT FACTOR1/0:**

00 = 0.04

01 = 0.1

10 = 0.15

11 = 0.2

Bit 1 **CHARGER ACTIVE:**

0 = charger is not charging

1 = charger is charging (DPPM or thermal regulation may be active)

Bit 0 **DISABLE ISINK AT USB** (disables an internal current sink from pin USB to GND)

0 = 60 μ A current sink enabled when no input voltage at pin USB detected

1 = 60 μ A current sink disabled

Note: There is a current sink on pins AC and USB which is activated when there is no voltage detected at the pin and Bit7 or Bit0 in CHCONFIG3 are set to 0. This is implemented in order to avoid the pins to be floating when not connected to a power source. The current sink is disabled automatically as soon as an input voltage is detected at the pin.

ADCONFIG. Register Address: 07h

| ADCONFIG | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
|--------------------------|-----------|------------------|-------------------|-------------|----------------|----------------|----------------|----------------|
| Bit name and function | AD enable | Conversion start | End of conversion | Vref enable | INPUT SELECT_3 | INPUT SELECT_2 | INPUT SELECT_1 | INPUT SELECT_0 |
| Default | 0 | 0 | 1 | 0 | 0 | 0 | 0 | 0 |
| Set by signal | | | | | | | | |
| Default value loaded by: | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO |
| Read/write | R/W | R/W | R | R/W | R/W | R/W | R/W | R/W |

Bit 7 AD ENABLE:

0 = A/D converter disabled
1 = A/D converter enabled

Bit 6 CONVERSION START

0 = no conversion in progress
1 = start A/D conversion, Bit is automatically cleared if conversion is done

Bit 5 END OF CONVERSION

0 = conversion did not finish
1 = conversion done

Bit 4 VREF ENABLE

0 = reference voltage LDO (pin BYPASS) for ADC is disabled
1 = reference voltage LDO (pin BYPASS) for ADC is enabled

Bit 3..0 INPUT SELECT – see table

| INPUT SELECT_3 | INPUT SELECT_2 | INPUT SELECT_1 | INPUT SELECT_0 | FULL SCALE INPUT VOLTAGE | INPUT SELECTED |
|----------------|----------------|----------------|----------------|--------------------------|---|
| 0 | 0 | 0 | 0 | 2.25V | Voltage at AD_IN1 |
| 0 | 0 | 0 | 1 | 2.25V | Voltage at AD_IN2 |
| 0 | 0 | 1 | 0 | 2.25V | Voltage at AD_IN3 |
| 0 | 0 | 1 | 1 | 2.25V | Voltage at AD_IN4 |
| 0 | 1 | 0 | 0 | 2.25V | Voltage at TS pin |
| 0 | 1 | 0 | 1 | 2.25V | Voltage at ISET pin == battery charge current |
| 0 | 1 | 1 | 0 | 6.0V | Voltage at AC pin |
| 0 | 1 | 1 | 1 | 6.0V | Voltage at SYS pin |
| 1 | 0 | 0 | 0 | 6.0V | Input voltage of the charger |
| 1 | 0 | 0 | 1 | 6.0V | Voltage at BAT pins |
| 1 | 0 | 1 | 0 | 6.0V | Voltage at AD_IN5 (at pin THRESHOLD) |
| 1 | 0 | 1 | 1 | 6.0V | Voltage at AD_IN6 (at pin ISET1) |
| 1 | 1 | 0 | 0 | 6.0V | Voltage at AD_IN7 (at pin ISET2) |
| 1 | 1 | 1 | 0 | 2.25 | Touch screen controller (TSC); all functions |
| 1 | 1 | 1 | 1 | 2.25 | Touch screen controller (TSC); x-position and y-position only |

TSCMODE. Register Address: 08h

| TSCMODE | B7 | B6 | B5 | B4 | B3 | B2 | B1 | BO |
|--------------------------|----|----|----|----|----|--------|--------|--------|
| Bit name and function | | | | | | TSC_M2 | TSC_M1 | TSC_M0 |
| Default | 0 | 0 | 0 | 0 | 0 | 1 | 1 | 1 |
| Set by signal | | | | | | | | |
| Default value loaded by: | | | | | | UVLO | UVLO | UVLO |
| Read/write | R | R | R | R | R | R/W | R/W | R/W |

Bit 3..0 MODE SELECT BITS FOR THE TOUCH SCREEN INTERFACE

Note: Data conversions using the touch screen interface require setting the touch screen mode with register TSCMODE and selecting the analog input channel for the ADC according to the following table.

Measurement of x-position:

- Set TSCMODE to 000 to select x-position measurement
- Set Bit AD_ENABLE=1 to provide power to the ADC.
- Set input select for the ADC in register AD_CONFIG to 1110 (AD_IN14 selected).
- Start a conversion by setting CONVERSION_START=1; wait until END_OF_CONVERSION=1
- Read register ADRESULT_1 and ADRESULT_2

| TSC_M2 | TSC_M1 | TSC_M0 | TSX1 (AD_IN1) | TSX2 (AD_IN2) | TSY1(AD_ IN3) | TSY2(AD_ IN4) | MODE | MEASUREMENT |
|--------|--------|--------|------------------|------------------|------------------|------------------|--|---------------------------------|
| 0 | 0 | 0 | TSREF | GND | A/D | HiZ | X-Position | Voltage TSY1 |
| 0 | 0 | 1 | A/D | HiZ | TSREF | GND | Y-Position | Voltage TSX1 |
| 0 | 1 | 0 | TSREF | TSREF | GND | GND | Pressure | Current TSX1 and TSX2 |
| 0 | 1 | 1 | TSREF | GND | HiZ | HiZ | Plate X | Current TSX1 |
| 1 | 0 | 0 | HiZ | HiZ | TSREF | GND | Plate Y | Current TSY1 |
| 1 | 0 | 1 | V2 | V2 | GND | GND | TSC standby | Voltage TSX1 and TSX2 |
| 1 | 1 | 0 | A/D | A/D | A/D | A/D | A/D | Voltage measurement with ADC |
| 1 | 1 | 1 | open | open | open | open | TSC and ADC disabled (no interrupt generation) | |

ADRESULT_1. Register Address: 09h

| ADRESULT_1 | B7 | B6 | B5 | B4 | B3 | B2 | B1 | BO |
|--------------------------|---------|---------|---------|---------|---------|---------|---------|-------------|
| Bit name and function | AD_BIT7 | AD_BIT6 | AD_BIT5 | AD_BIT4 | AD_BIT3 | AD_BIT2 | AD_BIT1 | AD_BIT0 LSB |
| Default | x | x | x | x | x | x | x | x |
| Set by signal | | | | | | | | |
| Default value loaded by: | R | R | R | R | R | R | R | R |
| Read/write | | | | | | | | |

ADRESULT_2. Register Address: 0Ah

| ADRESULT_2 | B7 | B6 | B5 | B4 | B3 | B2 | B1 | BO |
|--------------------------|----|----|----|----|----|----|----------------|---------|
| Bit name and function | | | | | | | AD_BIT9 MSB | AD_BIT8 |
| Default | 0 | 0 | 0 | 0 | 0 | 0 | x | x |
| Set by signal | | | | | | | | |
| Default value loaded by: | R | R | R | R | R | R | R | R |
| Read/write | | | | | | | | |

PGOOD. Register Address: 0Bh

| PGOOD | B7 | B6 | B5 | B4 | B3 | B2 | B1 | BO |
|-------------------------------------|---------------------------|------------------|------------------|-----------------|-----------------|-----------------|---------------|---------------|
| Bit name and function | $\overline{\text{Reset}}$ | PGOOD DELAY 1 | PGOOD DELAY 0 | PGOOD VDCDC1 | PGOOD VDCDC2 | PGOOD VDCDC3 | PGOOD LDO1 | PGOOD LDO2 |
| Default for -70, -73, -731, -732 | x | 1 | 1 | | | | | |
| Default for TPS65072 | x | 0 | 0 | | | | | |
| Set by signal | | | | PGOOD VDCDC1 | PGOOD VDCDC2 | PGOOD VDCDC3 | PGOOD LDO1 | PGOOD LDO2 |
| Default value loaded by: | | | | PGOOD VDCDC1 | PGOOD VDCDC2 | PGOOD VDCDC3 | PGOOD LDO1 | PGOOD LDO2 |
| Read/write | R | R/W | R/W | R | R | R | R | R |

Bit 7 $\overline{\text{Reset}}$:

- 0 = indicates that the comparator input voltage is above the 1V threshold.
- 1 = indicates that the comparator input voltage is below the 1V threshold.

Bit 6..5 PGOOD DELAY 0,1 (sets the delay time of $\overline{\text{Reset}}$ and PGOOD output):

- 00 = delay is 20ms
- 01 = delay is 100ms
- 10 = delay is 200ms
- 11 = delay is 400ms

Bit 4 PGOOD VDCDC1:

- 0 = indicates that the VDCDC1 converter output voltage is below its target regulation voltage or disabled.
- 1 = indicates that the VDCDC1 converter output voltage is within its nominal range.

Bit 3 PGOOD VDCDC2:

- 0 = indicates that the VDCDC2 converter output voltage is below its target regulation voltage or disabled.
- 1 = indicates that the VDCDC2 converter output voltage is within its nominal range.

Bit 2 PGOOD VDCDC3:

- 0 = indicates that the VDCDC3 converter output voltage is below its target regulation voltage or disabled
- 1 = indicates that the VDCDC3 converter output voltage is within its nominal range.

Bit 1 PGOOD LDO1:

- 0 = indicates that LDO1 output voltage is below its target regulation voltage or disabled
- 1 = indicates that the LDO1 output voltage is within its nominal range.

Bit 0 PGOOD LDO2:

- 0 = indicates that the LDO2 output voltage is below its target regulation voltage or disabled.
- 1 = indicates that the LDO2 output voltage is within its nominal range.

PGOODMASK. Register Address: 0Ch

| | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
|--------------------------------|----|----|----------------------------|----------------|----------------|----------------|----------|--------------|
| Bit name and function | | | MASK VDCDC3 and LDO1 | MASK VDCDC1 | MASK VDCDC2 | MASK VDCDC3 | MASKLDO1 | MASK LDO2 |
| Default for -70 | 0 | 0 | 0 | 0 | 1 | 0 | 0 | 0 |
| Default for -72 | 0 | 0 | 0 | 1 | 0 | 0 | 0 | 0 |
| Default for -73, -731, -732 | 0 | 0 | 0 | 1 | 1 | 1 | 0 | 0 |
| Set by signal | | | | | | | | |
| Default value loaded by: | | | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO |
| Read/write | R | R | R/W | R/W | R/W | R/W | R/W | R/W |

Bit 5 MASK VDCDC3 and LDO1:

0 = indicates that the output voltage of either DCDC3 or LDO1 is within its nominal range. The PGOOD output is not affected (not driven LOW)

1 = indicates that both LDO1 AND DCDC3 output voltage is below its target regulation voltage or disabled. This will drive the PGOOD output low.

Bit 4..0 MASK VDCDC1/2/3, LDO1,2:

0 = the status of the power good Bit in Register $\overline{\text{PGOOD}}$ does not affect the status of the PGOOD output pin

1 = the PGOOD pin is driven low in case the output voltage of the converter or LDO is below its target regulation voltage or disabled.

CON_CTRL1. Register Address: 0Dh

| CON_CTRL1 | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
|---|-----------------------------|-----------------------------|-----------------------------|-----------------|-----------------|-----------------|----------------|----------------|
| Bit name and function | DCDC_SQ2 | DCDC_SQ1 | DCDC_SQ0 | DCDC1 ENABLE | DCDC2 ENABLE | DCDC3 ENABLE | LDO1 ENABLE | LDO2 ENABLE |
| Default for –70, –72, –73, –732 for TPS65731 only | See Table 9 | See Table 9 | See Table 9 | 1 1 | 1 1 | 1 1 | 1 1 | 1 0 |
| Set by signal | | | | DCDC1_E NZ | DCDC2_EN Z | DCDC3_EN Z | LDO_ENZ | LDO_ENZ |
| Default value loaded by: | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO |
| Read/write | R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

The CON_CTRL1 register can be used to disable and enable all power supplies via the serial interface. Default is to allow all supplies to be on, providing the relevant enable pin is high. The following tables indicate how the enable pins and the CON_CTRL1 register are combined. The CON_CTRL1 Bits are automatically reset to default when the corresponding enable pin is low.

Bit 7..5 DCDC_SQ2 to DCDC_SQ0: power-up sequencing (power down sequencing is the reverse)

000 = power-up sequencing is: DCDC2 only; DCDC1 and DCDC3 are not part of the automatic sequencing and are enabled by their enable pins EN_DCDC1 and EN_DCDC3

001 = power-up sequencing is DCDC2 and DCDC3 at the same time, DCDC1 is not part of the automatic sequencing and is enabled by its enable pin EN_DCDC1

010 = power-up sequencing is: DCDC1 when power good then DCDC2 and DCDC3 at the same time

011 = power-up sequencing is: DCDC3 when power good then DCDC2; DCDC1 is not part of the automatic sequencing and is controlled by its EN_DCDC1 pin.

100 = power-up sequencing is: DCDC3 is started at the same time with LDO2 if Bit MASK_EN_DCDC3 in register 0Eh is set (default is set). DCDC1 and DCDC2 are started at the same time when LDO2 is PGOOD (defined in LDO sequencing 111); DCDC3 is enabled or disabled with its EN_DCDC3 pin if MASK_EN_DCDC3 in register 0Eh is cleared (set =0). (Sirf PRIMA, start-up from OFF or start-up after SLEEP)

101 = DCDC converters are enabled individually with the external enable pins

110 = DCDC1first, when power good then DCDC2, when power good then DCDC3

111 = power-up sequencing is: DCDC1 and DCDC2 at the same time >1ms after LDO2 has been started (defined in LDO sequencing 010); DCDC3 is not part of the automatic sequencing but is enabled with its EN_DCDC3 pin (Atlas4)

In case of automatic sequencing other than 101, the start is initiated by going into ON-state. DCDC converters that are not part of the automatic sequencing can be enabled by pulling their enable pin to a logic HIGH level at any time in ON-state. The enable pins for the converters that are automatically enabled, should be tied to GND. For sequencing option DCDC_SEQ=111, the start is initiated by going into ON-state, however, the external LDO connected to pin EN_EXTLDO is powered first, followed by LDO2.

(The sequencing of LDO1 and LDO2 is defined in register LDO_CTRL1)

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Bit 4..0 DCDC1,2,3: See tables below

| EN_DCDC1 PIN | CON_CTRL1<4> | DCDC1 CONVERTER | | EN_DCDC2 PIN | CON_CTRL1<3> | DCDC2 CONVERTER |
|--------------|--------------|-----------------|--|--------------|--------------|-----------------|
| 0 | x | disabled | | 0 | x | disabled |
| 1 | 0 | disabled | | 1 | 0 | disabled |
| 1 | 1 | enabled | | 1 | 1 | enabled |

| EN_DCDC3 PIN | CON_CTRL1<2> | DCDC3 CONVERTER |
|--------------|--------------|-----------------|
| 0 | x | disabled |
| 1 | 0 | disabled |
| 1 | 1 | enabled |

CON_CTRL2. Register Address: 0Eh

| CON_CTRL2 | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
|-----------------------------|--------------------|--------------------|--------|--------|---------------|--------------------|---------|---------|
| Bit name and function | ENABLE 1s timer | ENABLE 5s timer | DS_RDY | PWR_DS | MASK_EN_DCDC3 | UVLO hysteresis | UVLO1 | UVLO0 |
| Default value loaded by: | UVLO | UVLO | UVLO | UVLO | UVLO | BG_GOOD | BG_GOOD | BG_GOOD |
| Read/write | R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

Bit 7...6 ENABLE TIMERS:

0 = the state machine timers of 1s and 5s, respectively are disabled
 1 = the state machine timers of 1s and 5s, respectively are enabled

Bit 5 DS_RDY (data ready, memory content valid) for use with Sirf Prima processor DEEP SLEEP mode:

0 = status Bit which is indicating the memory content is not valid after wake up from DEEP SLEEP. This Bit is set / cleared by the Prima application processor. Cleared when device is in UVLO to tell processor there was a power loss. The Bits needs to be cleared by user software after a wake up from DEEP SLEEP to enable the DCDC2 converter to be powered down in shutdown sequencing depending on the status of LDO2.

1 = memory content is valid after wake up from DEEP SLEEP (set by I2C command by application processor only). The Prima processor is ready to power down to DEEP SLEEP mode or was just waking up from DEEP SLEEP mode.

Bit 4 PWR_DS (enter DEEP SLEEP for sequencing option DCDC_SEQ=100, LDO_SEQ=111):

0 = PMU is in normal operation

1 = PMU powers down all rails except DCDC2 and the external LDO on pin "EXT_LDO". PGOOD is pulled LOW.

Bit 3 MASK_EN_DCDC3; used for Prima application processor start-up sequencing:

0 = DCDC3 is enabled or disabled by the status of EN_DCDC3 for sequencing option DCDC_SEQ=100.

1 = DCDC3 will start at the same time with LDO2 for sequencing option DCDC_SEQ=100. The status of EN_DCDC3 is ignored

Bit 2 UNDERVOLTAGE LOCKOUT HYSTERESIS:

0 = 400mV hysteresis

1 = 500mV hysteresis

Bit 1..0 UVLO1, UVLO2 (undervoltage lockout voltage):

00 = the device turns off at 2.8V with the reverse of the sequencing defined in CON_CTRL1

01 = the device turns off at 3.0V with the reverse of the sequencing defined in CON_CTRL1

10 = the device turns off at 3.1V with the reverse of the sequencing defined in CON_CTRL1

11 = the device turns off at 3.25V with the reverse of the sequencing defined in CON_CTRL1

Note: The undervoltage lockout voltage is sensed at the SYS pin and the device goes to OFF state when the voltage is below the value defined in the register. BG_GOOD is the internal bandgap good signal which occurs at lower voltages than UVLO.

CON_CTRL3. Register Address: 0Fh

| CON_CTRL3 | B7 | B6 | B5 | B4 | B3 | B2 | B1 | BO |
|--------------------------|---------------|---------------|---------------|--------------------|--------------------|--------------------|-------------------|-------------------|
| Bit name and function | FPWM DCDC3 | FPWM DCDC2 | FPWM DCDC1 | DCDC1 discharge | DCDC2 discharge | DCDC3 discharge | LDO1 discharge | LDO2 discharge |
| Default value loaded by: | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO |
| Read/write | R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

- Bit 7 FPWM DCDC3:
0 = DCDC3 converter operates in PWM / PFM mode
1 = DCDC3 converter is forced into fixed frequency PWM mode
- Bit 6 FPWM DCDC2:
0 = DCDC2 converter operates in PWM / PFM mode
1 = DCDC2 converter is forced into fixed frequency PWM mode
- Bit 5 FPWM DCDC1:
0 = DCDC1 converter operates in PWM / PFM mode
1 = DCDC1 converter is forced into fixed frequency PWM mode
- Bit 4–0 0 = the output capacitor of the associated converter or LDO is not actively discharged when the converter or LDO is disabled
1 = the output capacitor of the associated converter or LDO is actively discharged when the converter or LDO is disabled. This decreases the fall time of the output voltage at light load

DEFDCDC1. Register Address: 10h

| DEFDCDC1 | B7 | B6 | B5 | B4 | B3 | B2 | B1 | BO |
|--------------------------|-----------------|------|----------|----------|----------|----------|----------|----------|
| Bit name and function | DCDC1 extadj | | DCDC1[5] | DCDC1[4] | DCDC1[3] | DCDC1[2] | DCDC1[1] | DCDC1[0] |
| Default value loaded by: | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO |
| Read/write | R/W | R | R/W | R/W | R/W | R/W | R/W | R/W |

DEFDCDC1 sets the output voltage for the DCDC1 converter. Per default the converter is internally fixed but can be programmed to an externally adjustable version by setting Bit 7 (Ext adj). The default setting is defined in an EEPROM Bit. In case the externally adjustable version is programmed, the external resistor divider need to be connected to the VDCDC1 pin, otherwise this pin needs to be connected to the output voltage directly. For the fixed voltage version, the output voltage is set with Bits B0 to B5 (DCDC1[5] to DCDC1[0]):

All step-down converters provide the same output voltage range, see details under DEFDCDC3

DEFDCDC2_LOW. Register Address: 11h

| DEFDCDC2_LOW | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
|--------------------------|----|----|----------|----------|----------|----------|----------|----------|
| Bit name and function | | | DCDC2[5] | DCDC2[4] | DCDC2[3] | DCDC2[2] | DCDC2[1] | DCDC2[0] |
| Default value loaded by: | | | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO |
| Read/write | R | R | R/W | R/W | R/W | R/W | R/W | R/W |

DEFDCDC2_HIGH. Register Address: 12h

| DEFDCDC2_HIGH | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
|--------------------------|--------------|----|----------|----------|----------|----------|----------|----------|
| Bit name and function | DCDC2 extadj | | DCDC2[5] | DCDC2[4] | DCDC2[3] | DCDC2[2] | DCDC2[1] | DCDC2[0] |
| Default value loaded by: | UVLO | | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO |
| Read/write | R/W | R | R/W | R/W | R/W | R/W | R/W | R/W |

The output voltage for DCDC2 is switched between the value defined in DEFDCDC2_LOW and DEFDCDC2_HIGH depending on the status of the DEFDCDC2 pin. IF DEFDCDC2 is LOW the value in DEFDCDC2_LOW is selected, if DEFDCDC2 = HIGH, the value in DEFDCDC2_HIGH is selected. Per default the converter is internally fixed but can be programmed to an externally adjustable version by EEPROM similar to DCDC1.

DEFDCDC3_LOW. Register Address: 13h

| DEFDCDC3_LOW | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
|--------------------------|-----|----|----------|----------|----------|----------|----------|----------|
| Bit name and function | | | DCDC3[5] | DCDC3[4] | DCDC3[3] | DCDC3[2] | DCDC3[1] | DCDC3[0] |
| Default value loaded by: | | | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO |
| Read/write | R/W | R | R/W | R/W | R/W | R/W | R/W | R/W |

DEFDCDC3_HIGH. Register Address: 14h

| DEFDCDC3_HIGH | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
|--------------------------|--------------|----|----------|----------|----------|----------|----------|----------|
| Bit name and function | DCDC3 extadj | | DCDC3[5] | DCDC3[4] | DCDC3[3] | DCDC3[2] | DCDC3[1] | DCDC3[0] |
| Default value loaded by: | UVLO | | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO |
| Read/write | R/W | R | R/W | R/W | R/W | R/W | R/W | R/W |

The output voltage for DCDC3 is switched between the value defined in DEFDCDC3_LOW and DEFDCDC3_HIGH depending on the status of the DEFDCDC3 pin. IF DEFDCDC3 is LOW the value in DEFDCDC3_LOW is selected, if DEFDCDC3 = HIGH, the value in DEFDCDC3_HIGH is selected. Per default the converter is internally fixed but can be programmed to an externally adjustable version by EEPROM similar to DCDC2.

| OUTPUT VOLTAGE [V] | B5 | B4 | B3 | B2 | B1 | B0 |
|--------------------|----|----|----|----|----|----|
| 0.725 | 0 | 0 | 0 | 0 | 0 | 0 |
| 0.750 | 0 | 0 | 0 | 0 | 0 | 1 |
| 0.775 | 0 | 0 | 0 | 0 | 1 | 0 |
| 0.800 | 0 | 0 | 0 | 0 | 1 | 1 |
| 0.825 | 0 | 0 | 0 | 1 | 0 | 0 |
| 0.850 | 0 | 0 | 0 | 1 | 0 | 1 |
| 0.875 | 0 | 0 | 0 | 1 | 1 | 0 |
| 0.900 | 0 | 0 | 0 | 1 | 1 | 1 |

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| OUTPUT VOLTAGE [V] | B5 | B4 | B3 | B2 | B1 | B0 |
|--------------------|----|----|----|----|----|----|
| 0.925 | 0 | 0 | 1 | 0 | 0 | 0 |
| 0.950 | 0 | 0 | 1 | 0 | 0 | 1 |
| 0.975 | 0 | 0 | 1 | 0 | 1 | 0 |
| 1.000 | 0 | 0 | 1 | 0 | 1 | 1 |
| 1.025 | 0 | 0 | 1 | 1 | 0 | 0 |
| 1.050 | 0 | 0 | 1 | 1 | 0 | 1 |
| 1.075 | 0 | 0 | 1 | 1 | 1 | 0 |
| 1.100 | 0 | 0 | 1 | 1 | 1 | 1 |
| 1.125 | 0 | 1 | 0 | 0 | 0 | 0 |
| 1.150 | 0 | 1 | 0 | 0 | 0 | 1 |
| 1.175 | 0 | 1 | 0 | 0 | 1 | 0 |
| 1.200 | 0 | 1 | 0 | 0 | 1 | 1 |
| 1.225 | 0 | 1 | 0 | 1 | 0 | 0 |
| 1.250 | 0 | 1 | 0 | 1 | 0 | 1 |
| 1.275 | 0 | 1 | 0 | 1 | 1 | 0 |
| 1.300 | 0 | 1 | 0 | 1 | 1 | 1 |
| 1.325 | 0 | 1 | 1 | 0 | 0 | 0 |
| 1.350 | 0 | 1 | 1 | 0 | 0 | 1 |
| 1.375 | 0 | 1 | 1 | 0 | 1 | 0 |
| 1.400 | 0 | 1 | 1 | 0 | 1 | 1 |
| 1.425 | 0 | 1 | 1 | 1 | 0 | 0 |
| 1.450 | 0 | 1 | 1 | 1 | 0 | 1 |
| 1.475 | 0 | 1 | 1 | 1 | 1 | 0 |
| 1.500 | 0 | 1 | 1 | 1 | 1 | 1 |
| 1.550 | 1 | 0 | 0 | 0 | 0 | 0 |
| 1.600 | 1 | 0 | 0 | 0 | 0 | 1 |
| 1.650 | 1 | 0 | 0 | 0 | 1 | 0 |
| 1.700 | 1 | 0 | 0 | 0 | 1 | 1 |
| 1.750 | 1 | 0 | 0 | 1 | 0 | 0 |
| 1.800 | 1 | 0 | 0 | 1 | 0 | 1 |
| 1.850 | 1 | 0 | 0 | 1 | 1 | 0 |
| 1.900 | 1 | 0 | 0 | 1 | 1 | 1 |
| 1.950 | 1 | 0 | 1 | 0 | 0 | 0 |
| 2.000 | 1 | 0 | 1 | 0 | 0 | 1 |
| 2.050 | 1 | 0 | 1 | 0 | 1 | 0 |
| 2.100 | 1 | 0 | 1 | 0 | 1 | 1 |
| 2.150 | 1 | 0 | 1 | 1 | 0 | 0 |
| 2.200 | 1 | 0 | 1 | 1 | 0 | 1 |
| 2.250 | 1 | 0 | 1 | 1 | 1 | 0 |
| 2.300 | 1 | 0 | 1 | 1 | 1 | 1 |
| 2.350 | 1 | 1 | 0 | 0 | 0 | 0 |
| 2.400 | 1 | 1 | 0 | 0 | 0 | 1 |
| 2.450 | 1 | 1 | 0 | 0 | 1 | 0 |
| 2.500 | 1 | 1 | 0 | 0 | 1 | 1 |
| 2.550 | 1 | 1 | 0 | 1 | 0 | 0 |
| 2.600 | 1 | 1 | 0 | 1 | 0 | 1 |
| 2.650 | 1 | 1 | 0 | 1 | 1 | 0 |
| 2.700 | 1 | 1 | 0 | 1 | 1 | 1 |

| OUTPUT VOLTAGE [V] | B5 | B4 | B3 | B2 | B1 | B0 |
|--------------------|----|----|----|----|----|----|
| 2.750 | 1 | 1 | 1 | 0 | 0 | 0 |
| 2.800 | 1 | 1 | 1 | 0 | 0 | 1 |
| 2.850 | 1 | 1 | 1 | 0 | 1 | 0 |
| 2.900 | 1 | 1 | 1 | 0 | 1 | 1 |
| 3.000 | 1 | 1 | 1 | 1 | 0 | 0 |
| 3.100 | 1 | 1 | 1 | 1 | 0 | 1 |
| 3.200 | 1 | 1 | 1 | 1 | 1 | 0 |
| 3.300 | 1 | 1 | 1 | 1 | 1 | 1 |

DEFSLEW. Register Address: 15h

| DEFSLEW | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
|--------------------------|----|----|----|----|----|-------|-------|-------|
| Bit name and function | | | | | | SLEW2 | SLEW1 | SLEW0 |
| Default | 0 | 0 | 0 | 0 | 0 | 1 | 1 | 0 |
| Default value loaded by: | | | | | | UVLO | UVLO | UVLO |
| Read/write | R | R | R | R | R | R/W | R/W | R/W |

The DEFSLEW register defines the slew rate of the output voltage for DCDC2 and DCDC3 in case the voltage is changed during operation. In case Bit “LDO2 tracking” in register DEF LDO2 is set, this is also valid for LDO2. When the voltage change is initiated by toggling pin DEFDCDC2 or DEFDCDC3, the start of the voltage change is triggered by the rising or falling edge of the DEFDCDC2 or DEFDCDC3 pin. If a voltage change is done internally by re-programming register DEFDCDC2_LOW, DEFDCDC2_HIGH, DEFDCDC3_LOW or DEFDCDC3_HIGH, the voltage change is initiated immediately after the new value has been written to the register with the slew rate defined.

| SLEW2 | SLEW1 | SLEW0 | VDCDC3 SLEW RATE |
|-------|-------|-------|------------------|
| 0 | 0 | 0 | 0.11 mV/μs |
| 0 | 0 | 1 | 0.22 mV/μs |
| 0 | 1 | 0 | 0.45 mV/μs |
| 0 | 1 | 1 | 0.9 mV/μs |
| 1 | 0 | 0 | 1.8 mV/μs |
| 1 | 0 | 1 | 3.6 mV/μs |
| 1 | 1 | 0 | 7.2 mV/μs |
| 1 | 1 | 1 | Immediate |

LDO_CTRL1. Register Address: 16h

| LDO_CTRL1 | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
|--------------------------|---------|---------|---------|----|---------|---------|---------|---------|
| Bit name and function | LDO_SQ2 | LDO_SQ1 | LDO_SQ0 | | LDO1[3] | LDO1[2] | LDO1[1] | LDO1[0] |
| Default value loaded by: | UVLO | UVLO | UVLO | | UVLO | UVLO | UVLO | UVLO |
| Read/write | R/W | R/W | R/W | R | R/W | R/W | R/W | R/W |

Bit 7..5 LDO_SQ2 to LDO_SQ0: power-up sequencing: (power down sequencing is the reverse)

000 = LDO1 and LDO2 are enabled as soon as device is in ON-state by pulling $\overline{\text{PB_IN}}=\text{LOW}$ or $\text{POWER_ON}=\text{HIGH}$

001 = LDO1 and LDO2 are enabled after DCDC3 was enabled and its power good Bit is high.

010 = external pin at "EN_EXTLDO" is driven HIGH first, after >1ms LDO2 is enabled, LDO1 is enabled at the same time with DCDC3. EN_EXTLDO is driven LOW by going into OFF-state, LDO2 is disabled at the same time with EN_EXTLDO going LOW. Disabling LDO2 in register CON_CTRL1 will not drive EN_EXTLDO=LOW. (Atlas4)

011 = LDO1 is enabled 300us after PGOOD of DCDC1, LDO2 is off. LDO2 can be enabled/disabled by an I2C command in register CON_CTRL1.

100 = LDO1 is enabled after DCDC1 shows power good; LDO2 is enabled with DCDC3

101 = LDO1 is enabled with DCDC2; LDO2 is enabled after DCDC1 is enabled and its power good Bit is high

110 = LDO1 is enabled 10ms after DCDC2 is enabled and its power good Bit is high, LDO2 is off. LDO2 can be enabled / disabled by an I2C command in register CON_CTRL1.

111 = external pin at EN_EXTLDO is driven HIGH first, after >1ms LDO2 is enabled, LDO1 is enabled when EN_DCDC3 pin is pulled high AND DCDC3 is power good (first power-up from OFF state). LDO1 is disabled when EN_DCDC3 pin goes LOW for SLEEP mode. LDO2 is disabled at the same time with DCDC2 and DCDC1 during shutdown (Sirf PRIMA).

Automatic sequencing sets the enable Bits of the LDOs accordingly, so the LDOs can be enabled or disabled by the I2C interface in ON-state.

All sequencing options that define a ramp in sequence for the DCDC converters and the LDOs, (not at the same time) are timed such that the power good signal triggers the start for the next converter. If there is a time defined such as 1ms delay, the timer is started after the power good signal of the previous converter is high. LDO enable is delayed by 170us internally to match the delay for the DCDC converters. By this, for sequencing options that define a ramp at the same time for an LDO and a DCDC converter, it is made sure they will ramp at the same time, given the fact the DCDC converters have an internal 170us delay as well.

Bit 3..0 LDO1(3) to LDO1(0):

The Bits define the default output voltage of LDO1 according to the table below:

| LDO1[3] | LDO1[2] | LDO1[1] | LDO1[0] | LDO1 OUTPUT VOLTAGE |
|---------|---------|---------|---------|---------------------|
| 0 | 0 | 0 | 0 | 1.0 V |
| 0 | 0 | 0 | 1 | 1.1 V |
| 0 | 0 | 1 | 0 | 1.2 V |
| 0 | 0 | 1 | 1 | 1.25 V |
| 0 | 1 | 0 | 0 | 1.3 V |
| 0 | 1 | 0 | 1 | 1.35 V |
| 0 | 1 | 1 | 0 | 1.4 V |
| 0 | 1 | 1 | 1 | 1.5 V |
| 1 | 0 | 0 | 0 | 1.6 V |
| 1 | 0 | 0 | 1 | 1.8 V |
| 1 | 0 | 1 | 0 | 2.5 V |
| 1 | 0 | 1 | 1 | 2.75 V |
| 1 | 1 | 0 | 0 | 2.8 V |
| 1 | 1 | 0 | 1 | 3.0 V |
| 1 | 1 | 1 | 0 | 3.1 V |
| 1 | 1 | 1 | 1 | 3.3 V |

DEFLDO2. Register Address: 17h

| DEFLDO2 | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
|--------------------------|----|---------------|---------|---------|---------|---------|---------|---------|
| Bit name and function | | LDO2 tracking | LDO2[5] | LDO2[4] | LDO2[3] | LDO2[2] | LDO2[1] | LDO2[0] |
| Default value loaded by: | | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO |
| Read/write | R | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

The DEFLDO2 register is used to set the output voltage of LDO2 according to the voltage table defined under DEFDCDC3 when Bit LDO2 tracking is set to 0. In case Bit LDO2 tracking is set to 1, the output voltage of LDO2 is defined by the contents defined for DCDC3.

Bit 6 LDO2 TRACKING:

0 = the output voltage is defined by register DEFLDO2

1 = the output voltage follows the setting defined for DCDC3 (DEFDCDC3_LOW or DEFDCDC3_HIGH, depending on the state of pin DEFDCDC3)

Bit 5..0 LDO2[5] to LDO2[0]:

output voltage setting for LDO2 similar to DCDC3

WLED_CTRL1. Register Address: 18h

| WLED_CTRL1 | B7 | B6 | B5 | B4 | B3 | B2 | B1 | BO |
|--------------------------|--------------|----|--------------------|--------------------|----|----|----|----|
| Bit name and function | Enable ISINK | | Dimming frequency1 | Dimming frequency0 | | | | |
| Default | 0 | 0 | 0 | 1 | 0 | 0 | 0 | 0 |
| Default value loaded by: | UVLO | | UVLO | UVLO | | | | |
| Read/write | R/W | R | R/W | R/W | R | R | R | R |

Bit 7 **ENABLE ISINK:**
 0 = both current sinks are turned OFF, the wLED boost converter is disabled
 1 = both current sinks are turned on, the wLED boost converter is enabled

Bit 5..4 **DIMMING FREQUENCY 0/1:**
 00 = 100 Hz
 01 = 200 Hz
 10 = 500 Hz
 11 = 1000 Hz

WLED_CTRL2. Register Address: 19h

| WLED_CTRL2 | B7 | B6 | B5 | B4 | B3 | B2 | B1 | BO |
|--------------------------|---------------|------------------|------------------|------------------|------------------|------------------|------------------|------------------|
| Bit name and function | Current level | LED DUTY CYCLE_6 | LED DUTY CYCLE_5 | LED DUTY CYCLE_4 | LED DUTY CYCLE_3 | LED DUTY CYCLE_2 | LED DUTY CYCLE_1 | LED DUTY CYCLE_0 |
| Default | 0 | 0 | 0 | 1 | 1 | 1 | 1 | 0 |
| Default value loaded by: | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO | UVLO |
| Read/write | R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

Bit 7 **CURRENT LEVEL:**
 0 = current defined with resistor connected from ISET2 to GND
 1 = current defined with resistor connected from ISET1 to GND

Bit 6..0 sets the duty cycle for PWM dimming from 1% (000000) to 100% (1100011).
 Values above 1100011 set the duty cycle to 0 %; default is 30% duty cycle

APPLICATION INFORMATION

STEP-DOWN CONVERTERS

OUTPUT FILTER DESIGN (INDUCTOR AND OUTPUT CAPACITOR)

Inductor Selection

The step-down converters operate typically with 2.2µH output inductor. Larger or smaller inductor values can be used to optimize the performance of the device for specific operation conditions. The selected inductor has to be rated for its DC resistance and saturation current. The DC resistance of the inductance will influence directly the efficiency of the converter. Therefore an inductor with lowest DC resistance should be selected for highest efficiency.

[Equation 4](#) can be used to calculate the maximum inductor current under static load conditions. The saturation current of the inductor should be rated higher than the maximum inductor current as calculated with [Equation 4](#). This is recommended because during heavy load transient the inductor current will rise above the calculated value.

$$\Delta I_L = V_{out} \times \frac{1 - \frac{V_{out}}{V_{in}}}{L \times f} \quad (4)$$

$$I_{Lmax} = I_{outmax} + \frac{\Delta I_L}{2} \quad (5)$$

With

f = Switching Frequency (2.25MHz typical)

L = Inductor Value

ΔI_L = Peak to Peak inductor ripple current

I_{Lmax} = Maximum Inductor current

The highest inductor current will occur at maximum V_{in}.

Open core inductors have a soft saturation characteristic and they can usually handle higher inductor currents versus a comparable shielded inductor.

A more conservative approach is to select the inductor current rating just for the maximum switch current of the corresponding converter. It must be considered, that the core material from inductor to inductor differs and will have an impact on the efficiency especially at high switching frequencies.

Refer to [Table 4](#) and the typical applications for possible inductors.

Table 4. Tested Inductors

| INDUCTOR TYPE | RECOMMENDED MAXIMUM DC CURRENT | INDUCTOR VALUE | SUPPLIER |
|---------------|--------------------------------------|----------------|-----------|
| LPS3010 | 0.6 A | 2.2 µH | Coilcraft |
| LPS3015 | 1.2 A | 2.2 µH | Coilcraft |
| LPS4018 | 1.5 A | 2.2 µH | Coilcraft |
| VLCF4020 | 1.5 A | 2.2 µH | TDK |

Output Capacitor Selection

The advanced Fast Response voltage mode control scheme of the two converters allow the use of small ceramic capacitors with a typical value of 10µF, without having large output voltage under and overshoots during heavy load transients. Ceramic capacitors having low ESR values result in lowest output voltage ripple and are therefore recommended. Please refer to for recommended components.

If ceramic output capacitors are used, the capacitor RMS ripple current rating will always meet the application requirements. Just for completeness the RMS ripple current is calculated as:

$$I_{\text{RMSOut}} = V_{\text{out}} \times \frac{1 - \frac{V_{\text{out}}}{V_{\text{in}}}}{L \times f} \times \frac{1}{2 \times \sqrt{3}} \quad (6)$$

At nominal load current the inductive converters operate in PWM mode and the overall output voltage ripple is the sum of the voltage spike caused by the output capacitor ESR plus the voltage ripple caused by charging and discharging the output capacitor:

$$\Delta V_{\text{out}} = V_{\text{out}} \times \frac{1 - \frac{V_{\text{out}}}{V_{\text{in}}}}{L \times f} \times \left(\frac{1}{8 \times C_{\text{out}} \times f} + \text{ESR} \right) \quad (7)$$

Where the highest output voltage ripple occurs at the highest input voltage V_{in} .

At light load currents the converters operate in Power Save Mode and the output voltage ripple is dependent on the output capacitor value. The output voltage ripple is set by the internal comparator delay and the external capacitor. The typical output voltage ripple is less than 1% of the nominal output voltage.

Input Capacitor Selection/Input Voltage

Because of the nature of the buck converter having a pulsating input current, a low ESR input capacitor is required for best input voltage filtering and minimizing the interference with other circuits caused by high input voltage spikes. The converters need a ceramic input capacitor of 10 μ F. The input capacitor can be increased without any limit for better input voltage filtering.

The input voltage for the step-down converters needs to be connected to pin VINDCDC1/2 for DCDC1 and DCDC2 and to pin VINDCDC3 for DCDC3. These pins need to be tied together to the power source on pin SYS (output of the power path). The 3 step-down converters must not be supplied from different input voltages.

Table 5. Possible Capacitors

| | | | |
|------------|------|---------------------------|---------|
| 22 μ F | 0805 | TDK C2012X5R0J226MT | Ceramic |
| 22 μ F | 0805 | Taiyo Yuden JMK212BJ226MG | Ceramic |
| 10 μ F | 0805 | Taiyo Yuden JMK212BJ106M | Ceramic |
| 10 μ F | 0805 | TDK C2012X5R0J106M | Ceramic |

Output Voltage Selection

The DEFDCDC2 and DEFDCDC3 pins are used to set the output voltage for step-down converter DCDC2 and DCDC3. See table 1 for the default voltages if the pins are pulled to GND or to Vcc.

Voltage Change on DCDC2 and DCDC3

The output voltage of DCDC2 and DCDC3 can be changed during operation from e.g. 1.0V to 1.2V (TPS65070) and back by toggling the DEFDCDC2 or DEFDCDC3 pin. The status of the DEFDCDC3 pin is sensed during operation and the voltage is changed as soon as the logic level on this pin changes from low to high or vice versa.

The output voltage for DCDC2 and DCDC3 can also be changed by changing the register content in registers DEFDCDC2_LOW, DEFDCDC2_HIGH, DEFDCDC3_LOW and DEFDCDC3_HIGH.

White-LED BOOST CONVERTER

LED-Current Setting/Dimming

The white LED boost converter generates an output voltage, high enough to drive current through up to 10 white LEDs connected in series. support one or two strings of white LEDs. If two strings of white LEDs are used, the number of LEDs in each string is limited to 6LEDs due to the switch current limit as defined in the electrical characteristics. The boost converter block contains two current sinks to control the current through the white LEDs. The anodes of the “upper” white-LEDs are directly connected to the output voltage at the output capacitor. The cathode of the “lowest” LED is connected to the input of the current sink at pin ISINK1 or ISINK2. The internal current sink controls the output voltage of the boost converter such that there is a minimum voltage at the current sink to regulate the defined current. The maximum current is set with a resistor connected from pin

ISET1 to GND. Dimming is done with an internal PWM modulator by changing the duty cycle in the current sinks from 1% to 100%. In order to set a LED current of less than 1% of the current defined at ISET1, a second current range is set with a resistor at pin ISET2 to GND. By changing between the two current ranges and varying the duty cycle, it is possible to achieve a dimming ratio of > 1:100. The main functions of the converter like enable / disable of the converter, PWM duty cycle and dimming frequency are programmed in registers WLED_CTRL1 and WLED_CTRL2 – see the register description for details.

If only one string of white LEDs are used, ISINK1 and ISINK2 need to be connected in parallel.

Setup

In applications not requiring the wLED boost converter, the pins should be tied to a GND as stated below:

Pins L4, FB_wLED, ISINK1 and ISINK2 should be directly connected to GND. Each ISET1 and ISET2 should be connected to GND with a 100k resistor. Optionally ISET1 and ISET2 can be used as analog inputs to the ADC. In this case, these pins can be tied to a voltage source in the range from 0V to 2.25V.

Setting the LED Current

There are two resistors which set the default current for the current sinks at ISINK1 and ISINK2.

The resistor connected to ISET1 is used if Bit CURRENT LEVEL is set 1 in register 19h.

The resistor connected to ISET2 is used if Bit CURRENT LEVEL is set 0 in register 19h (default).

This allows switching between two different maximum values for the LED current with one Bit to extend the resolution for dimming.

Dimming is done by an internal PWM signal that turns on and off the current sinks ISINK1 and ISINK2 at 200Hz (default). The duty cycle range is 1% to 100% with a 1% resolution and a default duty cycle of 30%. In order to get the full scale LED current, the PWM dimming needs to be set to 100% in register 19h. This is done by writing 63h to register 19h.

K_{ISET} is defined to be 1000 in the electrical spec, the reference voltage at ISET1 and ISET2 is 1.24V.

The current for each string is set by the resistor to:

$$ISINK1=ISINK2= K_{ISET} \times 1.24V/R_{ISETx} \quad (8)$$

$$R_{ISET1}, R_{ISET2} = K_{ISET} \times 1.24V/10mA=124 \text{ k}\Omega \quad (9)$$

A resistor value of 124 k Ω sets the current on each string to 10mA.

For one string of wLEDs, both strings need to be connected in parallel, so the current in the wLEDs is twice the current programmed by the resistor at ISET1 or ISET2.

Connecting both strings in parallel is required because the wLED converter generates its output voltage dependant on the current in ISINK1 and ISINK2. If the current falls below the target, the output voltage is increased. If one string is open, the wLED driver will boost the output voltage to its maximum because it assumes the voltage is not high enough to drive current into this string (there could be different numbers of wLEDs in the two strings).

Inductor Design

The inductor in a boost converter serves as an energy storage element. The energy stored equals $\frac{1}{2} L \times I^2$. Therefore, the inductor must not be saturated as the inductance will drop and the energy stored will be reduced causing bad efficiency. The converter operates with typically 15 μ H to 22 μ H inductors. A design example for an application powering 6LEDs in one string given below:

$V_{in} = 2.8 \text{ V}$ — minimum input voltage for the boost converter

$V_o = 6 \times 3.2 \text{ V} = 19.2 \text{ V}$ — assuming a forward voltage of 3.2V per LED

$V_f = 0.5 \text{ V}$ — forward voltage of the Schottky diode

$I_o = 25 \text{ mA}$ maximum LED current

$f_{sw} = 1.125 \text{ MHz}$ — switching frequency — $T=890\text{ns}$

$R_{ds(on)} = 0.6R$ — drain-source resistance of the internal NMOS switch

V_{sw} — voltage drop at the internal NMOS switch

I_{AVG} — average current in NMOS when turned on

The duty cycle for a boost converter is:

$$D = \frac{V_o + V_f - V_{in}}{V_o + V_f - V_{sw}} \quad (10)$$

With:

$$V_{sw} = R_{ds(on)} \times I_{AVG} \quad I_{avg} = \frac{I_o}{1 - D} \quad (11)$$

A different approach to calculate the duty cycle is based on the efficiency of the converter. The typical number can be found in the graphs, or as a first approach, we can assume to get an efficiency of about 80% as a typical value.

$$D \approx \left(1 - \eta \times \frac{V_i}{V_o + V_f} \right) \quad (12)$$

With the values given above

$$D \approx \left(1 - 0.8 \frac{2.8 \text{ V}}{19.2 \text{ V} + 0.5 \text{ V}} \right) \approx 89\% \quad (13)$$

$$t_{on} = T \times D = 890 \text{ ns} \times 0.89 = 792 \text{ ns}$$

$$t_{off} = 890 \text{ ns} - 792 \text{ ns} = 98 \text{ ns}$$

$$V_{sw} = R_{ds(on)} \times I_{AVG} = R_{ds(on)} \times \frac{I_o}{1 - D} = 0.6 \Omega \times \frac{25 \text{ mA}}{1 - 0.89} \approx 140 \text{ mV} \quad (14)$$

When the NMOS switch is turned on, the input voltage is forcing a current into the inductor. The current slope can be calculated with:

$$di = \frac{V_L \times dt}{L} = \frac{(V_{in} - V_{sw}) \times dt}{L} = \frac{(2.8 \text{ V} - 0.14 \text{ V}) \times 792 \text{ ns}}{18 \mu\text{H}} = 117 \text{ mA} \quad (15)$$

$$I_{avg} = \frac{I_o}{1 - D} = \frac{25 \text{ mA}}{1 - 0.89} = 227 \text{ mA} \quad (16)$$

The minimum and maximum inductor current can be found by adding half of the inductor current ripple (di) to the average value, which gives:

$$I_{max} = 227 \text{ mA} + \frac{117 \text{ mA}}{2} = 285 \text{ mA}$$

$$I_{min} = 227 \text{ mA} - \frac{117 \text{ mA}}{2} = 169 \text{ mA} \quad (17)$$

Given the values above, an inductor with a current rating greater than 290mA is needed. Plenty of margin should be kept to the rating in the inductor vendors data sheets as the maximum current is typically specified at a inductance drop of 20% or even 30%. A list of tested inductors is given in [Table 6](#) with the test conditions as mentioned below.

Test conditions:

- $V_{in} = 2.8 \text{ V}$
- $V_f = 3.2 \text{ V}$ (per LED)
- $V_f = 0.5 \text{ V}$ (Schottky diode)
- $I_{out} = 25 \text{ mA}$ per string; no dimming

Table 6. Tested Inductors

| LED CONFIGURATION | INDUCTOR TYPE | INDUCTOR VALUE | SUPPLIER |
|-------------------|---------------|------------------|-----------|
| 1 × 6LEDs | LPS3015 | 18 μH | Coilcraft |
| 2 × 6LEDs | LPS4018 | 47 μH | Coilcraft |
| 1 × 10LEDs | LPS4018 | 47 μH | Coilcraft |

Other inductors, with lower or higher inductance values can be used. A higher inductance will cause a lower inductor current ripple and therefore will provide higher efficiency. The boost converter will also stay in continuous conduction mode over a wider load current range. The energy stored in an inductor is given by $E = 1/2 L \times I^2$ where I is the peak inductor current. The maximum current in the inductor is limited by the internal current limit of the device, so the maximum power is given by the minimum peak current limit (see electrical specifications) times the inductance value. For highest output power, a large inductance value is needed. The minimum inductor value possible is limited by the energy needed to supply the load. The limit for the minimum inductor value is given during the on-time of the switch such that the current limit is not reached.

Example for the minimum inductor value:

$$\begin{aligned} V_{in} &= 4.2 \text{ V}, V_{out} = 19.7 \text{ V}, I_{out} = 5 \text{ mA}, V_{sw} = 0.1 \text{ V} \\ &\rightarrow D = 79\% \\ &\rightarrow t_{on} = 703 \text{ ns} \end{aligned}$$

During the on-time, the inductor current should not reach the current limit of 1.4 A.

With $V_{...}$ voltage across the inductor ($V = V_{in} - V_{sw}$)

$$\rightarrow L = V \times dt/di = (4.2 \text{ V} - 0.1 \text{ V}) \times 703 \text{ ns} / 1.4 \text{ A} = 2 \mu\text{H}$$

Diode Selection

Due to the non-synchronous design of the boost converter, an external diode is needed. For best performance, a Schottky diode with a voltage rating of 40V or above should be used. A diode such as the MBR0540 with an average current rating of 0.5A is sufficient.

Output Capacitor Selection

A ceramic capacitor such as X5R or X7R type is required at the output. See [Table 7](#) for reference.

Table 7. Tested Capacitor

| LED CONFIGURATION | TYPICAL VOLTAGE ACROSS OUTPUT CAPACITOR | CAPACITOR VALUE | CAPACITOR SIZE | CAPACITOR TYPE | MANUFACTURER |
|--------------------|---|--------------------------|----------------|-----------------|--------------|
| 2x6LEDs or 1x6LEDs | 21 V | 4.7 μF / 50 V | 1206 | UMK316BJ475KL | Taiyo Yuden |
| 1x10LEDs | 35 V | 4.7 μF / 50 V | 1210 | GRM32ER71H475KA | Murata |

Input Capacitor Selection

A small ceramic input capacitor of 10 μF is needed at the input of the boost converter. If the inductor is directly connected to the SYS output of , the capacitor can be shared. In this case the capacitance needs to be 22 μF or above. Only X5R or X7R ceramic capacitors should be used.

BATTERY CHARGER

Temperature Sensing

The battery charger integrated in has an over temperature protection for the Li-ion cell. The temperature is sensed with a NTC located at the battery. Comparators in suspend charge at a temperature below 0°C and above 45°C. The charger supports two different resistor values for the NTC. The default is internally programmed to 10k. It is possible to change to a 100k NTC with the I2C interface.

Table 8. NTCs Supported

| RESISTANCE AT 25°C | CURVE / B VALUE | RT2 NEEDED FOR LINEARIZATION | MANUFACTURER |
|--------------------|------------------|------------------------------|--------------|
| 10k | Curve 2 / B=3477 | 75k | Several |
| 100k | Curve 1 / B=3964 | 370k | Several |

For best performance, the NTC needs to be linearized by connecting a resistor (RT2) in parallel to the NTC as shown in [Figure 46](#). The resistor value of RT2 needed for linearization can be found in [Table 8](#).

If the battery charger needs to be operated without a NTC connected, e.g. for test purposes, a resistor of 10k or 100k needs to be connected from TS to GND, depending for which NTC is configured to in register CHCONFIG1.

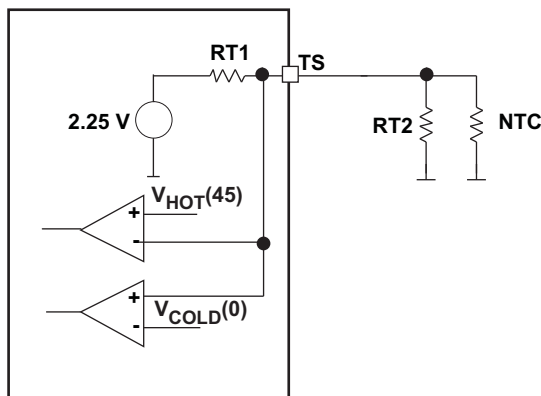


Figure 45. Linearizing the NTC

Changing the Charging Temperature Range (Default 0°C to 45°C)

The battery charger is designed to operate with the two NTCs listed above. These will give a cold and hot temperature threshold of 0°C and 45°C. If the charger needs to operate (charge) in a wider temperature range e.g. -5°C to 50°C, the circuit can be modified accordingly. The NTC changes its resistance based on the equation listed below:

$$R_{NTC}(T) = R_{25} \times e^{\left(B \times \left(\frac{1}{T} - \frac{1}{T_0} \right) \right)} \quad (18)$$

With:

- R25 = NTC resistance at 25°C
- T = temperature in Kelvin
- T0 = reference temperature (298K)

Resistor RT2 in parallel to the NTC is used to linearize the resistance change with temperature of the NTC. As the NTC has a high resistance at low temperature, the resulting resistance of NTC in parallel with RT2 is lower especially for low temperatures where the NTC has a high resistance, so RT2 in parallel has a significant impact. For higher temperatures, the resistance of the NTC dropped significantly, so RT2 in parallel does not change the resulting resistance a lot. See [Figure 46](#).

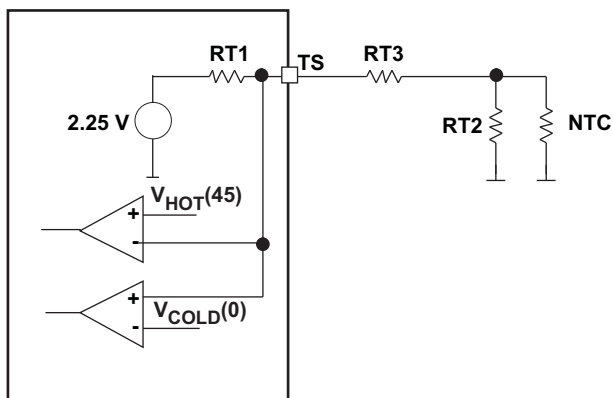


Figure 46. Changing the Temperature Range

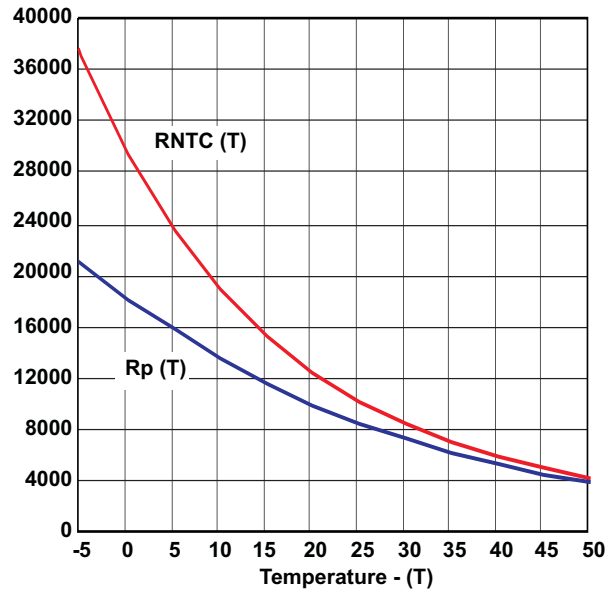


Figure 47. NTC [R(T)] and NTC in Parallel to RT2 [Rges(T)]

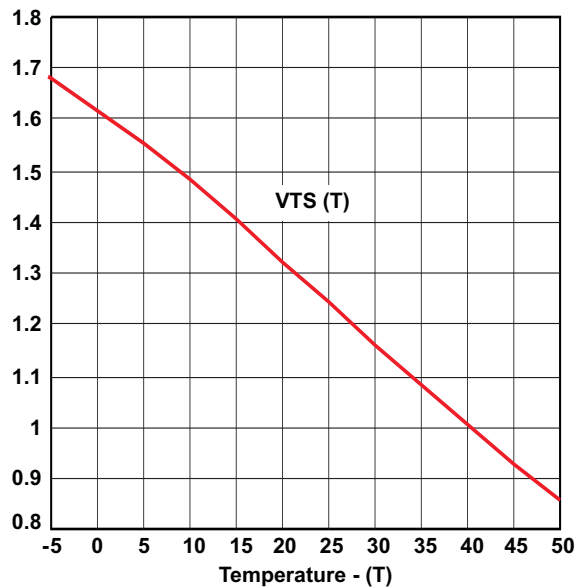


Figure 48. Resulting TS Voltage

As Figure 47 shows, the result is an extended charging temperature range at lower temperatures. The upper temperature limit is shifted to lower values as well resulting in a V(HOT) temperature of slightly less than 45°C. Therefore RT3 is needed to shift the temperature range to higher temperatures again. Figure 48 shows the result for:

- RT2 = 47k
- RT3 = 820R

Using these values will extend the temperature range for charging to -5°C to 50°C.

POWER SOLUTIONS FOR DIFFERENT APPLICATION PROCESSORS

Default Settings

For proper power supply design with , not only the default output voltage is relevant but also in what sequence the different power rails are enabled. The voltages are typically enabled internally based on the sequencing options programmed. For different application processors, there are different sequencing options available. In addition, the delay time and pulse for the reset signal to the application processor is different. See [Table 9](#) with the default settings for sequencing, output voltages and reset options for the family:

Table 9. Sequencing Settings

| | DEDICATED FOR | DCDC_SQ[2..0] | LDO_SQ[2..0] | COMMENT |
|--|---------------|---------------|--------------|---------|
|--|---------------|---------------|--------------|---------|

Starting

was developed for battery powered applications with focus on lowest shutdown and quiescent current. In order to achieve this, in shutdown all mayor blocks and the system voltage at the output of the power path (SYS) are turned off and only the input that turns on , pin $\overline{\text{PB_IN}}$, is supervised. is designed such that only an ON-key on $\overline{\text{PB_IN}}$ is needed pulling this pin LOW to enable . No external pull-up is needed as this is integrated into .

Once $\overline{\text{PB_IN}}$ is pulled LOW, the system voltage is ramped and the dcdc converters and LDOs are started with the sequencing defined for the version used. If $\overline{\text{PB_IN}}$ is released again, TPS6507x would turn off, so a pin was introduced to keep TPS6507x enabled after $\overline{\text{PB_IN}}$ was released. Pin $\overline{\text{POWER_ON}}$ serves this function and needs to be pulled HIGH before the user releases the ON-key ($\overline{\text{PB_IN}} = \text{HIGH}$). This HIGH signal at $\overline{\text{POWER_ON}}$ can be provided by the GPIO of a processor or by a pull-up resistor to any voltage in the system which is higher than 1.2V. Pulling $\overline{\text{POWER_ON}}$ to a supply voltage would significantly reduce the time $\overline{\text{PB_IN}}$ has to be asserted LOW. If $\overline{\text{POWER_ON}}$ is tied to a GPIO, the processor has to boot up first which may take some time. In this case however, the processor could do some additional debouncing, hence does not keep the power enabled if the ON-key is only pressed for a short time. When there is a supply voltage for the battery charger at pins AC or USB, the situation is slightly different. In this case, the power path is enabled and the system voltage (SYS) has ramped already to whatever the voltage at AC or USB is. The dcdc converters are not enabled yet but the start-up could not only be done by pulling $\overline{\text{PB_IN}} = \text{LOW}$ but also by pulling $\overline{\text{POWER_ON}} = \text{HIGH}$.

In applications that do not require an ON-key but shall power-up automatically once supply voltage is applied, there are two cases to consider. If TPS6507x is powered from its AC or USB pin (not powered from its BAT pin), $\overline{\text{POWER_ON}}$ just needs to be pulled HIGH to enable the converters. $\overline{\text{PB_IN}}$ must not be tied LOW in this case.

If TPS6507x is powered from its BAT pin, $\overline{\text{PB_IN}}$ needs to be tied LOW to start-up the converters.

Layout Considerations

As for all switching power supplies, the layout is an important step in the design. Proper function of the device demands careful attention to PCB layout. Care must be taken in board layout to get the specified performance. If the layout is not carefully done, the regulators may show poor line and/or load regulation, and stability issues as well as EMI problems. It is critical to provide a low impedance ground path. Therefore, use wide and short traces for the main current paths. The input capacitors should be placed as close as possible to the IC pins as well as the inductor and output capacitor.

For TPS6507x, connect the PGND pin of the device to the PowerPAD™ land of the PCB and connect the analog ground connection (GND) to the PGND at the PowerPAD™. The PowerPAD™ serves as the power ground connection for the DCDC1 and DCDC2 converters. Therefore it is essential to provide a good thermal and electrical connection to GND using multiple vias to the GND-plane. Keep the common path to the GND pin, which returns the small signal components, and the high current of the output capacitors as short as possible to avoid ground noise. The VDCDCx line should be connected right to the output capacitor and routed away from noisy components and traces (for example, the L1, L2, L3 and L4 traces). See the EVM users guide for details about the layout for TPS6507x.

APPLICATION CIRCUITS

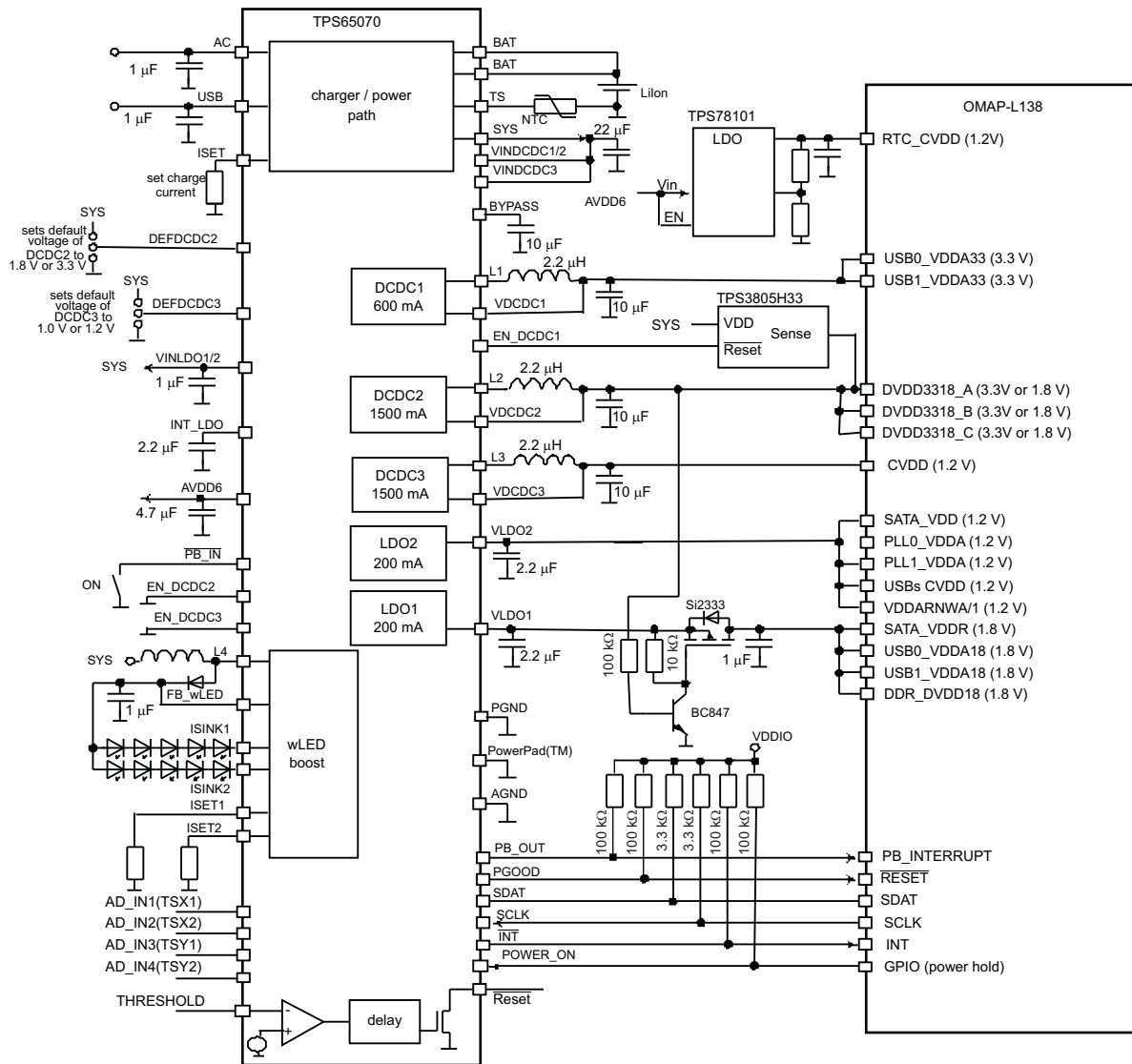


Figure 49. Powering OMAP-L138

TPS65070-Q1, TPS65072-Q1, TPS65073-Q1, TPS650732-Q1

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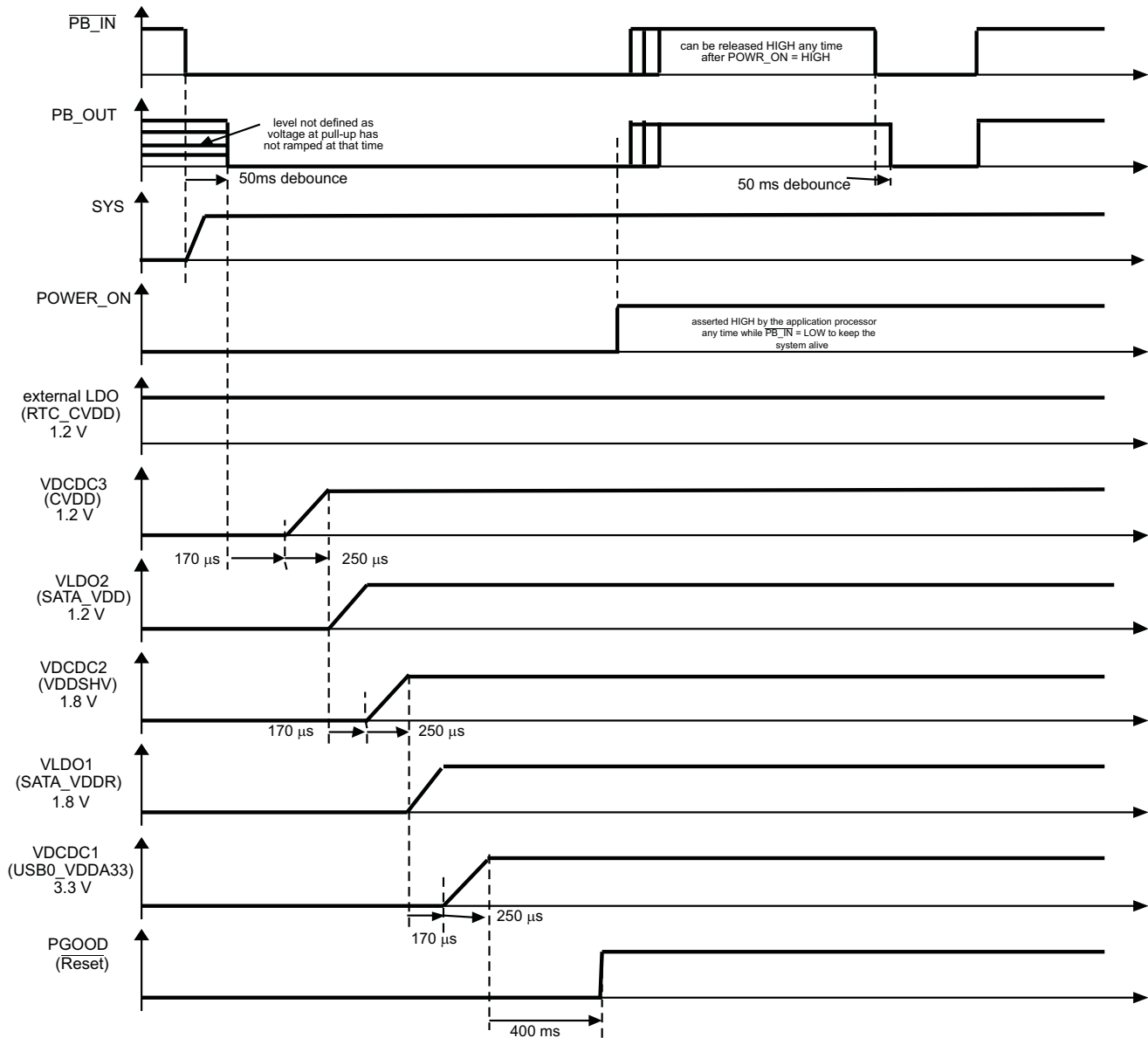
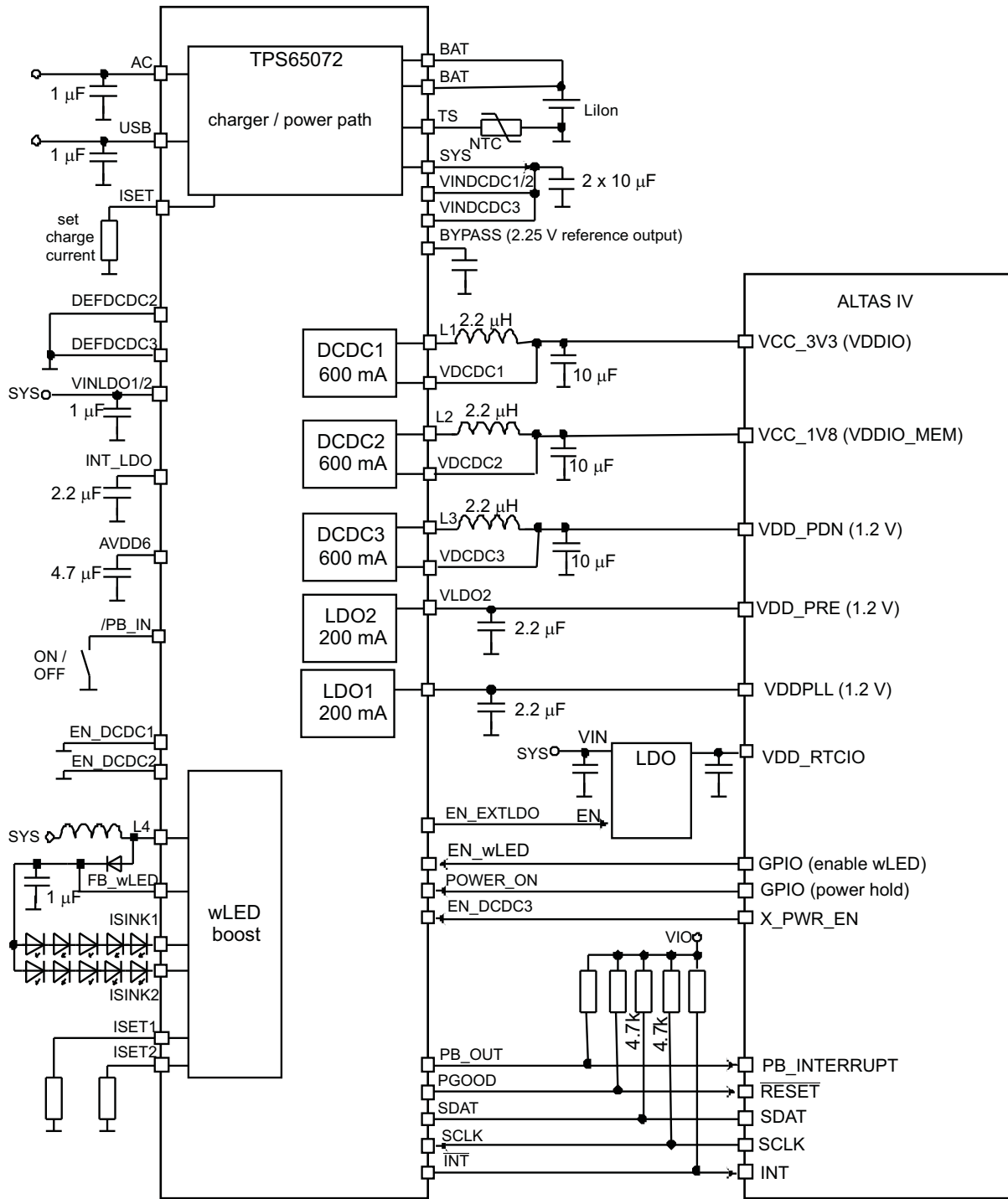


Figure 50. Timing for OMAP-L138



Note: /Reset to Atlas 4 may need to be a RC delay from VDDIO

Figure 51. Powering Atlas IV

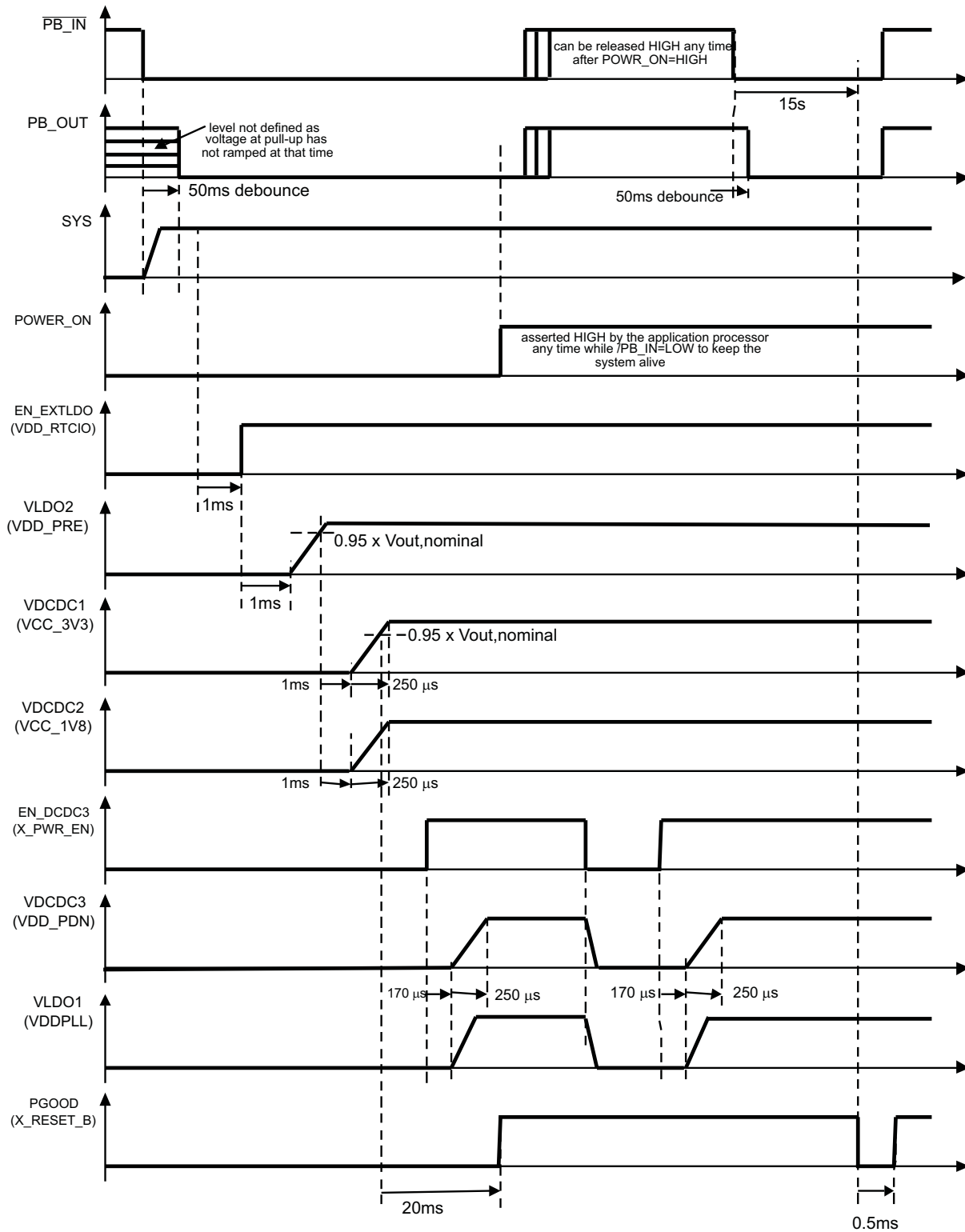


Figure 52. Timing for Atlas IV

Prima SLEEP Mode and DEEP SLEEP Mode Support

TPS6507x contains a sequencing option for the Sifir Prima processor. The sequencing option defines how the voltages are ramped at initial power-up and shutdown as well as the timing for entering power save mode for the processor (SLEEP mode). The Prima processor supports SLEEP mode and also DEEP SLEEP mode. The main difference from a power supply point of view is:

- How the supply voltages are turned off
- Which voltages are turned off
- How power save mode is exited into normal mode
- Reset asserted or not (PGOOD pin of TPS6507x going actively low)

The sequencing option for Prima is defined in one register each for the sequencing of the DCDC converters and for the LDOs. DCDC_SQ[2..0]=100 in register CON_CTRL1 defines the startup sequence for the DCDC converters while LDO_SQ[2..0]=111 defines the sequence for the LDOs. The default is factory programmed therefore it is ensured the first power-up is done in the right sequence.

When TPS6507x is off, a small state machine supervises the status of pin PB_IN while major blocks are not powered for minimum current consumption from the battery as long as there is no input voltage to the charger. Power-up for the TPS6507x is started by $\overline{\text{PB_IN}}$ going LOW. This will turn on the power-FET from the battery so the system voltage (SYS) is rising and the main blocks of the PMU are powered. After a debounce time of 50ms, the main state machine will pull PB_OUT = LOW to indicate that there is a “keypress” by the user and will ramp the DCDC converters and LDOs according to the sequence programmed. It is important to connect the power rails for the processor to exactly the dcDC converters and LDOs as shown in the schematic and sequencing diagrams for proper sequencing. For Prima, the voltage rails for VDD_RTCIO needs to ramp first. This power rail is not provided by the PMU but from an external LDO which is enabled by a signal called EN_EXTLDO from the PMU. The PMU will therefore first rise the logic level on pin EN_EXTLDO high to enable the external LDO. After a 1ms delay the PMU will ramp LDO2 for VDD_PRE and DCDC3 for VDD_PDN. When the output voltage of LDO2 is within its nominal range the internal power good comparator will trigger the state machine which will ramp DCDC1 and DCDC2 to provide the supply voltage for VCC_3V3 and VCC_1V8. Now Prima needs to pull its X_PWR_EN signal high which drives EN_DCDC3 on the PMU. This will now enable LDO1 to power VDDPLL. X_RESET_B will be released by the PMU on pin PGOOD based on the voltage of DCDC1 after a delay of 20ms.

SLEEP Mode

At first power-up (start-up from OFF state), the voltage for VDD_PDN is ramped at the same time than VDD_PRE. This is defined by Bit MASK_EN_DCDC3 in register CON_CTRL2 which is “1” per default. For enabling SLEEP mode, Prima needs to clear this Bit, so the EN_DCDC3 pin takes control over the DCDC3 converter. Prima SLEEP mode is initialized by Prima pulling its X_PWR_EN pin LOW which is driving the EN_DCDC3 pin of TPS6507x. This will turn off the power for VDDPLL (LDO1) and also for VDD_PDN (DCDC3). All other voltage rails will stay on. Based on a “keypress” with PB_OUT going LOW, Prima will wake up and assert EN_DCDC3=HIGH. This will turn DCDC3 and LDO1 back on and Sifir PRIMA will enter normal operating mode.

DEEP SLEEP Mode

Entry into DEEP SLEEP mode is controlled by Prima by writing to register CON_CTRL2 of TPS6507x. Before entering DEEP SLEEP mode, Prima will back up all memory and set Bit DS_RDY=1 to indicate the memory was saved and the content is valid. Setting PWR_DS=1 will turn off all voltage rails except DCDC2 for the memory voltage and the PMU will apply a reset signal by pulling PGOOD=LOW. Prima can not detect logic level change by PB_OUT going low in DEEP SLEEP mode. A wakeup from DEEP sleep is therefore managed by the PMU. The PMU will clear Bit PWR_DS and turn on the converters again based on a user “keypress” when PB_IN is being pulled LOW. Prima will now check if DS_RDY=1 to determine if the memory content is still valid and clear the Bit afterwards. In case there is a power loss and the voltage of the PMU is dropping below the undervoltage lockout threshold, the registers in the PMU are re-set to the default and DS_RDY is cleared. The PMU would perform a start-up from OFF state instead of exit from DEEP SLEEP and Sifir PRIMA would read DS_RDY=0, which indicates memory data is not valid.

See timing diagrams for Sifir Prima SLEEP and DEEP SLEEP in [Figure 53](#) and [Figure 54](#).

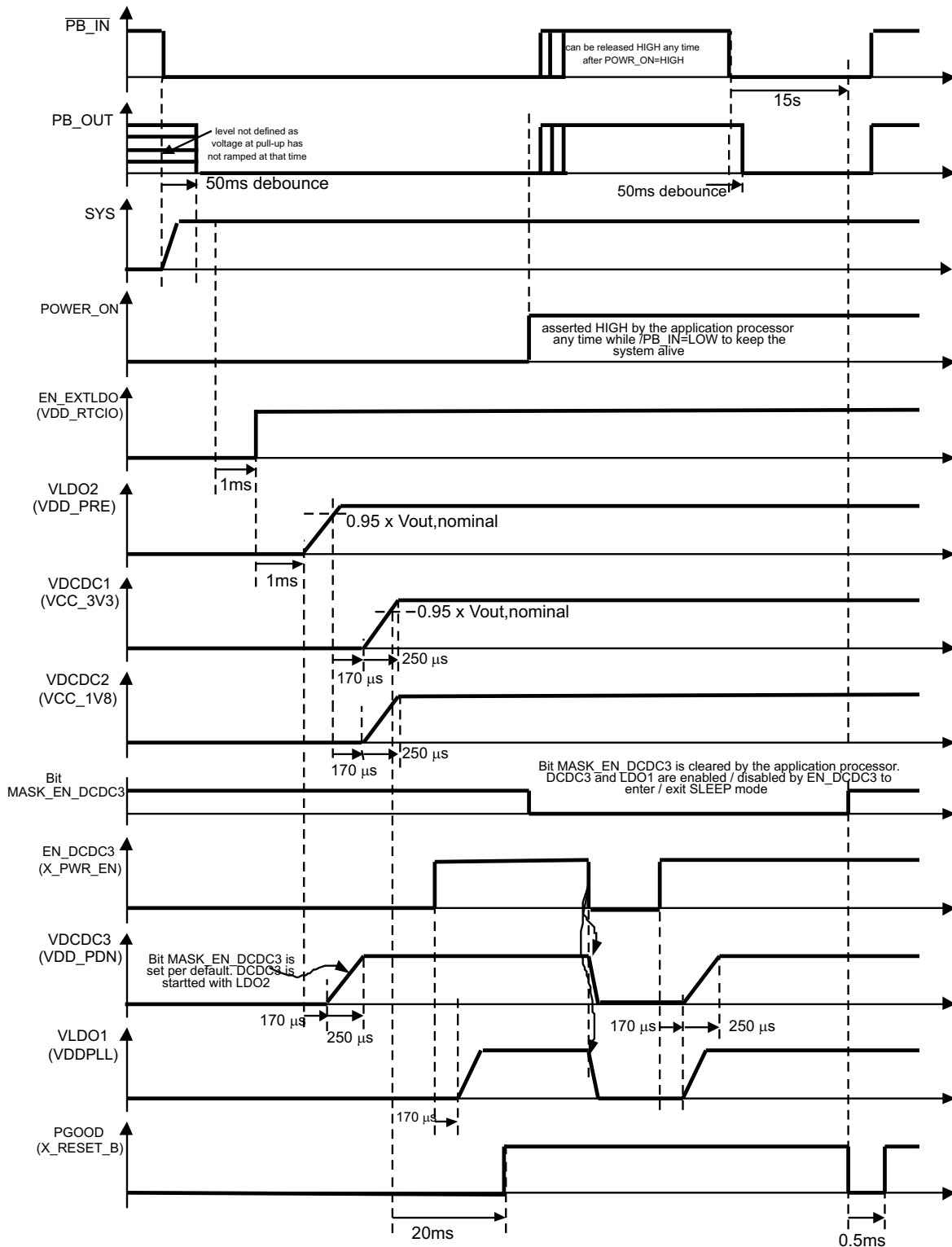


Figure 53. Timing for Sirf Prima SLEEP Mode

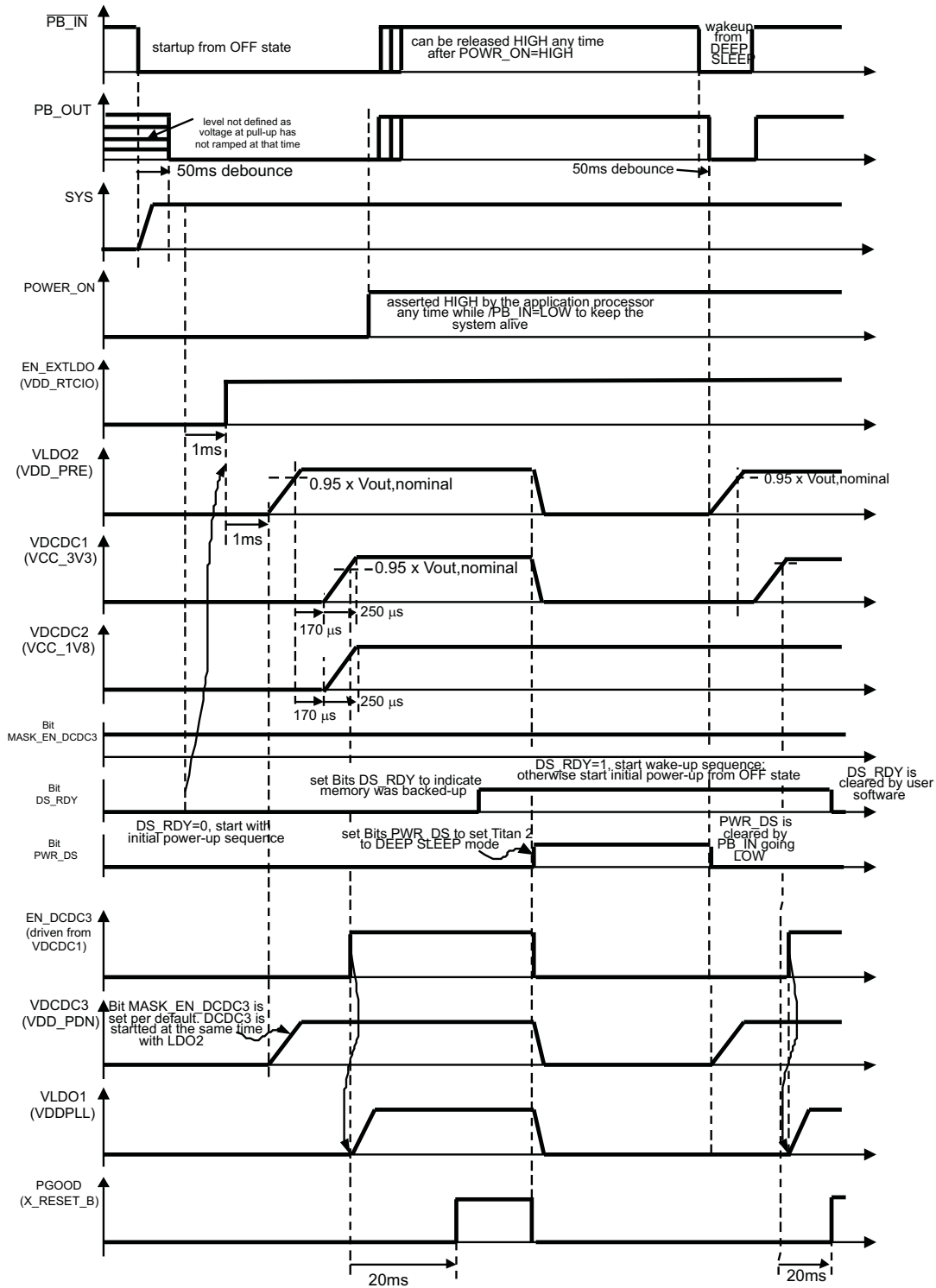


Figure 54. Timing for Sirf Prima DEEP SLEEP Mode

TPS65070-Q1, TPS65072-Q1, TPS65073-Q1, TPS650732-Q1

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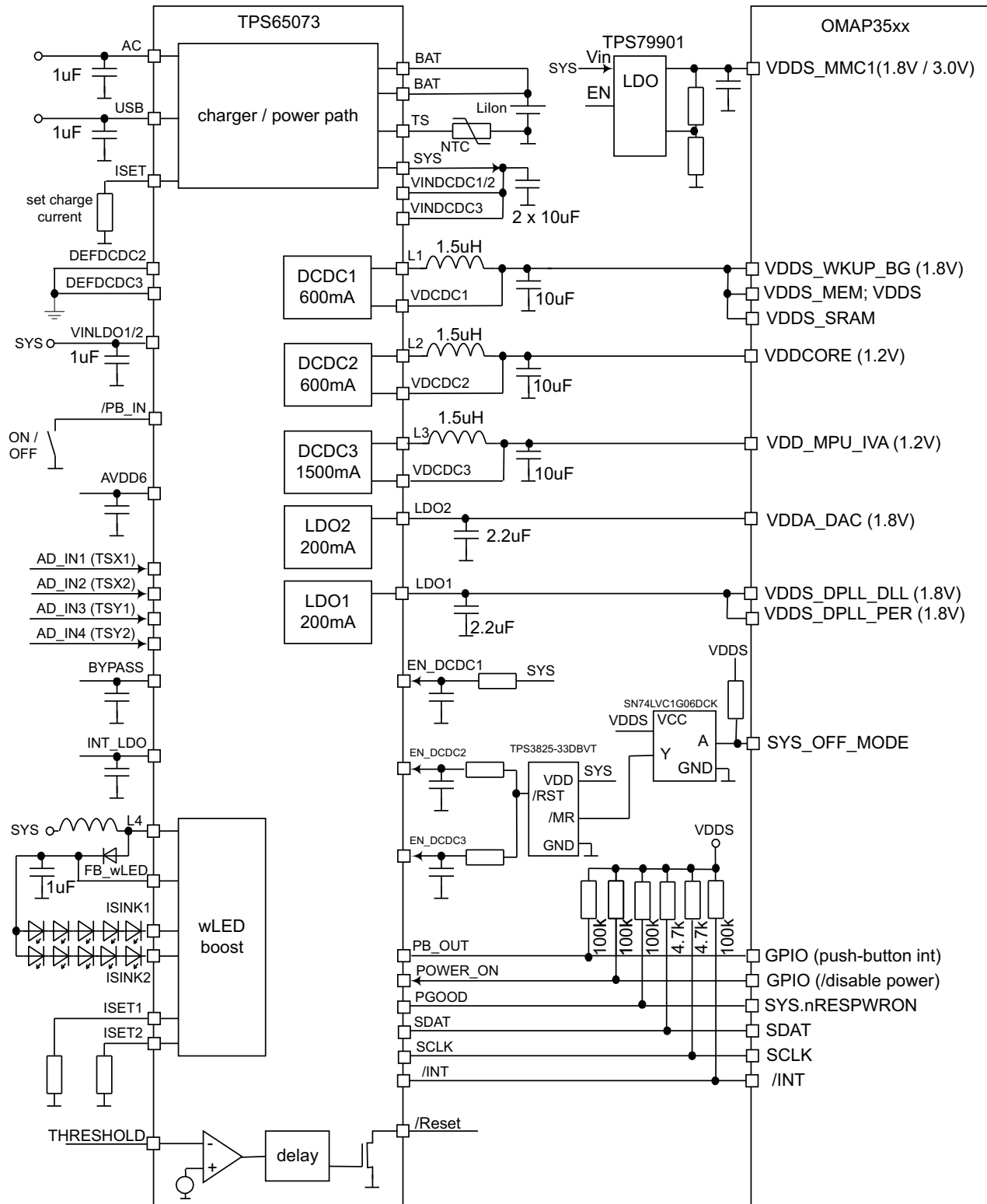


Figure 55. OMAP35xx (Supporting SYS-OFF Mode)

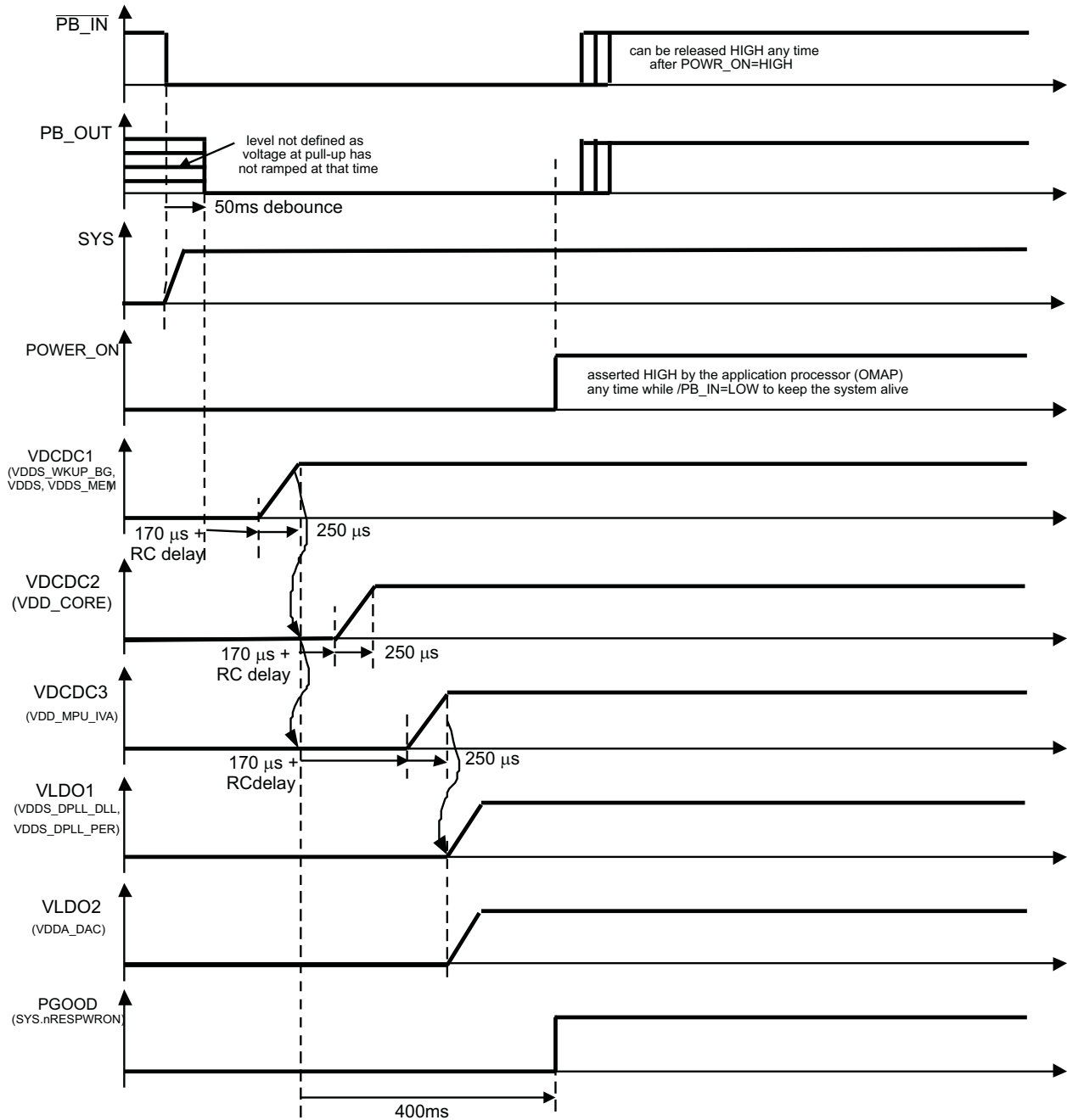


Figure 56. OMAP35xx Timing (Supporting SYS-OFF Mode)

TPS65070-Q1, TPS65072-Q1, TPS65073-Q1, TPS650732-Q1

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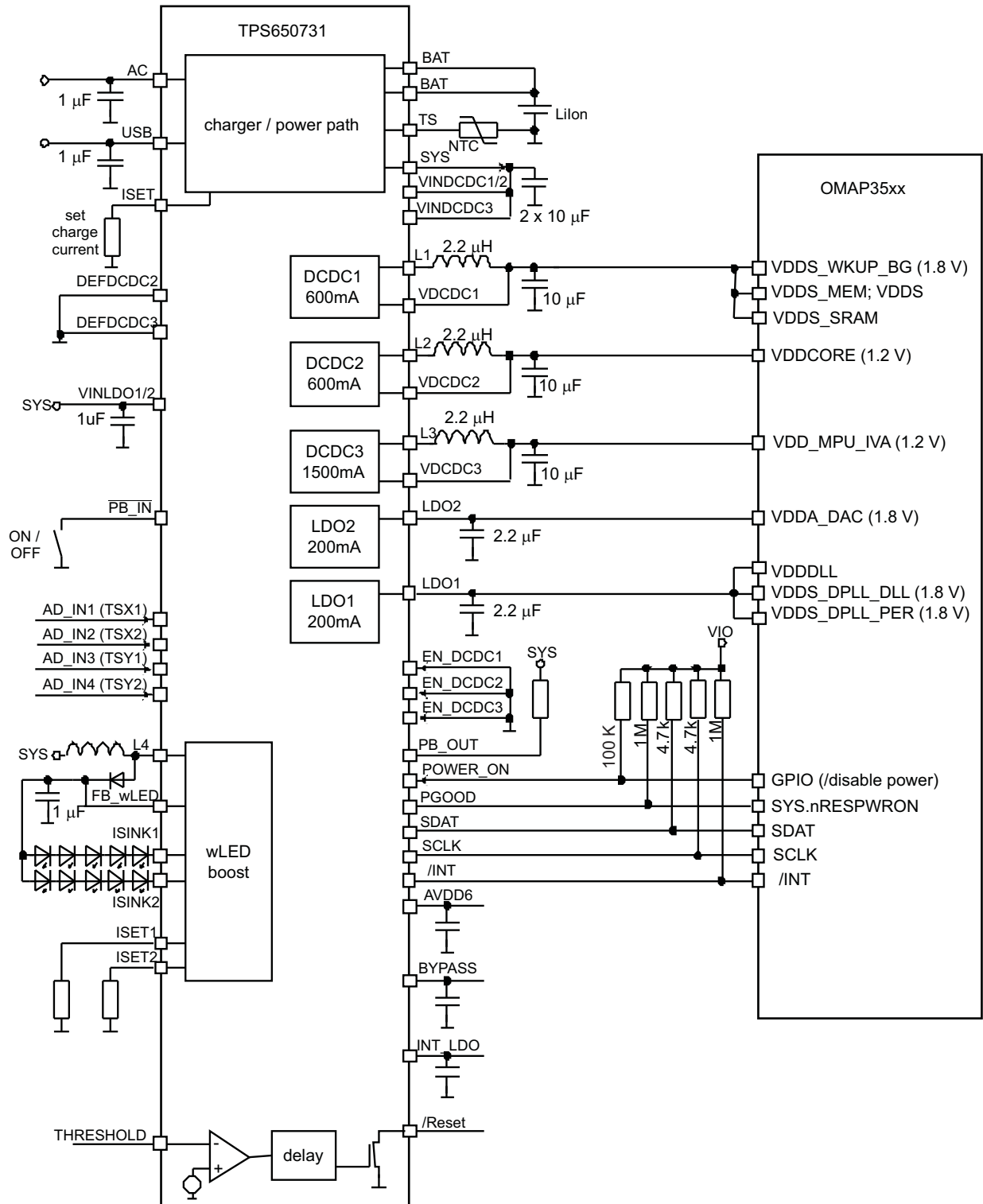


Figure 57. TPS650731 for OMAP35xx

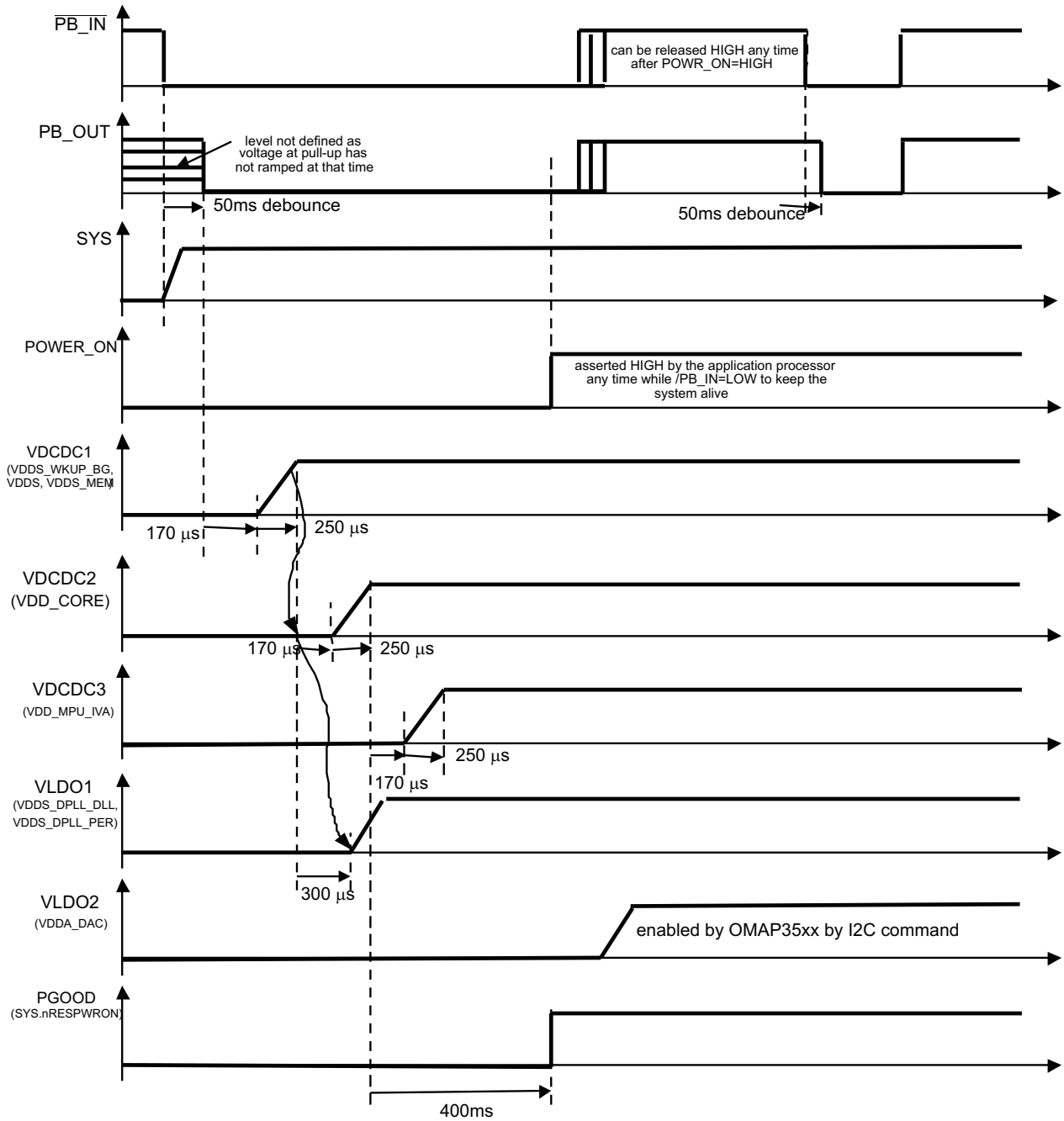


Figure 58. TPS650731: OMAP35xx timing

TPS65070-Q1, TPS65072-Q1, TPS65073-Q1, TPS650732-Q1

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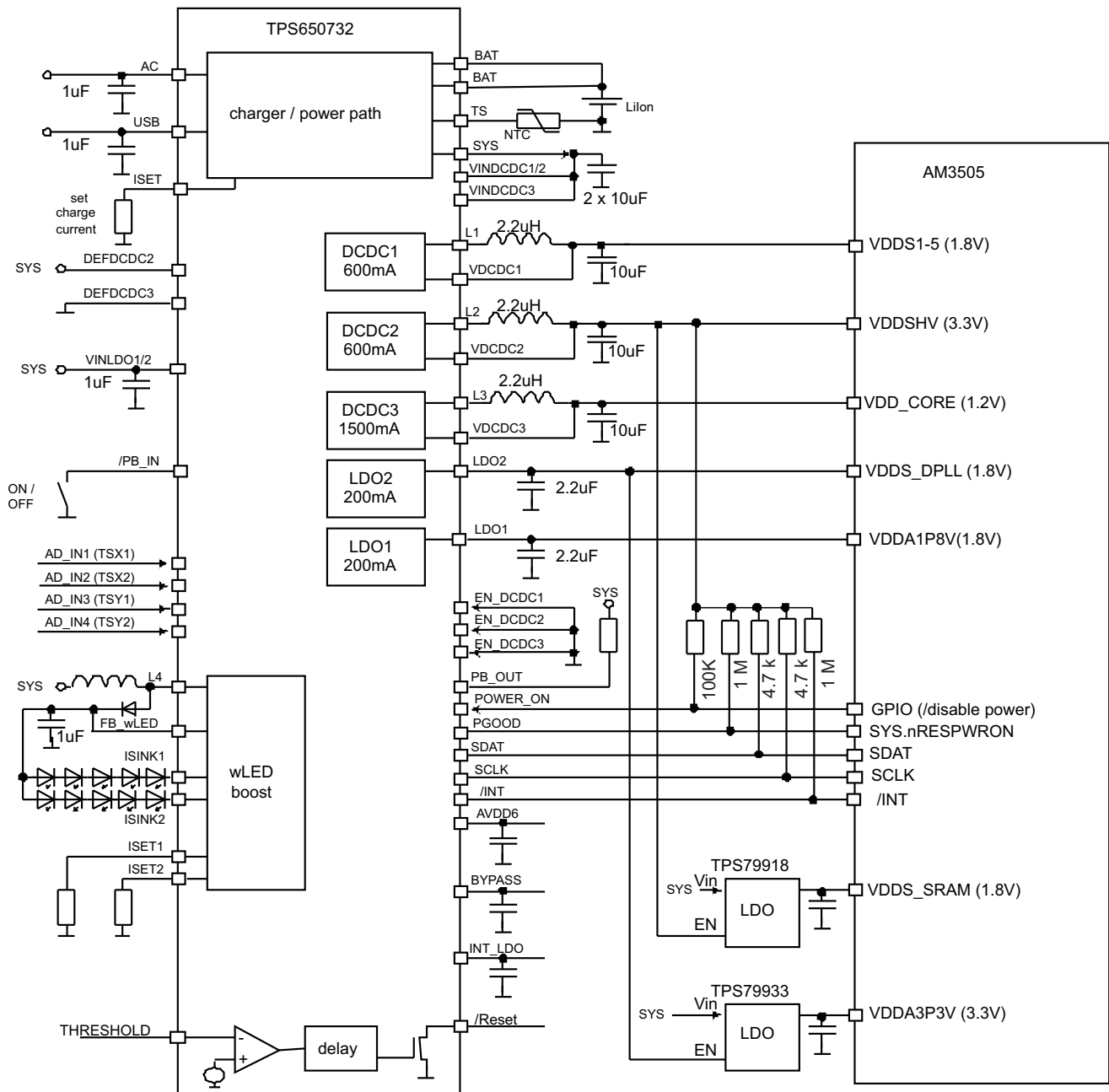


Figure 59. Powering AM3505 Using TPS650732

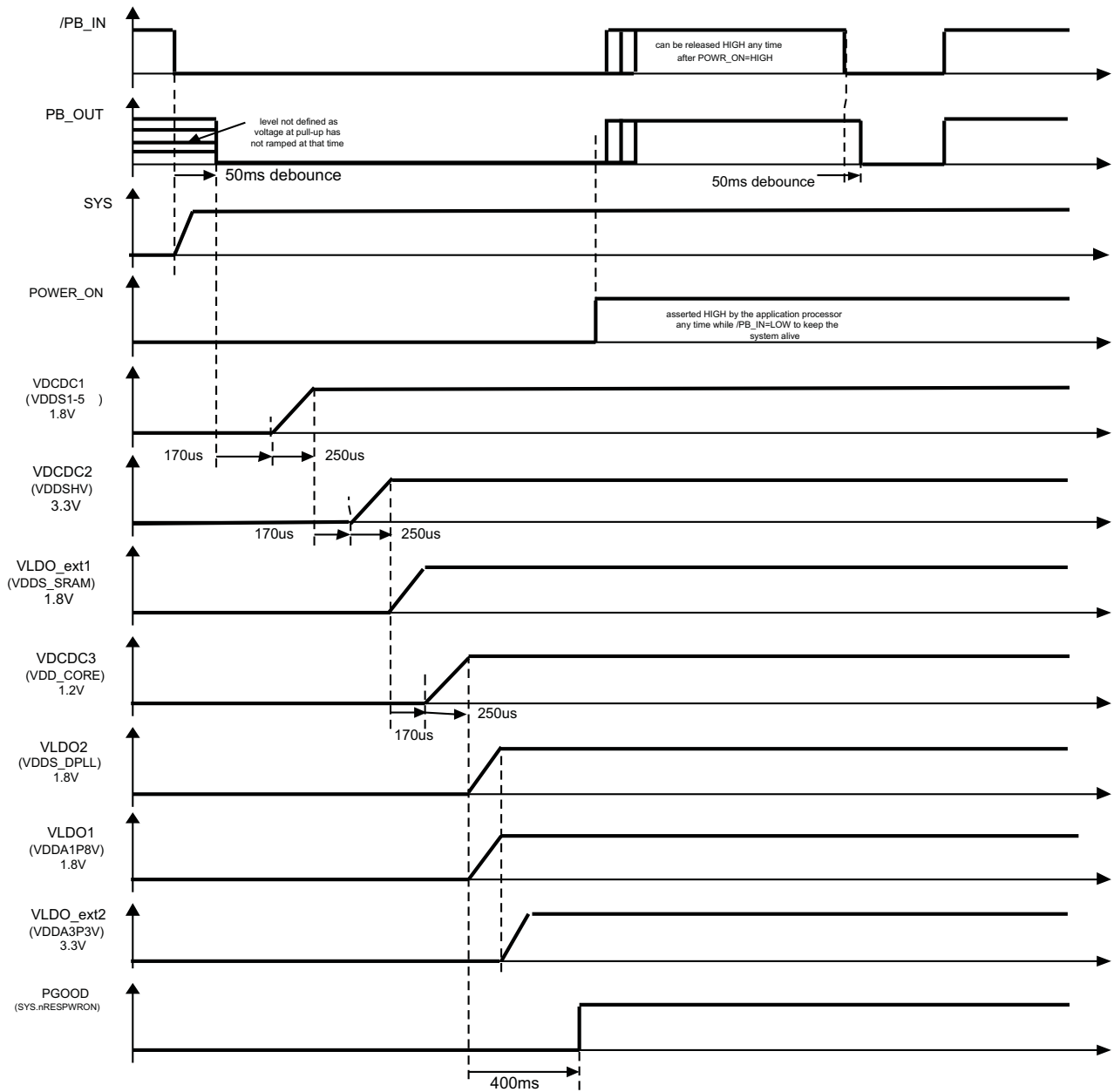


Figure 60. Timing Using TPS650732 for AM3505

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|------------------|----------------------|--------------|--------------------------|-------------------------|
| TPS650732TRSLRQ1 | ACTIVE | VQFN | RSL | 48 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | -40 to 105 | TPS 650732T | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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OTHER QUALIFIED VERSIONS OF TPS650732-Q1 :

- Catalog: [TPS650732](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TPS650732TRSLRQ1 | VQFN | RSL | 48 | 2500 | 330.0 | 16.4 | 6.3 | 6.3 | 1.1 | 12.0 | 16.0 | Q2 |

TAPE AND REEL BOX DIMENSIONS



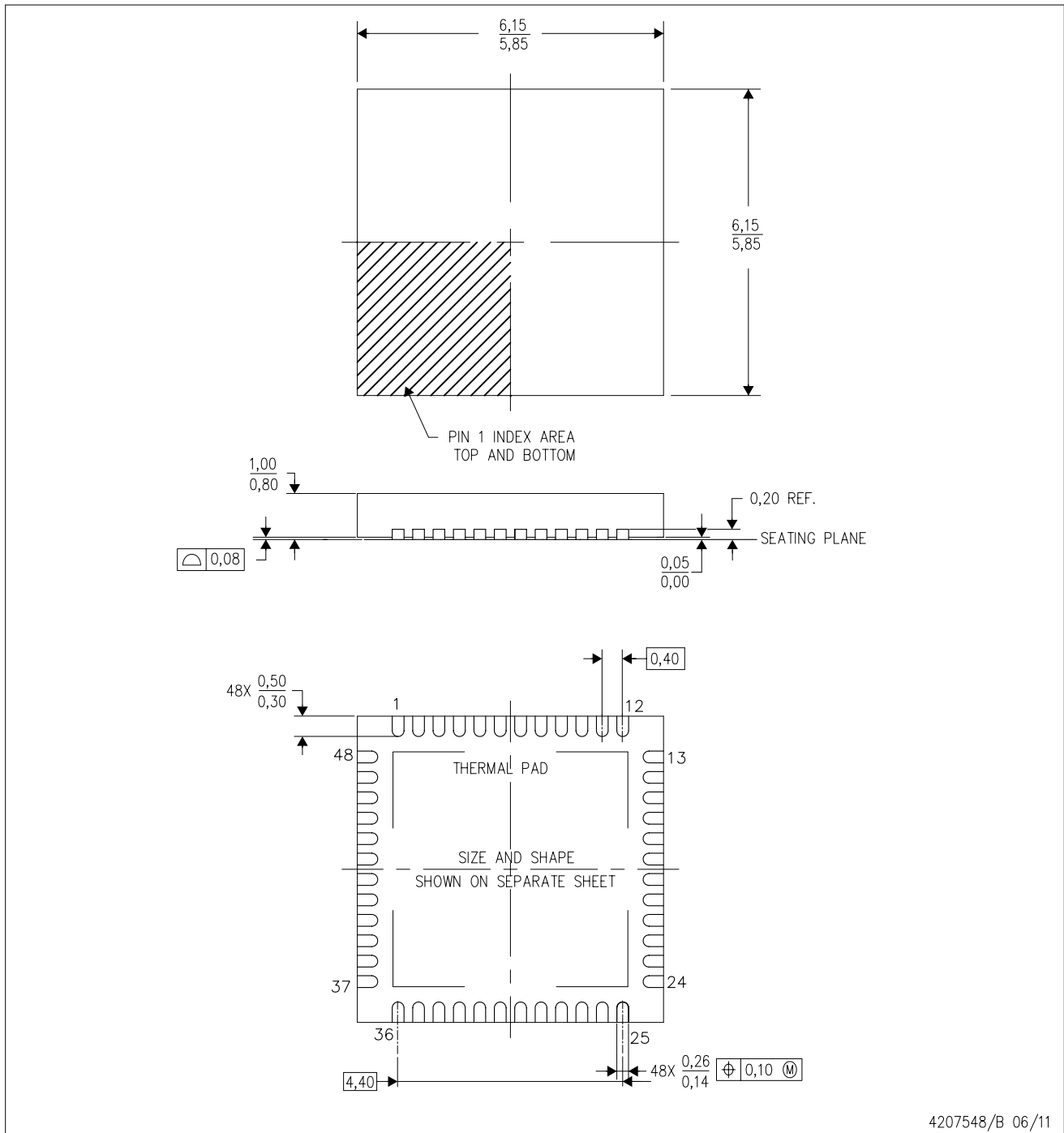
*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TPS650732TRSLRQ1 | VQFN | RSL | 48 | 2500 | 367.0 | 367.0 | 38.0 |

MECHANICAL DATA

RSL (S-PVQFN-N48)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Quad Flatpack, No-leads (QFN) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.

THERMAL PAD MECHANICAL DATA

RSL (S-PVQFN-N48)

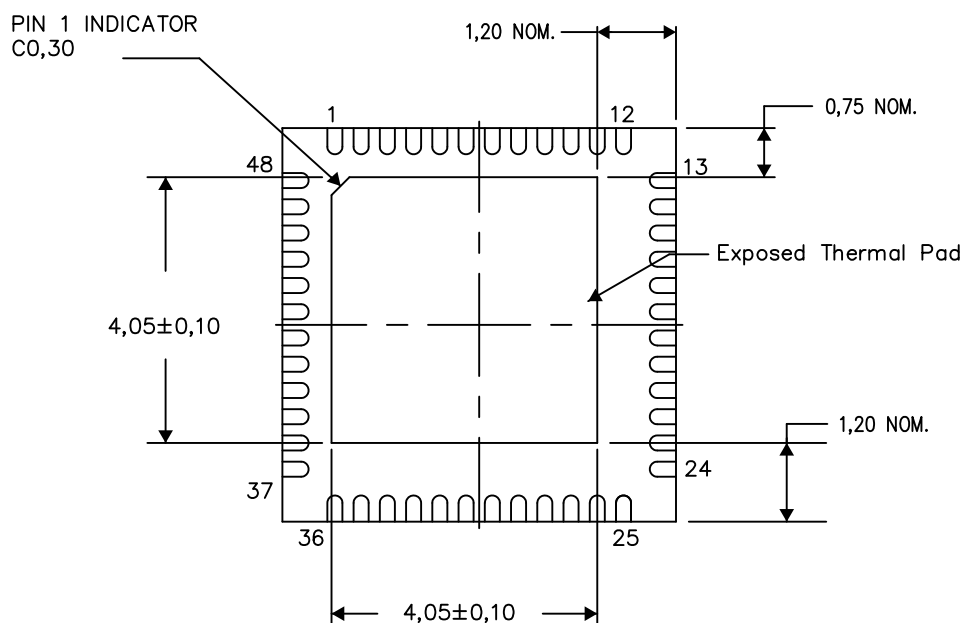
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

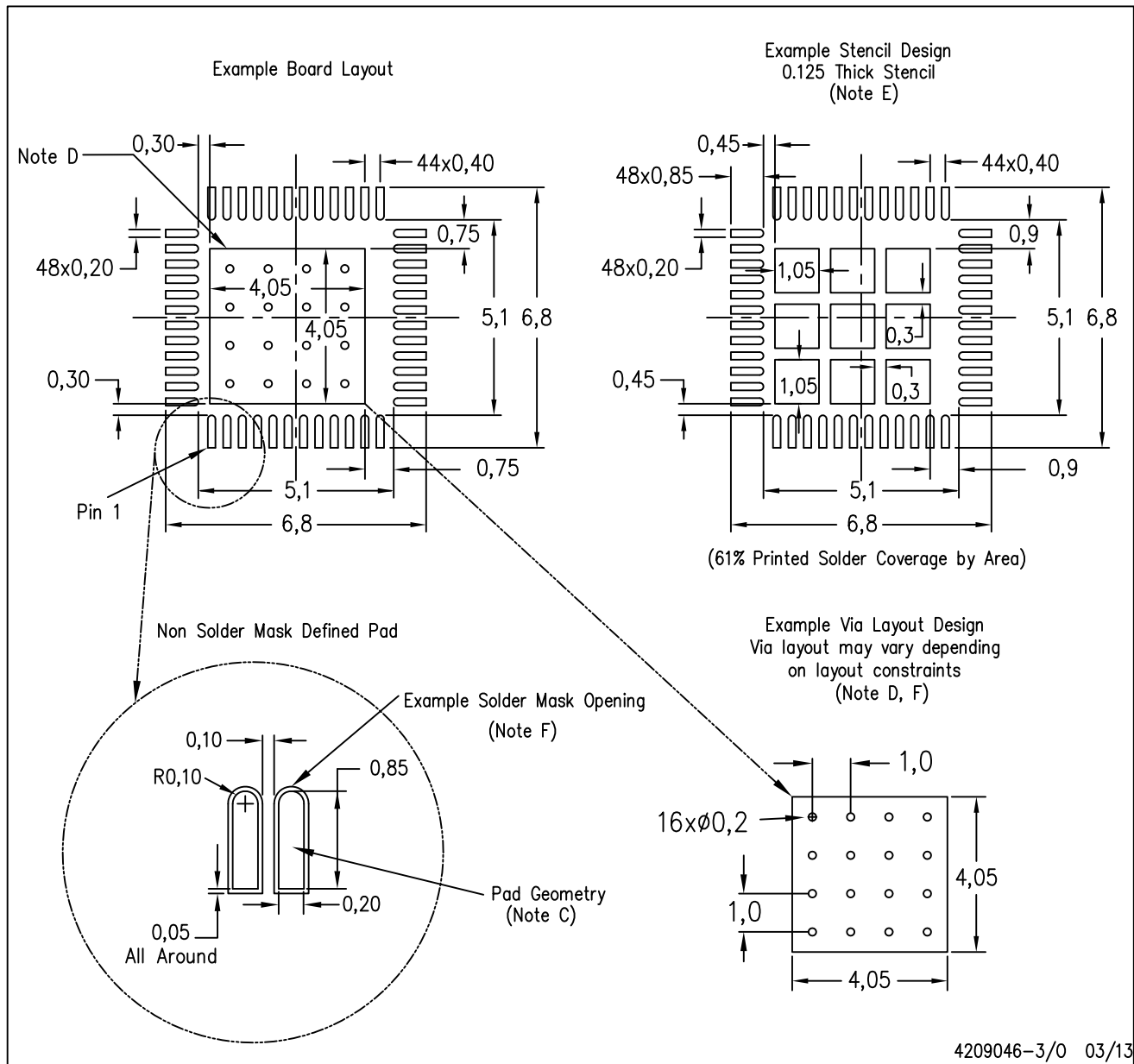
Exposed Thermal Pad Dimensions

4207841-4/P 03/13

NOTE: All linear dimensions are in millimeters

RSL (S-PVQFN-N48)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in the thermal pad.

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